

K9GBG08U0B
K9LCG08U0B
K9HDG08UXB

32Gb B-die NAND Flash

Multi-Level-Cell (2bit/cell)

datasheet

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1.0 INTRODUCTION

1.1 Features

- Voltage Supply :
 - VCC : 3.3V (2.7V ~ 3.6V)
 - VccQ : 3.3V (2.7V ~ 3.6V)
- Organization of Single die
 - Page Size : (8K + 1K) x 8bit
 - Data Register : (8K + 1K) x 8bit
 - Block Size : (1M + 128K) bytes
 - Unit Device Capacity: (4096M + 512M)bytes
- Products
 - K9GBG08U0B: Unit device x 1
 - K9LCG08U0B: Unit device x 2
 - K9HDG08U1B: Unit device x 4
- Automatic Program and Erase
 - Page Program : (8K + 1K)Byte
 - Block Erase : (1M + 128K)Byte
- Page Read Operation
 - Random Read(tR) : 80us(Max)
 - Serial Access : 25ns(Min.)
- Write Cycle Time
 - Page Program time : 1.3ms(Typ.)
 - Block Erase Time : 5ms(Typ.)
- Command/Address/Data Multiplexed I/O Port
- Hardware Data Protection
 - Program/Erase Lockout During Power Transitions
- Reliable CMOS Floating-Gate Technology
- ECC Requirement : 40bits/ (1K+128)byte
- Randomizer function required by Controller
- Unique ID for Copyright Protection.
- Package
 - K9GBG08U0B-SCB0 : Pb/Halogen Free Package
48-Pin TSOP (12 x 20 / 1.00 mm pitch)
 - K9LCG08U0B-SCB0 : Pb/Halogen Free Package
48-Pin TSOP (12 x 20 / 1.00 mm pitch)
 - K9HDG08U1B-SCB0 : Pb/Halogen Free Package
48-Pin TSOP (12 x 20 / 1.00 mm pitch)

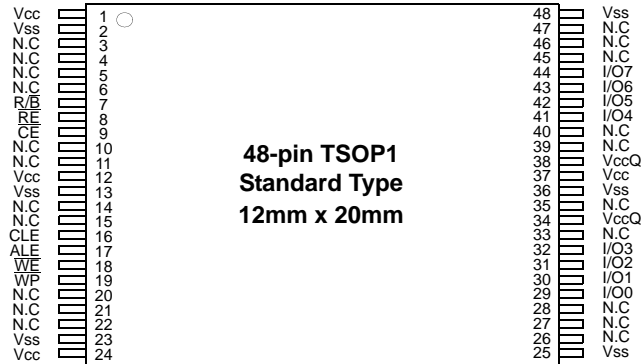
1.2 Product List

| Part Number | Density | Interface | Organization | Vcc Range | VccQ Range | PKG Type |
|-------------|---------|--------------|--------------|-------------|-------------|----------|
| K9GBG08U0B | 32Gb | Conventional | x8 | 2.7V ~ 3.6V | 2.7V ~ 3.6V | 48TSOP |
| K9LCG08U0B | 64Gb | | | | | |
| K9HDG08U1B | 128Gb | | | | | |

1.3 General Description

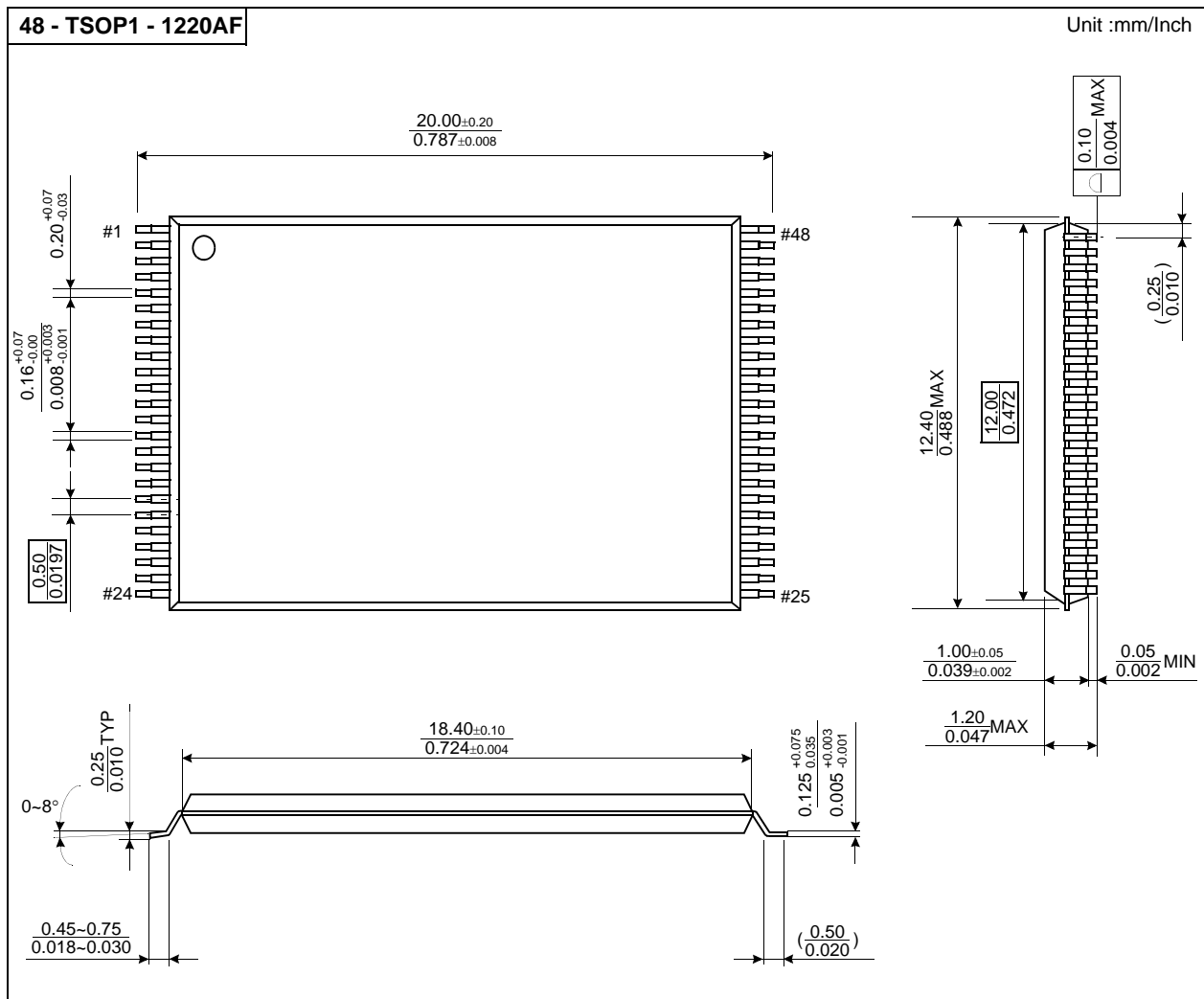
The device is offered in 3.3V Vcc. Its NAND cell provides the most cost-effective solution for the solid state mass storage market. A program operation can be performed in typical 1.3ms on the (8K+1K) byte page and an erase operation can be performed in typical 5ms on a (1M+128K)byte block. Data in the data register can be read out at 25ns cycle time per byte. The I/O pins serve as the ports for address and data input/output as well as command input. The on-chip write controller automates all program and erase functions including pulse repetition, where required, and internal verification and margining of data. Even the write-intensive systems can take advantage of the K9XXG08UXB's extended reliability of P/E cycles which are presented in the Qualification report by providing ECC(Error Correcting Code) with real time mapping-out algorithm. The K9XXG08UXB is an optimum solution for large nonvolatile storage applications such as solid state file storage and other portable applications requiring non-volatility.

1.4 Pin Configuration (48TSOP, Mono, DDP)

K9GBG08U0B-SCB0
K9LCG08U0B-SCB0

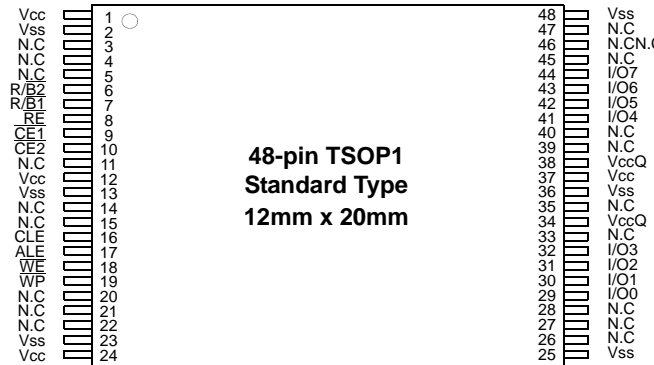
1.4.1 Package Dimensions

48-PIN LEAD FREE PLASTIC THIN SMALL OUT-LINE PACKAGE TYPE(I)



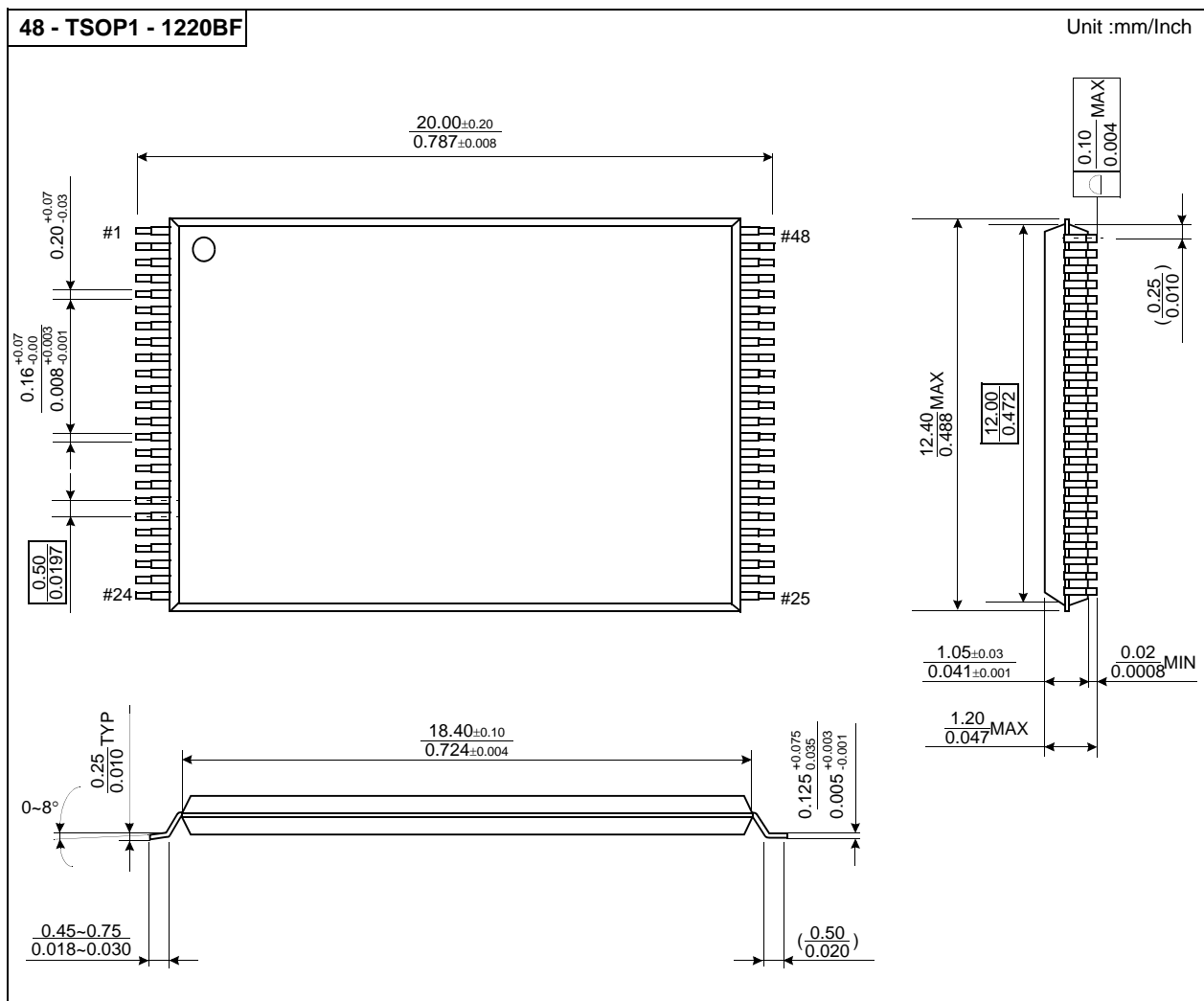
1.5 Pin Configuration (48TSOP, QDP)

K9HDG08U1A-SCB0



1.5.1 Package Dimensions

48-pin lead free(or Halogen free) plastic thin small out line package

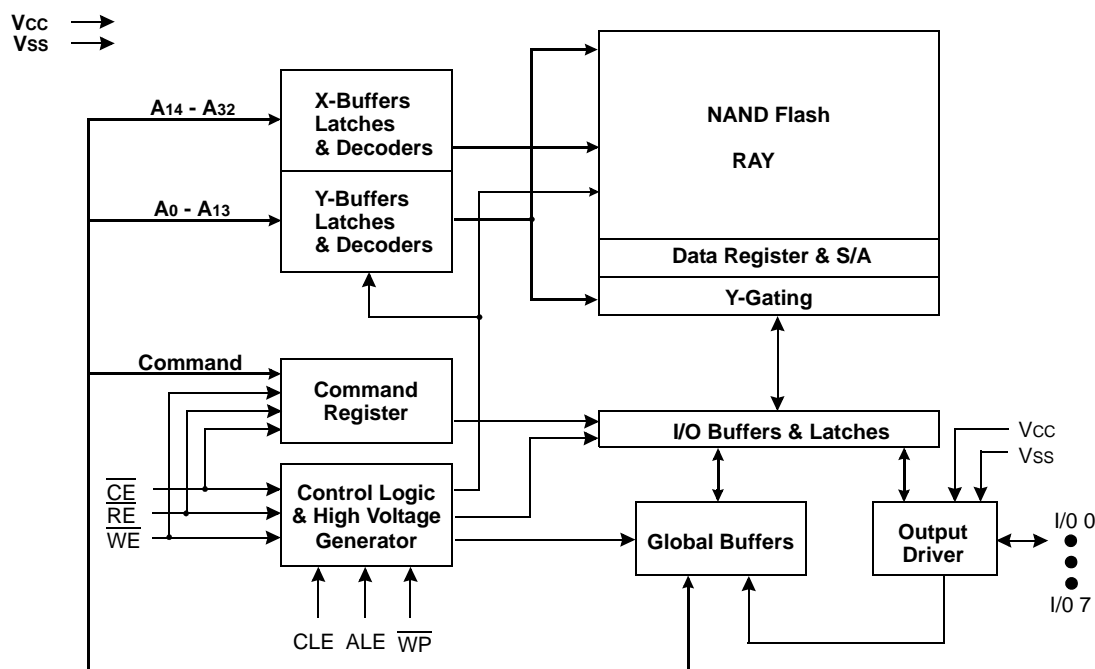
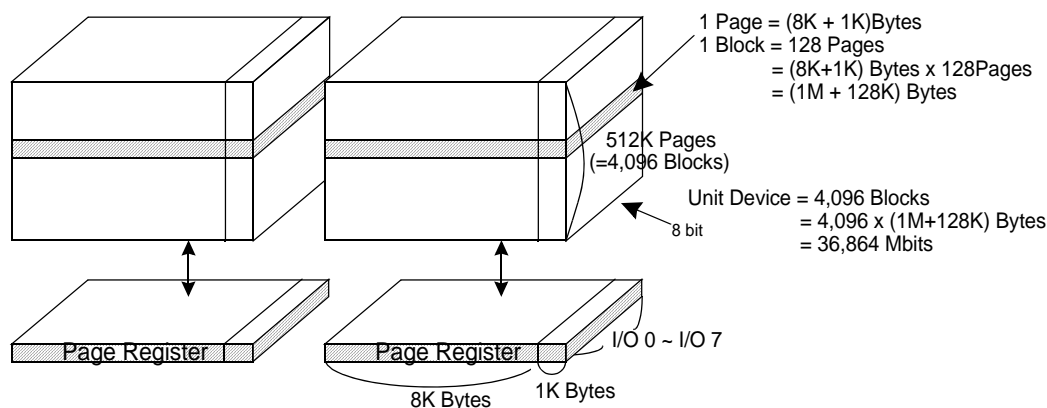


1.6 Pin Description

| Pin Name | Pin Function |
|-------------------------------------|---|
| I/O ₀ ~ I/O ₇ | DATA INPUTS/OUTPUTS The I/O pins are used to input command, address and data, and to output data during read operations. The I/O pins float to high-z when the chip is deselected or when the outputs are disabled. |
| CLE | COMMAND LATCH ENABLE The CLE input controls the activating path for commands sent to the command register. When active high, commands are latched into the command register through the I/O ports on the rising edge of the WE signal. |
| ALE | ADDRESS LATCH ENABLE The ALE input controls the activating path for address to the internal address registers. Addresses are latched on the rising edge of \overline{WE} with ALE high. |
| \overline{CE} | CHIP ENABLE The \overline{CE} input is the device selection control. When the device is in the Busy state, \overline{CE} high is ignored, and the device does not return to standby mode in program or erase operation. |
| \overline{RE} | READ ENABLE The \overline{RE} input is the serial data-out control, and when active drives the data onto the I/O bus. Data is valid tREA after the falling edge of \overline{RE} which also increments the internal column address counter by one. |
| \overline{WE} | WRITE ENABLE The \overline{WE} input controls writes to the I/O port. Commands, address and data are latched on the rising edge of the \overline{WE} pulse. |
| \overline{WP} | WRITE PROTECT The \overline{WP} pin provides inadvertent program/erase protection during power transitions. The internal high voltage generator is reset when the \overline{WP} pin is active low. |
| R/ \overline{B} | READY/BUSY OUTPUT The R/ \overline{B} output indicates the status of the device operation. When low, it indicates that a program, erase or random read operation is in process and returns to high state upon completion. It is an open drain output and does not float to high-z condition when the chip is deselected or when outputs are disabled. |
| Vcc | POWER Vcc is the power supply for device. |
| VccQ | I/O POWER The VccQ is the power supply for input and/or output signals. |
| Vss | GROUND |
| VssQ | I/O GROUND The VssQ is the power supply ground |
| N.C | NO CONNECTION Lead is not internally connected. |

NOTE :

Connect all VCC and VSS pins of each device to common power supply outputs.
Do not leave VCC or VSS disconnected.

Functional Block Diagram**Array Organization of Unit Device**

| | I/O 0 | I/O 1 | I/O 2 | I/O 3 | I/O 4 | I/O 5 | I/O 6 | I/O 7 | |
|-----------|-------------------------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|--|
| 1st Cycle | A ₀ ⁽¹⁾ | A ₁ | A ₂ | A ₃ | A ₄ | A ₅ | A ₆ | A ₇ | Column Address |
| 2nd Cycle | A ₈ | A ₉ | A ₁₀ | A ₁₁ | A ₁₂ | A ₁₃ | *L | *L | |
| 3rd Cycle | A ₁₄ | A ₁₅ | A ₁₆ | A ₁₇ | A ₁₈ | A ₁₉ | A ₂₀ | A ₂₁ | Row Address; Page Address : A ₁₄ ~ A ₂₀ Plane Address : A ₂₁ Block Address : A ₂₂ ~ A ₃₂ |
| 4th Cycle | A ₂₂ | A ₂₃ | A ₂₄ | A ₂₅ | A ₂₆ | A ₂₇ | A ₂₈ | A ₂₉ | |
| 5th Cycle | A ₃₀ | A ₃₁ | A ₃₂ | *L | *L | *L | *L | *L | |

NOTE :

- A₀ must be set to "Low"
- Data input/output unit should be 2-byte(16bit).
Column Address : Starting Address of the Register.
* When unused address bits shall be set to "Low".
* The device ignores any additional input of address cycles than required

2.0 PRODUCT INTRODUCTION

NAND Flash Memory has addresses multiplexed into 8 I/Os. This scheme dramatically reduces pin counts and allows system upgrades to future densities by maintaining consistency in system board design. Command, address and data are all written through I/O's by bringing WE to low while CE is low. Those are latched on the rising edge of WE. Command Latch Enable(CLE) and Address Latch Enable(ALE) are used to multiplex command and address respectively, via the I/O pins. Some commands require one bus cycle. For example, Reset Command, Status Read Command, etc. require just one cycle bus. Some other commands, like page read and block erase and page program, require two cycles: one cycle for setup and the other cycle for execution.- Page Read and Page Program need the same five address cycles following the required command input. In Block Erase operation, however, only the three row address cycles are used. Device operations are selected by writing specific commands into the command register. The table below defines the specific commands.

[Table 1] Command Sets

| Function | 1st Set | 2nd Set | Acceptable Command during busy |
|---|------------|------------|--------------------------------|
| Read | 00h | 30h | |
| Cache Read | 31h | - | |
| Read Start for Last Page Cache Read | 3Fh | - | |
| Read for Copy-Back | 00h | 35h | |
| Intelligent Copy-Back Read | 00h | 3Ah | |
| Page Program | 80h | 10h | |
| Cache Program | 80h | 15h | |
| Copy-Back Program | 85h | 10h | |
| Intelligent Copy-Back Program | 8Ch | 15h | |
| Intelligent Copy-Back Program for Last Page | 8Ch | 10h | |
| Block Erase | 60h | D0h | |
| Random Data Input ⁽¹⁾ | 85h | - | |
| Random Data Output ⁽¹⁾ | 05h | E0h | |
| Two-Plane Read ⁽³⁾ | 60h----60h | 30h | |
| Two-Plane Read for Copy-Back ⁽³⁾ | 60h----60h | 35h | |
| Two-Plane Intelligent Copy-Back Read | 60h----60h | 3Ah | |
| Two-Plane Cache Read ⁽³⁾ | 60h----60h | 33h | |
| Two-Plane Random Data Output ^{(1) (3)} | 00h----05h | E0h | |
| Two-Plane Page Program ⁽²⁾ | 80h----11h | 81h----10h | |
| Two-Plane Copy-Back Program ⁽²⁾ | 85h----11h | 81h----10h | |
| Two-Plane Intelligent Copy-Back Program | 8Ch----11h | 8Ch----15h | |
| Two-Plane Cache Program ⁽²⁾ | 80h----11h | 81h----15h | |
| Two-Plane Intelligent Copy-Back Program for Last Page | 8Ch----11h | 8Ch----10h | |
| Two-Plane Block Erase | 60h----60h | D0h | |
| Read ID | 90h | - | |
| Device Identification Table Read | ECh | - | |
| Read Status | 70h | - | O |
| Read chip#0 status | F1h | - | O |
| Read chip#1 status | F2h | - | O |
| Set Feature | EFh | - | |
| Reset | FFh | - | O |

NOTE :

- 1) Random Data Input/Output can be executed in a page.
- 2) Any command between 11h and 80h/81h/85h is prohibited except 70h/F1h/F2h and FFh.
- 3) Two-Plane Random Data out must be used after Two-Plane Read or Two-Plane Cache Read operation

CAUTION :

Any undefined command inputs are prohibited except for above command set of Table 1 .

2.1 Absolute Maximum DC Rating

Stresses greater than those listing in Table 2 may cause permanent damage to the device. This is a stress rating only. Operation beyond the operating conditions specified in Table 2 is not recommended. Extended exposure beyond these conditions may affect device reliability.

[Table 2] Absolute Maximum Rating

| Parameter | Symbol | Rating | Unit |
|------------------------------------|------------------|--------------------------------------|------|
| Voltage on any pin relative to Vss | V _{CC} | -0.6 to +4.6 | V |
| | V _{CCQ} | -0.6 to +4.6 | |
| | V _{IN} | -0.6 to V _{CCQ} + 0.3(<4.6) | |
| | V _{IO} | | |
| Storage Temperature | T _{STG} | -65 to +100 | °C |

NOTE :

- 1) Minimum DC voltage is -0.6V on input/output pins at 3.3VccQ. During transitions, this level may undershoot to -2.0V for periods <30ns. Maximum DC voltage on input/output pins is 4.6V at 3.3VccQ which, during transitions, may overshoot to VccQ+2.0V for periods <20ns.
- 2) Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2.2 Recommended Operating Conditions

(Voltage reference to GND, K9XXG08UXB-SCB0:TA=0 to 70°C⁽¹⁾)

| Parameter | Symbol | Min | Typ. | Max | Unit |
|---|--------|-----|------|-----|------|
| Supply Voltage | Vcc | 2.7 | 3.3 | 3.6 | V |
| Ground Voltage | Vss | 0 | 0 | 0 | V |
| Supply Voltage for I/O signaling (3.3V) | VccQ | 2.7 | 3.3 | 3.6 | V |
| Ground Voltage for I/O signaling | VssQ | 0 | 0 | 0 | V |

NOTE :

- 1) Data retention is not guaranteed on out of operating condition temperature.

2.3 DC And Operating Characteristics(Recommended operating conditions otherwise noted.)

[Table 3] DC & Operating Characteristics for VccQ=3.3V

| Parameter | Symbol | Test Conditions | 2-Plane | | | Unit |
|--------------------------------|--------------------|---|---------|-----|-----|------|
| | | | Min | Typ | Max | |
| Page Read Operation Current | ICC1 | - | - | - | 45 | mA |
| Page Program Operation Current | ICC2 | - | - | - | 45 | |
| Erase Operation Current | ICC3 | - | - | - | 45 | |
| I/O Burst Read Current | ICC4R | C _{LOAD} =0pF (I _{OUT} =0mA) CE=V _{IL} , Half data switching t _{RC} =10ns(100Mhz) | - | - | - | |
| | ICCQ4R | | - | - | - | |
| I/O Burst Write Current | ICC4W | CE=V _{IL} , Half data switching | - | - | - | |
| | ICCQ4W | | - | - | - | |
| Bus Idle Current | ICC5 | - | - | - | - | μA |
| Stand-by Current(CMOS) | ISB ⁽³⁾ | CE=VccQ-0.2, WP=0V/VccQ | - | - | - | |
| Input Leakage Current | ILI ⁽⁴⁾ | VIN=0 to VccQ(max) | - | - | ±10 | |
| Output Leakage Current | ILO ⁽⁴⁾ | VOUT=0 to VccQ(max) | - | - | ±10 | |
| Output High Voltage Level | VOH | IOH=-400μA | 2.4 | - | - | V |
| Output Low Voltage Level | VOL | IOL= 2.1mA | - | - | 0.4 | |
| Output Low Current(R/B) | IOL(R/B) | VOL=0.4V | 8 | 10 | - | mA |

NOTE :

- 1) Typical value is measured at Vcc=3.3V, TA=25°C. Not 100% tested.
- 2) VOH and VOL should be available on these two conditions; Output Strength is nominal and VccQ=3.3V, Rpd/Rpu are all VccQx0.5. If the driver strength settings are supported, Table 14 shall be used to derive the output driver impedance values.

2.4 Valid Block

| Parameter | Symbol | Min | Typ. | Max | Unit |
|------------|--------|--------|------|-------|--------|
| K9GBG08U0B | NvB | 3,994 | - | 4,096 | Blocks |
| K9LCG08U0B | | 7,988 | - | 8,192 | |
| K9HDG08U1B | | 15,976 | - | 16384 | |

NOTE :

- 1) The device may include initial invalid blocks when first shipped. Additional invalid blocks may develop while being used. The number of valid blocks is presented with both cases of invalid blocks considered. Invalid blocks are defined as blocks that contain one or more bad bits which cause status failure during program and erase operation. Do not erase or program factory-marked bad blocks. Refer to the attached technical notes for appropriate management of initial invalid blocks.
- 2) The 1st block, which is placed on 00h block address, is guaranteed to be a valid block at the time of shipment.
- 3) The number of valid blocks is on the basis of single plane operations, and this may be decreased with two plane operations.

2.5 AC Test Condition

(K9XXG08UXB-SCB0:TA=0 to 70°C, VCC=2.7V~3.6V, unless otherwise noted)

| Parameter | K9XXG08UXB |
|--------------------------------|------------------------------------|
| Input Pulse Levels | V _{IL} to V _{IH} |
| Input Rise and Fall Times | 1.0V/ns |
| Input and Output Timing Levels | V _{CC} Q/2 |
| Output Load | CL= 5pF |

2.6 Capacitance(TA=25°C, VCC=3.3V, f=1MHz)

| Item | Symbol | Test Condition | K9XXG08UXB | | Unit |
|--------------------------|----------------------|---------------------|------------|-----|------|
| | | | Min | Max | |
| Input/Output Capacitance | C _{I/O} | V _{IL} =0V | - | 8 | pF |
| | C _{I/O(W)*} | | - | 5 | pF |
| Input Capacitance | C _{IN} | V _{IN} =0V | - | 8 | pF |
| | C _{IN(W)*} | | - | 5 | pF |

NOTE :

- 1) Capacitance is periodically sampled and not 100% tested.
- 2) C_{I/O(W)} and C_{IN(W)} are tested at wafer level.

2.7 Mode Selection

| CLE | ALE | CE | WE | RE | WP | Mode | |
|-----|------------------|----|----|----|-----------------------------------|----------------------|-----------------------|
| H | L | L | | H | X | Read Mode | Command Input |
| L | H | L | | H | X | | Address Input(5clock) |
| H | L | L | | H | H | Write Mode | Command Input |
| L | H | L | | H | H | | Address Input(5clock) |
| L | L | L | H | H | H | Data Input | |
| L | L | L | H | | X | Data Output | |
| X | X | X | X | H | X | During Read(Busy) | |
| X | X | X | X | X | H | During Program(Busy) | |
| X | X | X | X | X | H | During Erase(Busy) | |
| X | X ⁽¹⁾ | X | X | X | L | Write Protect | |
| X | X | H | X | X | 0V/V _{CC} ⁽²⁾ | Stand-by | |

NOTE :

- 1) X can be V_{IL} or V_{IH}.
- 2) WP should be biased to CMOS high or CMOS low for standby.

2.8 Program / Erase Characteristics

| Parameter | Symbol | Min | Typ | Max | Unit |
|---|----------------------|-----|-----|-------|-------|
| Data Transfer from Flash array to Register | tR | - | - | 80 | μs |
| Program Time | tPROG | - | 1.3 | 5 | ms |
| Dummy Busy Time for Two-Plane setting | tDBSY | - | 0.5 | 1 | μs |
| Dummy Busy Time for Cache Program | tCBSY | - | - | tPROG | ms |
| Dummy Busy Time for Intelligent Copy-Back Program | tCBSY2 | - | - | tR | μs |
| Cache Busy in Read Cache | t _{DCBSYR} | - | - | tR | μs |
| Dummy Busy Time for Intelligent Copy-Back Read | t _{DCBSYR2} | - | - | tPROG | ms |
| Number of Partial Program Cycles in the Same Page | Nop | - | - | 1 | cycle |
| Block Erase Time | tBERS | - | 5 | 10 | ms |

NOTE :

1) Typical program time is measured at V_{cc}=3.3V, T_A=25°C. Not 100% tested.2) Typical Program time is defined as the time within which more than 50% of the whole pages are programmed at 3.3V V_{cc} and 25°C temperature.

3) Within a same block, program time(tPROG) of page group A is faster than that of page group B. Typical tPROG is the average program time of the page group A and B.

Page Group A: Page 0, 1, 3, 5, 7, 9, 11, ... , 115, 117, 119, 121, 123, 125

Page Group B: Page 2, 4, 6, 8, 10, 12, ... , 118, 120, 122, 124, 126, 127

4) tCBSY depends on the timing between internal programming time and data in time.

2.9 AC Timing Characteristics for Command / Address / Data Input

| Parameter | Symbol | Min | Max | Unit |
|---------------------------------------|---------------------|-----|-----|------|
| CLE Setup Time | tCLS ⁽¹⁾ | 12 | - | ns |
| CLE Hold Time | tCLH | 5 | - | ns |
| $\overline{\text{CE}}$ Setup Time | tCS ⁽¹⁾ | 20 | - | ns |
| $\overline{\text{CE}}$ Hold Time | tCH | 5 | - | ns |
| $\overline{\text{RE}}$ Set up time | tCRES | 10 | - | ns |
| $\overline{\text{WE}}$ Pulse Width | tWP | 11 | - | ns |
| ALE Setup Time | tALS ⁽¹⁾ | 12 | - | ns |
| ALE Hold Time | tALH | 5 | - | ns |
| Data Setup Time | tDS ⁽¹⁾ | 12 | - | ns |
| Data Hold Time | tDH | 5 | - | ns |
| Write Cycle Time | tWC | 25 | - | ns |
| $\overline{\text{WE}}$ High Hold Time | tWH | 11 | - | ns |
| Address to Data Loading Time | tADL ⁽²⁾ | 300 | - | ns |

NOTE :

1) The transition of the corresponding control pins must occur only once while $\overline{\text{WE}}$ is held low2) tADL is the time from the $\overline{\text{WE}}$ rising edge of final address cycle to the $\overline{\text{WE}}$ rising edge of first data cycle

2.10 AC Characteristics for Operation

| Parameter | Symbol | Min | Max | Unit |
|---|--------|-------|--------------|------|
| ALE Low to RE Low | tAR | 10 | - | ns |
| Command Write cycle to Address Write cycle Time for Random data input | tCWA | 300 | - | ns |
| Ready to RE Low | tRR | 20 | - | ns |
| RE Pulse Width | tRP | 11 | - | ns |
| Read Cycle Time | tRC | 25 | - | ns |
| RE Access Time | tREA | - | 20 | ns |
| RE High to Output hold | tRHOH | 15 | - | ns |
| CE Access Time | tCEA | - | 25 | ns |
| CE Hold Time | tCH | 5 | - | ns |
| RE High to Output Hi-Z | tRHZ | - | 100 | ns |
| CE High to Output Hi-Z | tCHZ | - | 30 | ns |
| CLE to RE Low | tCLR | 10 | - | ns |
| RE Set up time | tCRES | 10 | - | ns |
| CE High to ALE, CLE or WE Don't Care | tCSD | 10 | - | ns |
| RE Low to Output Hold | tRLOH | 5 | - | ns |
| RE High Hold Time | tREH | 11 | - | ns |
| Output Hi-Z to RE Low | tIR | 0 | - | ns |
| RE High to WE Low | tRHW | 100 | - | ns |
| Device Resetting Time(Read/Program/Erase) | tRST | - | 10/30/200(1) | μs |
| Busy time for Set Feature and Get Feature | tFEAT | - | 1 | μs |
| WE High to Busy | tWB | - | 100 | ns |
| Write Cycle Time | tWC | 25 | - | ns |
| WE High pulse width | tWH | 11 | - | ns |
| WE High to RE Low | tWHR | 120 | - | ns |
| WE High to RE Low for Random data out | tWHR2 | 300 | - | ns |
| WE Low pulse Width | tWP | 11 | - | ns |
| WP High/Low to WE low | tWW | 100ns | - | ns |

NOTE :

1) If reset command(FFh) is written at Ready state, the device goes into Busy for maximum 10μs.

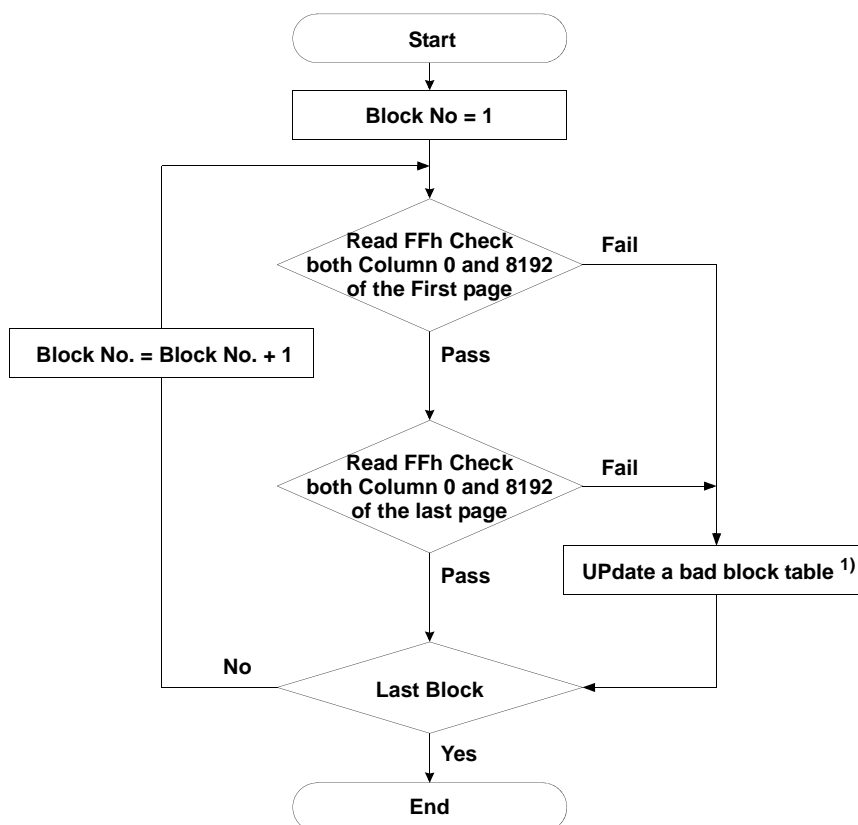
3.0 NAND FLASH TECHNICAL NOTES

3.1 Initial Invalid Block(s)

Initial invalid blocks are defined as blocks that contain one or more initial invalid bits whose reliability is not guaranteed by Samsung. The information regarding the initial invalid block(s) is called the initial invalid block information. Devices with initial invalid block(s) have the same quality level as devices with all valid blocks and have the same AC and DC characteristics. An initial invalid block(s) does not affect the performance of valid block(s) because it is isolated from the bit line and the common source line by a select transistor. The system design must be able to mask out the initial invalid block(s) via address mapping. The 1st block, which is placed on 00h block address, is guaranteed to be a valid block at the time of shipment.

3.2 Identifying Initial Invalid Block(s)

All device locations are erased(FFh) except locations where the initial invalid block(s) information is written prior to shipping. The initial invalid block(s) status is defined by the 1st byte in the spare area. Samsung makes sure that the first or the last page of every initial invalid block has non-FFh data at the both column address of 0 and 8,192. The initial invalid block information is also erasable in most cases, and it is impossible to recover the information once it has been erased. Therefore, the system must be able to recognize the initial invalid block(s) based on the initial invalid block information and create the initial invalid block table via the following suggested flow chart. Any intentional erasure of the initial invalid block information is prohibited.



Flow chart to create initial invalid block table.

NOTE :

1) No erase operation is allowed to detected bad blocks.

3.3 Error In Write or Read Operation

Within its life time, additional invalid blocks may develop with NAND Flash memory. Refer to the qualification report for the actual data. Block replacement should be done upon erase or program error.

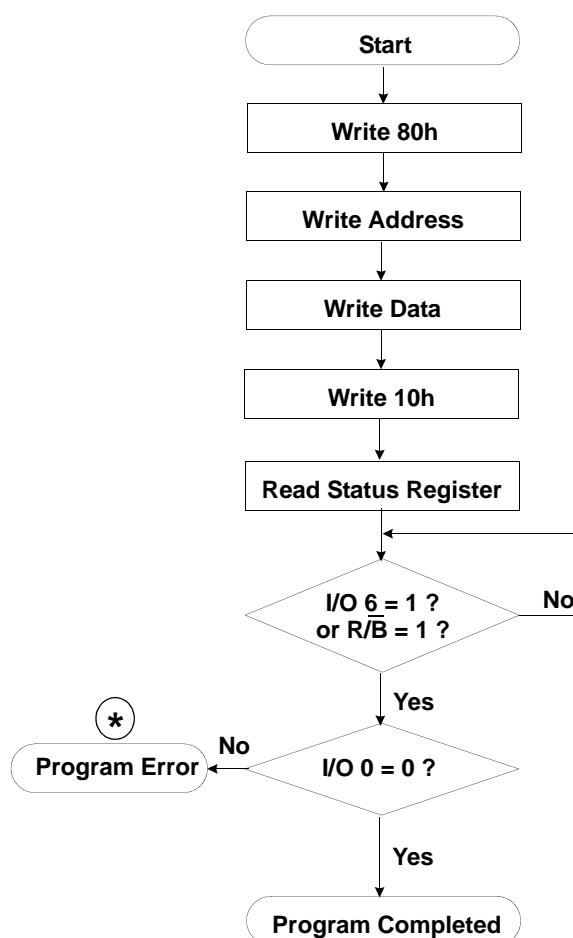
| Failure Mode | | Detection and Countermeasure sequence |
|--------------|-----------------------|---|
| Write | Erase Failure | Status Read after Erase --> Block Replacement |
| | Program Failure | Status Read after Program --> Block Replacement |
| Read | Up to 40-Bits Failure | Verify ECC -> ECC Correction |

ECC

: Error correcting code such as BCH code.

Example) 40 bit correction / 1KB

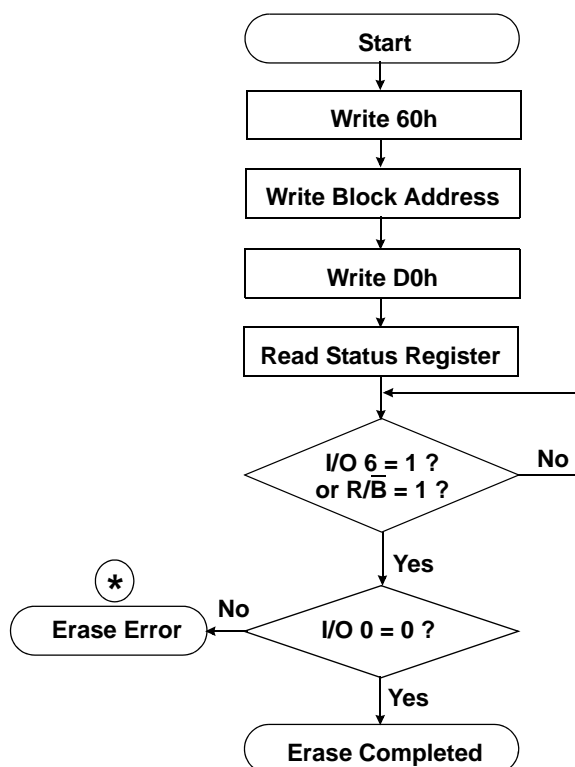
Program Flow Chart



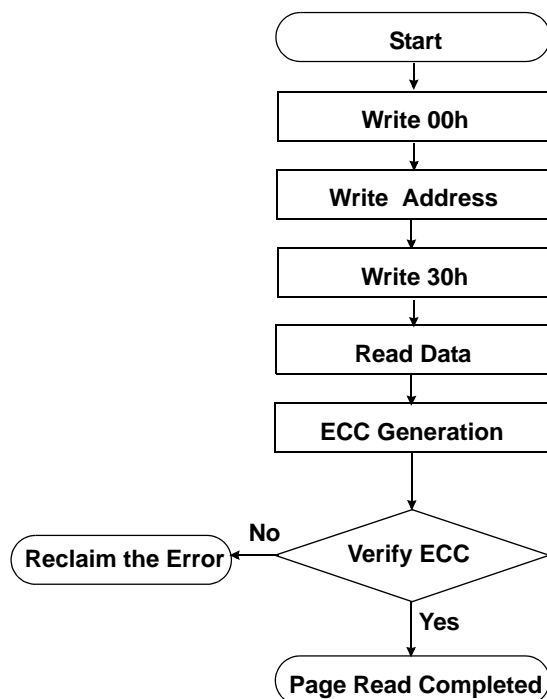
(*): If program operation results in an error, map out the block including the page in error and copy the target data to another block.

NAND Flash Technical Notes (Continued)

Erase Flow Chart

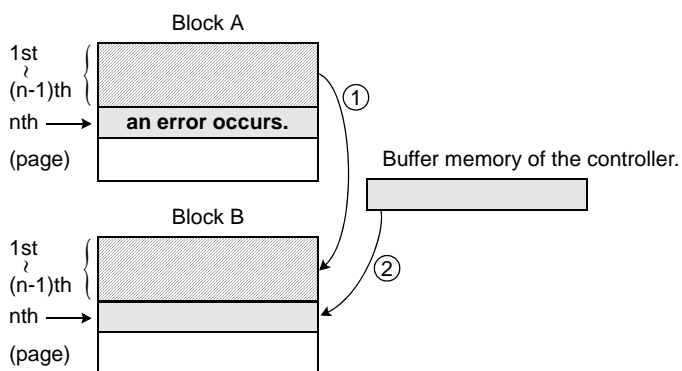


Read Flow Chart



* : If erase operation results in an error, map out the failing block and replace it with another block.

Block Replacement



* Step1

When an error happens in the nth page of the Block 'A' during erase or program operation.

* Step2

Copy the data in the 1st ~ (n-1)th page to the same location of another free block. (Block 'B')

* Step3

Then, copy the nth page data of the Block 'A' in the buffer memory to the nth page of the Block 'B'.

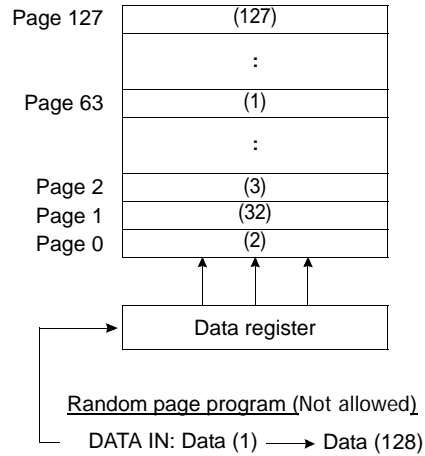
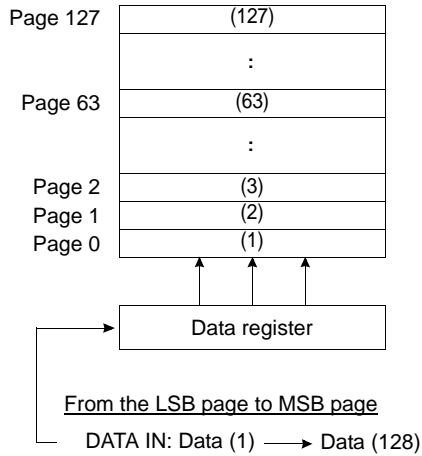
* Step4

Do not erase or program to Block 'A' by creating an 'invalid block' table or other appropriate scheme.

3.4 Addressing For Program Operation

Within a block, the pages must be programmed consecutively from the LSB (least significant bit) page of the block to MSB (most significant bit) pages of the block. Random page address programming is prohibited. In this case, the definition of LSB page is the LSB among the pages to be programmed. Therefore, LSB doesn't need to be page 0.

A page in 'group A' must be programmed before the program operation for a page in 'group B' is performed



Paired Page Address Information

| Paired Page Address(1/2) | | Paired Page Address(2/2) | |
|--------------------------|---------|--------------------------|---------|
| Group A | Group B | Group A | Group B |
| 00h | 02h | 3Fh | 42h |
| 01h | 04h | 41h | 44h |
| 03h | 06h | 43h | 46h |
| 05h | 08h | 45h | 48h |
| 07h | 0Ah | 47h | 4Ah |
| 09h | 0Ch | 49h | 4Ch |
| 0Bh | 0Eh | 4Bh | 4Eh |
| 0Dh | 10h | 4Dh | 50h |
| 0Fh | 12h | 4Fh | 52h |
| 11h | 14h | 51h | 54h |
| 13h | 16h | 53h | 56h |
| 15h | 18h | 55h | 58h |
| 17h | 1Ah | 57h | 5Ah |
| 19h | 1Ch | 59h | 5Ch |
| 1Bh | 1Eh | 5Bh | 5Eh |
| 1Dh | 20h | 5Dh | 60h |
| 1Fh | 22h | 5Fh | 62h |
| 21h | 24h | 61h | 64h |
| 23h | 26h | 63h | 66h |
| 25h | 28h | 65h | 68h |
| 27h | 2Ah | 67h | 6Ah |
| 29h | 2Ch | 69h | 6Ch |
| 2Bh | 2Eh | 6Bh | 6Eh |
| 2Dh | 30h | 6Dh | 70h |
| 2Fh | 32h | 6Fh | 72h |
| 31h | 34h | 71h | 74h |
| 33h | 36h | 73h | 76h |
| 35h | 38h | 75h | 78h |
| 37h | 3Ah | 77h | 7Ah |
| 39h | 3Ch | 79h | 7Ch |
| 3Bh | 3Eh | 7Bh | 7Eh |
| 3Dh | 40h | 7Dh | 7Fh |

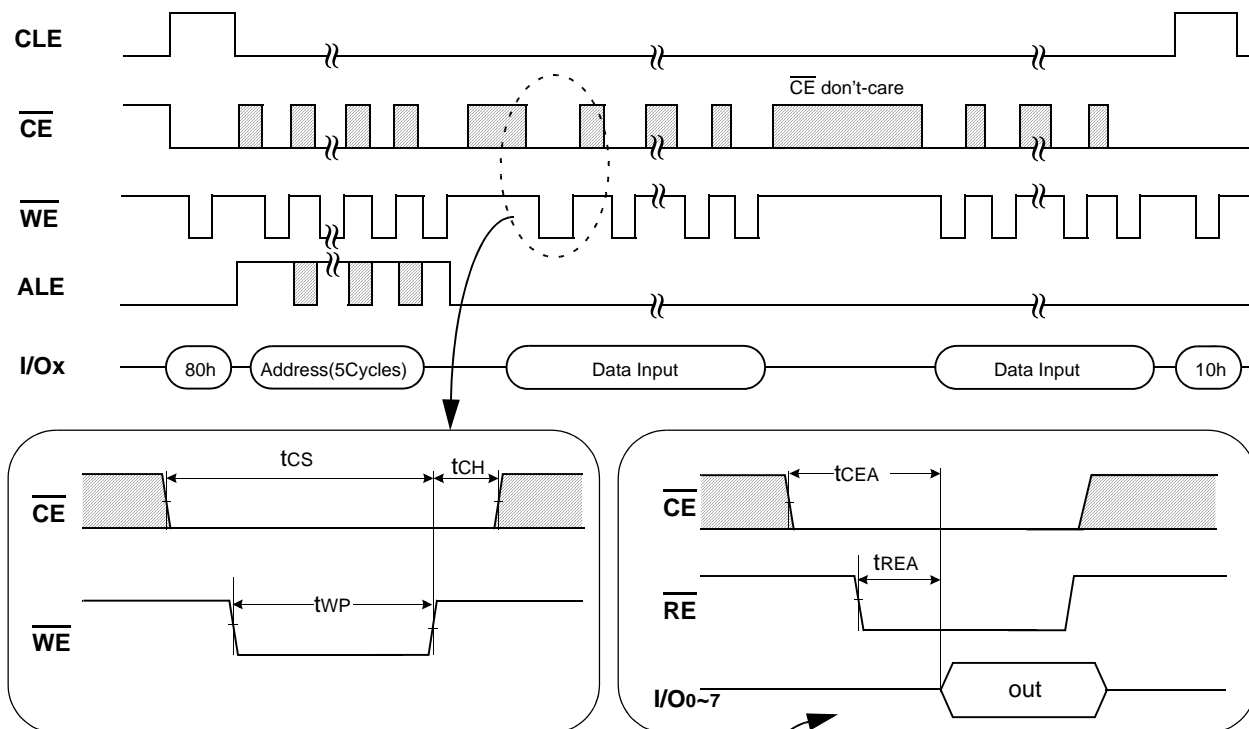
NOTE :

When program operation is abnormally aborted (ex. power-down, reset), not only page data under program but also paired page data may be damaged.

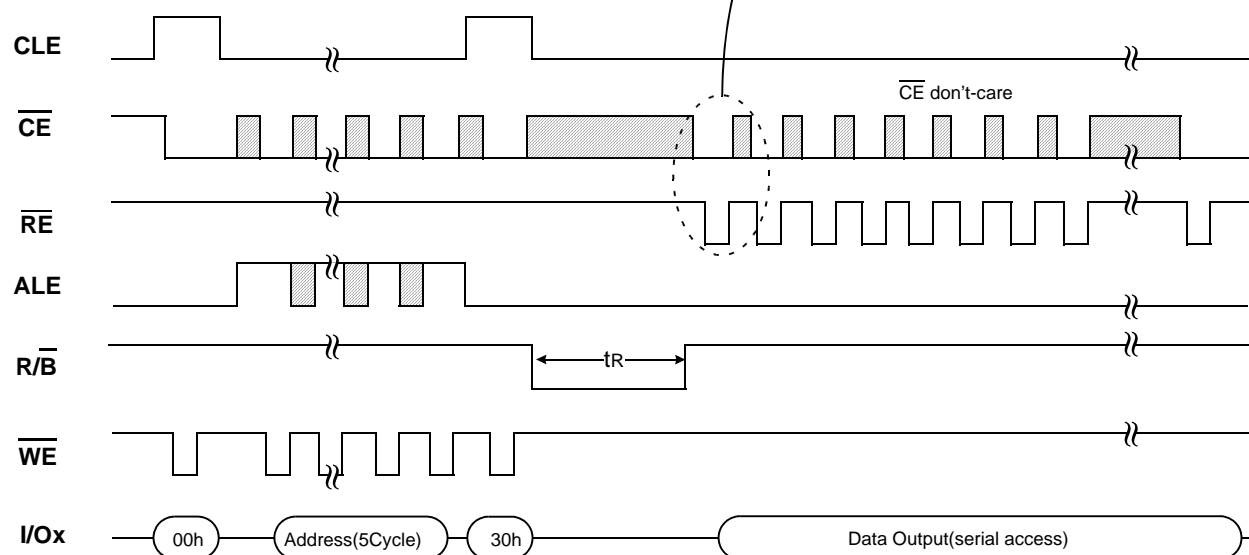
3.5 System Interface Using $\overline{\text{CE}}$ don't-care.

For an easier system interface, $\overline{\text{CE}}$ may be inactive during the data-loading or serial access as shown below. The internal (8K+1K) byte data registers are utilized as separate buffers for this operation and the system design gets more flexible. In addition, for voice or audio applications which use slow cycle time on the order of μ -seconds, de-activating $\overline{\text{CE}}$ during the data-loading and serial access would provide significant savings in power consumption.

Program Operation with $\overline{\text{CE}}$ don't-care

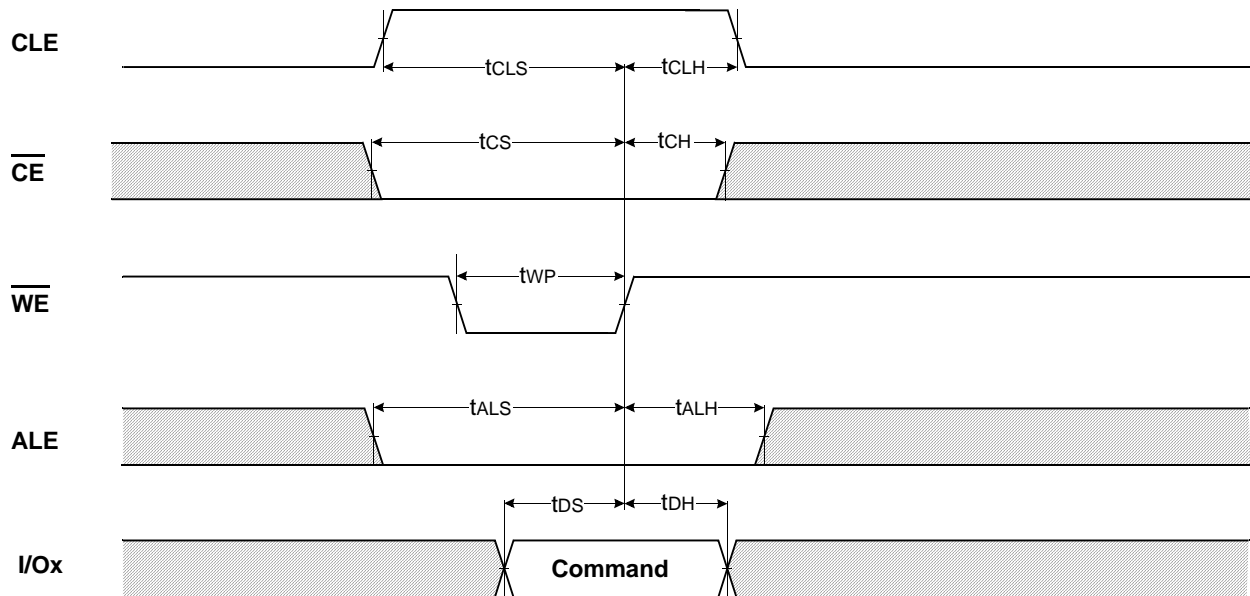


Read Operation with $\overline{\text{CE}}$ don't-care

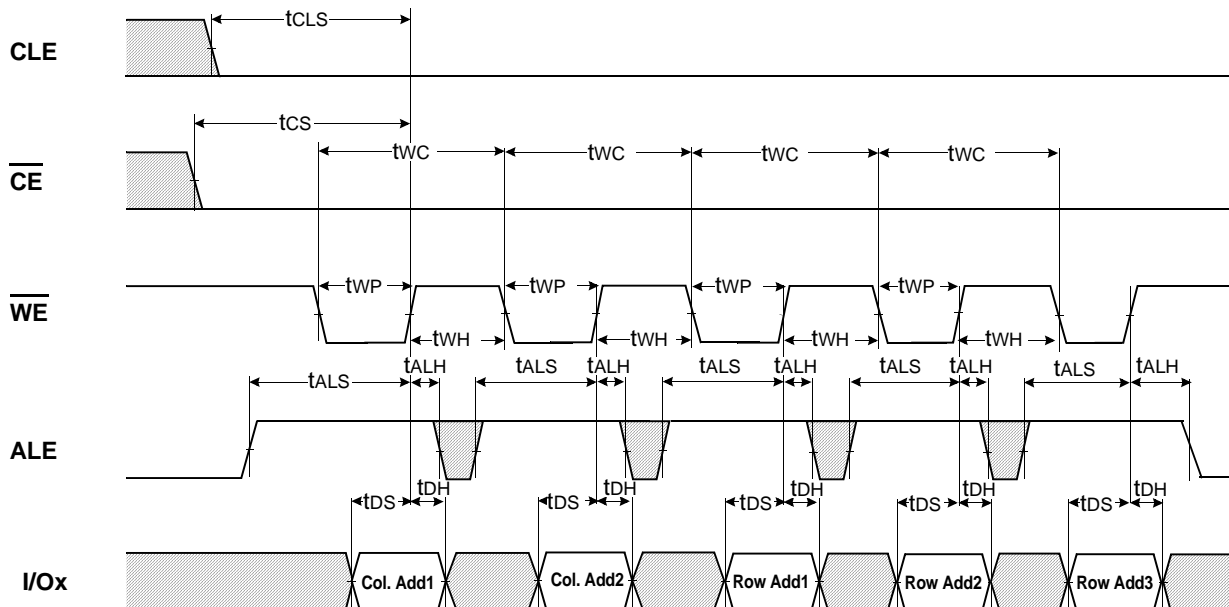


4.0 TIMING DIAGRAMS

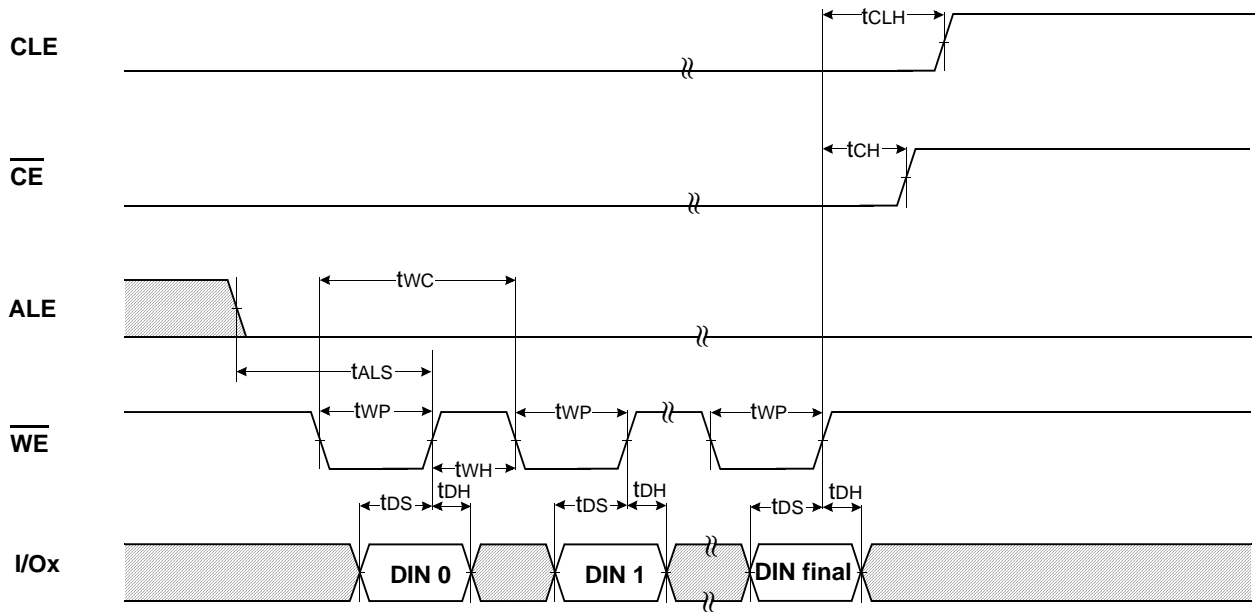
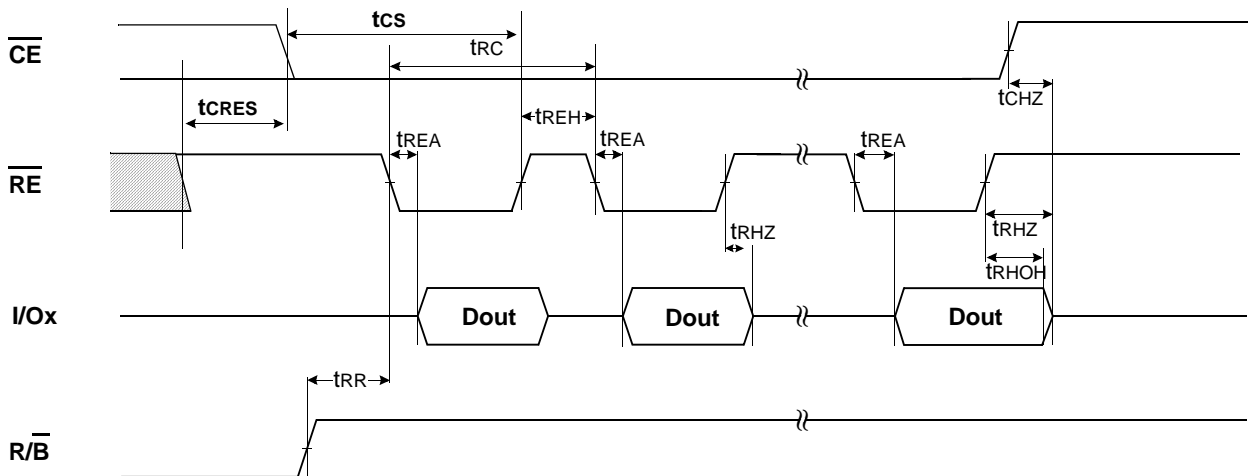
4.1 Command Latch Cycle



4.2 Address Latch Cycle

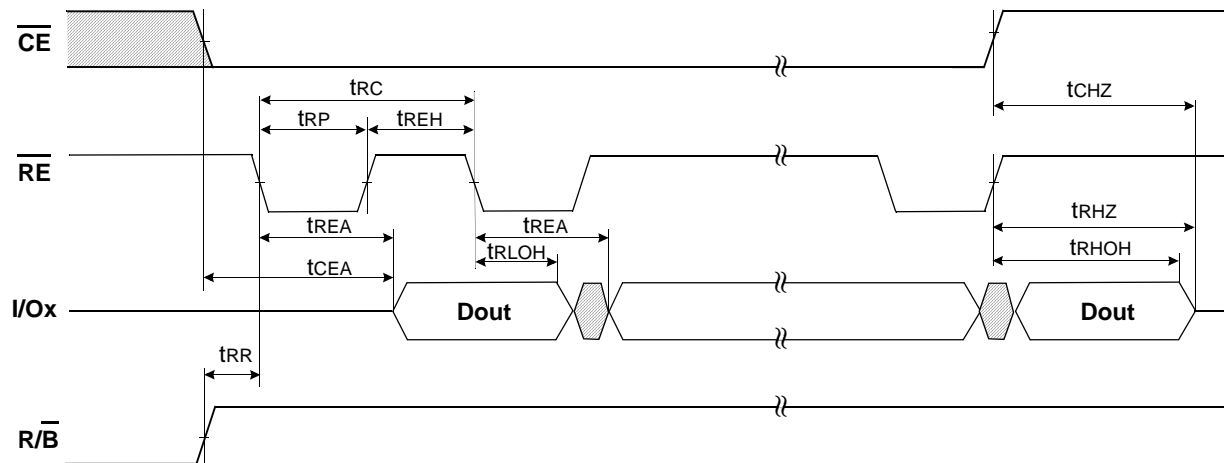


4.3 Input Data Latch Cycle

4.4 * Serial Access Cycle after Read (CLE=L, \overline{WE} =H, ALE=L)

NOTE :

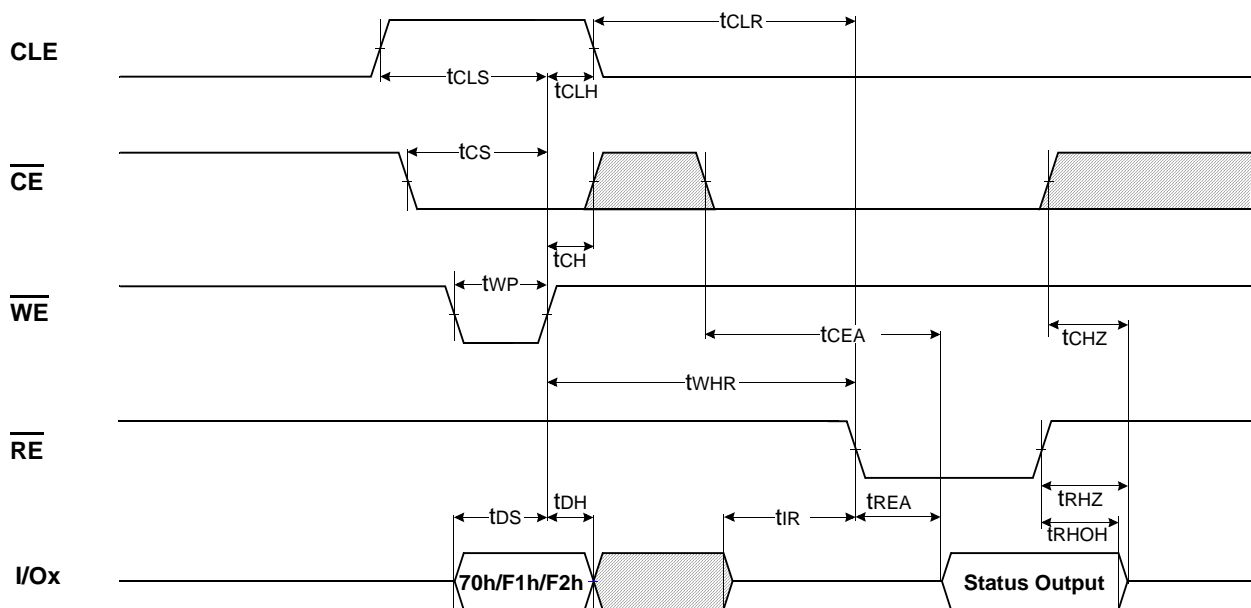
- 1) Transition is measured at $\pm 200\text{mV}$ from steady state voltage with load.
This parameter is sampled and not 100% tested.
- 2) t_{RLOH} is valid when frequency is higher than 20MHz.
 t_{RHOH} starts to be valid when frequency is lower than 20MHz.

4.5 Serial Access Cycle after Read(EDO Type, $\overline{CLE}=L$, $\overline{WE}=H$, $ALE=L$)

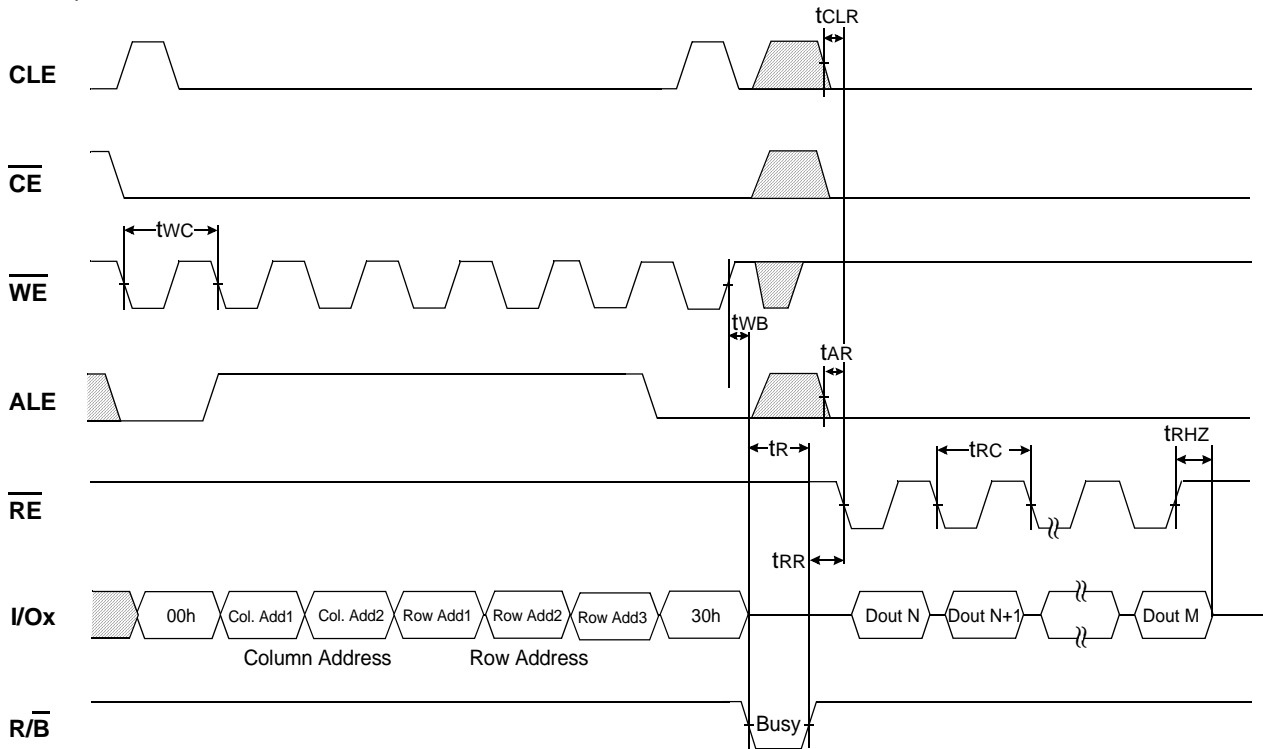
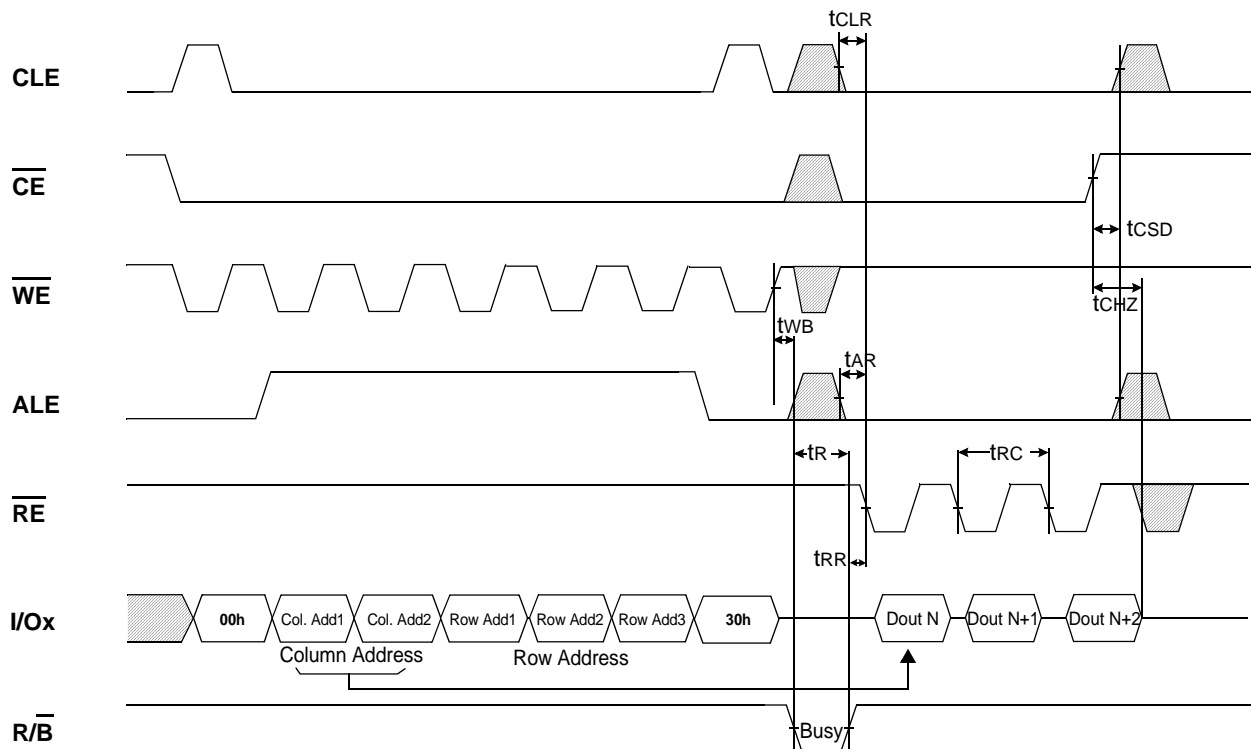
NOTE :

- 1) Transition is measured at $\pm 200\text{mV}$ from steady state voltage with load.
This parameter is sampled and not 100% tested.
- 2) t_{RLOH} is valid when frequency is higher than 20MHz.
 t_{RHOH} starts to be valid when frequency is lower than 20MHz.

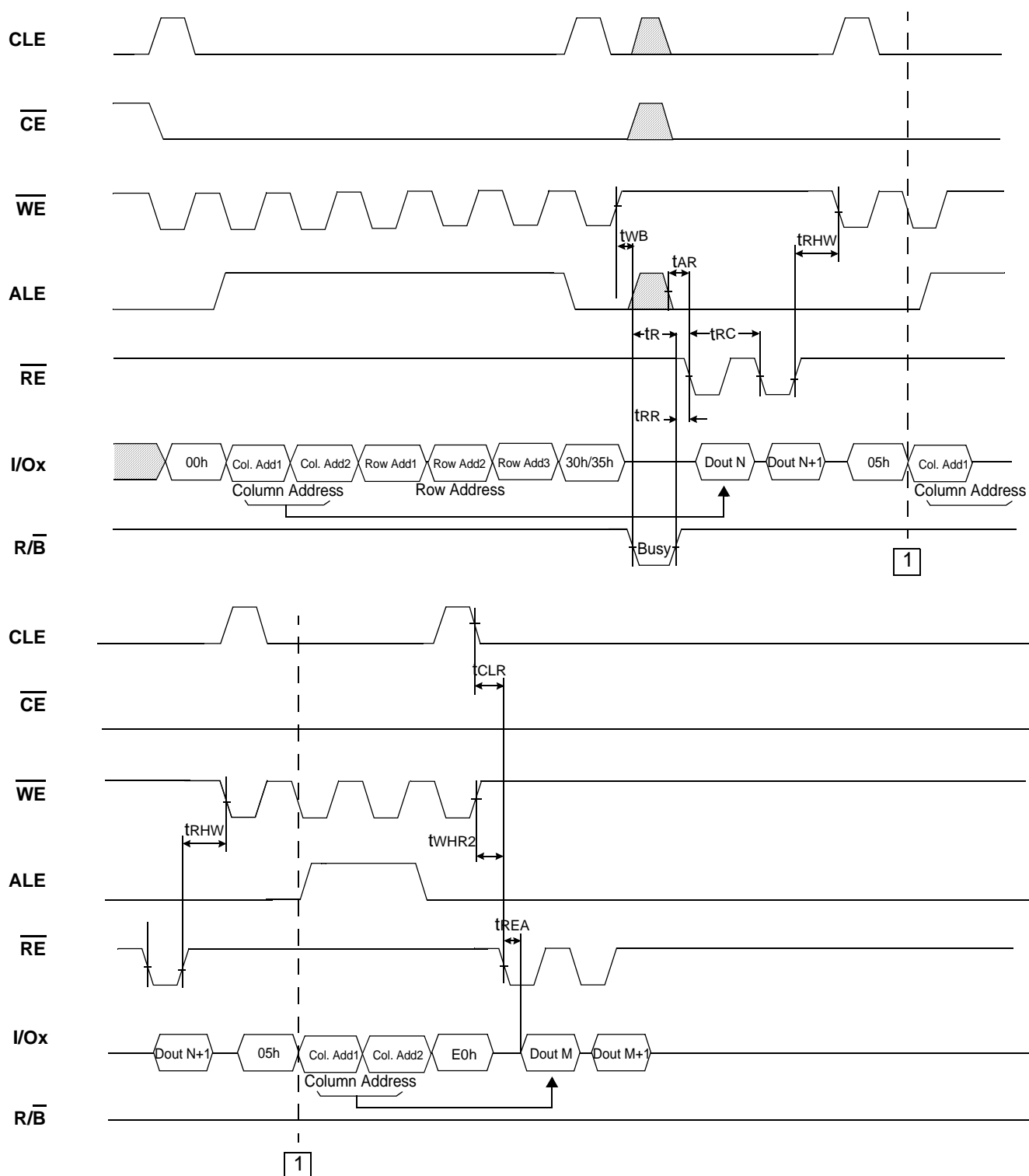
4.6 Status Read Cycle



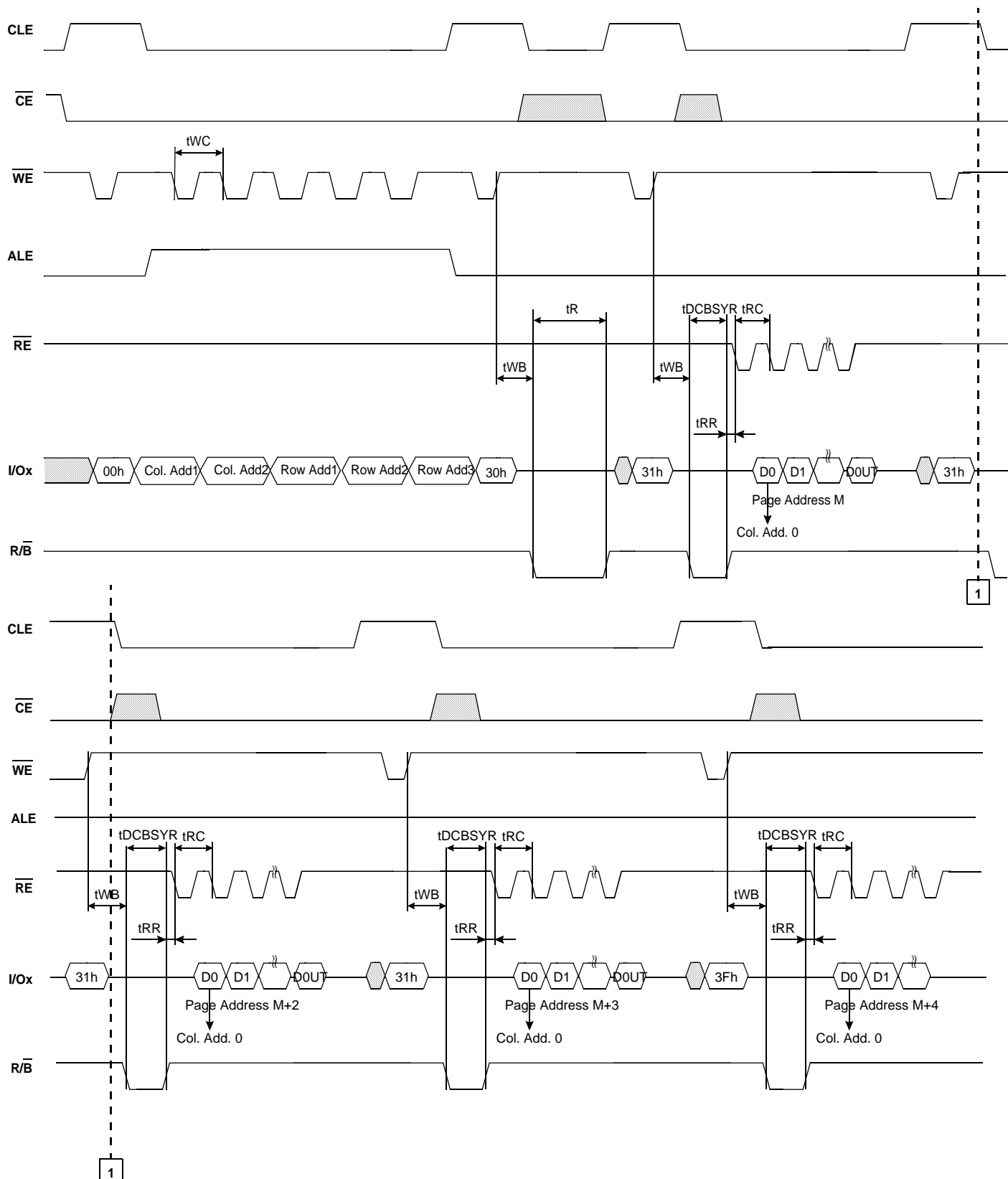
4.7 Read Operation

4.8 Read Operation (Intercepted by $\overline{\text{CE}}$)

4.9 Random Data Output In a Page



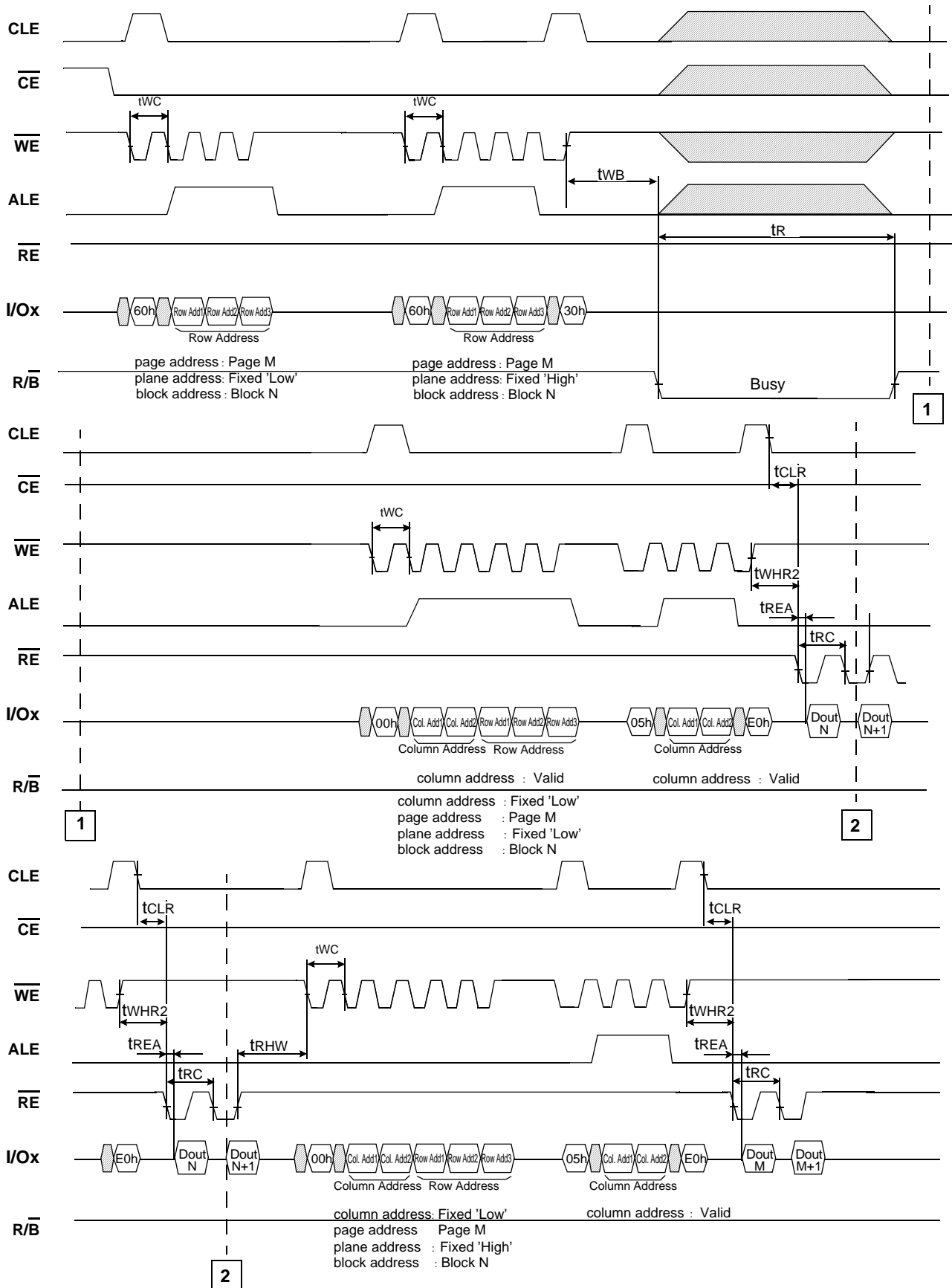
4.10 Cache Read Operation



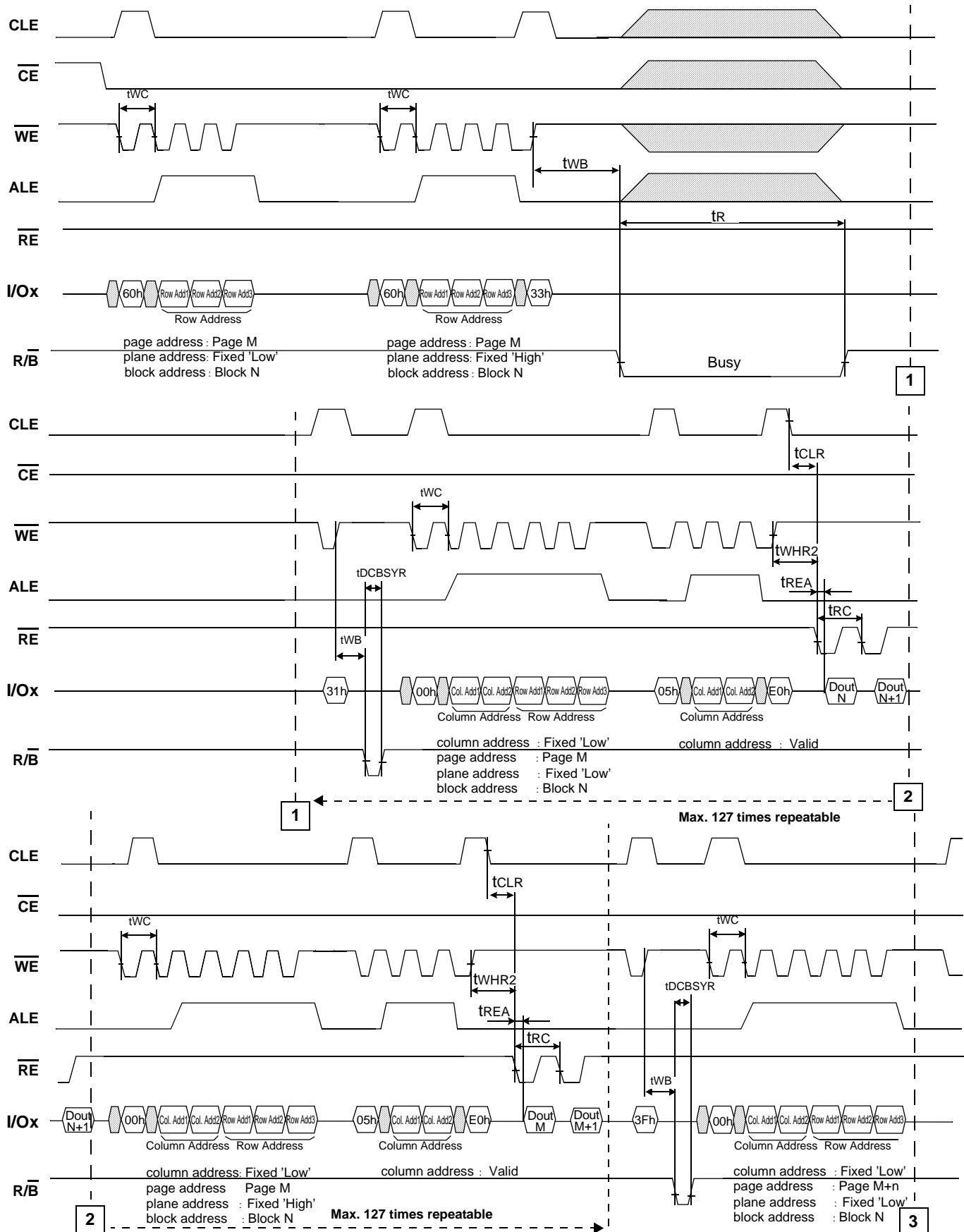
NOTE :

- NOTE:
- 1) The column address will be reset to 0 by the 31h and 3Fh command input.
 - 2) Cache Read operation is available only within a block.

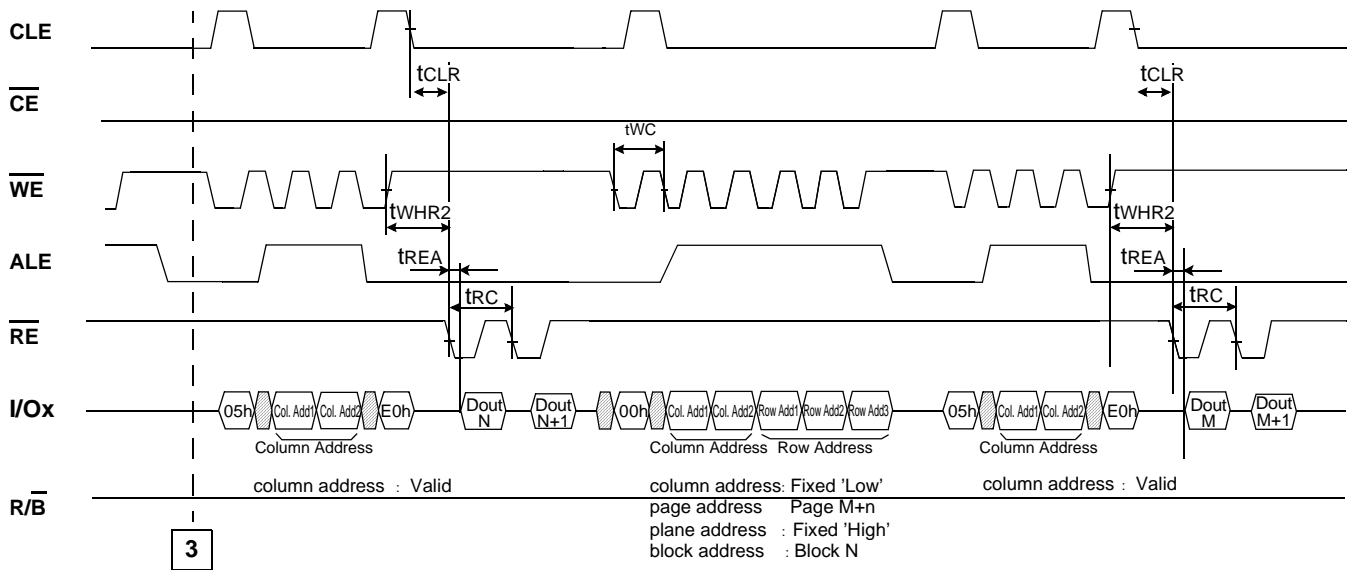
4.11 Two-Plane Page Read Operation with Two-Plane Random Data Out



4.12 Two-Plane Cache Read Operation with Two-Plane Random Data Out (1/2)



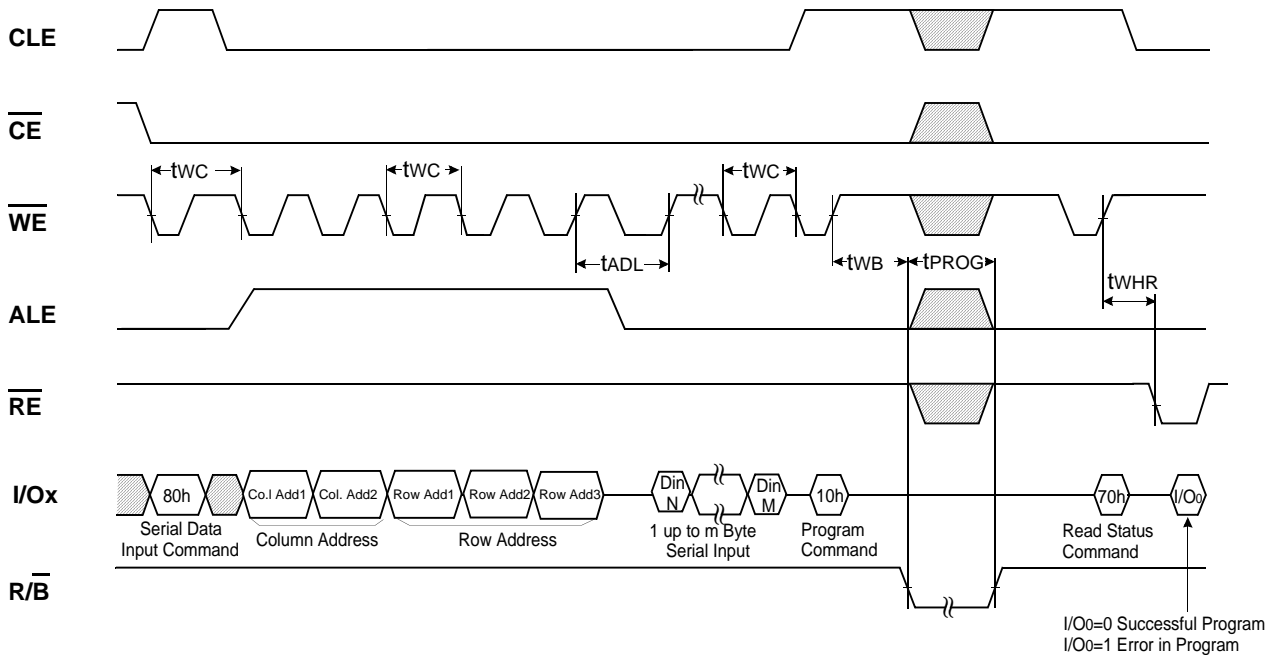
4.13 Two-Plane Cache Read Operation with Two-Plane Random Data Out (2/2)



NOTE :

- 1) The column address will be reset to 0 by the 3Fh command input.
- 2) Cache Read operation is available only within a block.
- 3) Make sure to terminate the operation with 3Fh command. If the operation is terminated by 31h command, monitor I/O 6 (Ready/Busy) by issuing Status Read Command (70h/F1h/F2h) and make sure the previous page read operation is completed. If the page read operation is completed, issue FFh reset before next operation.

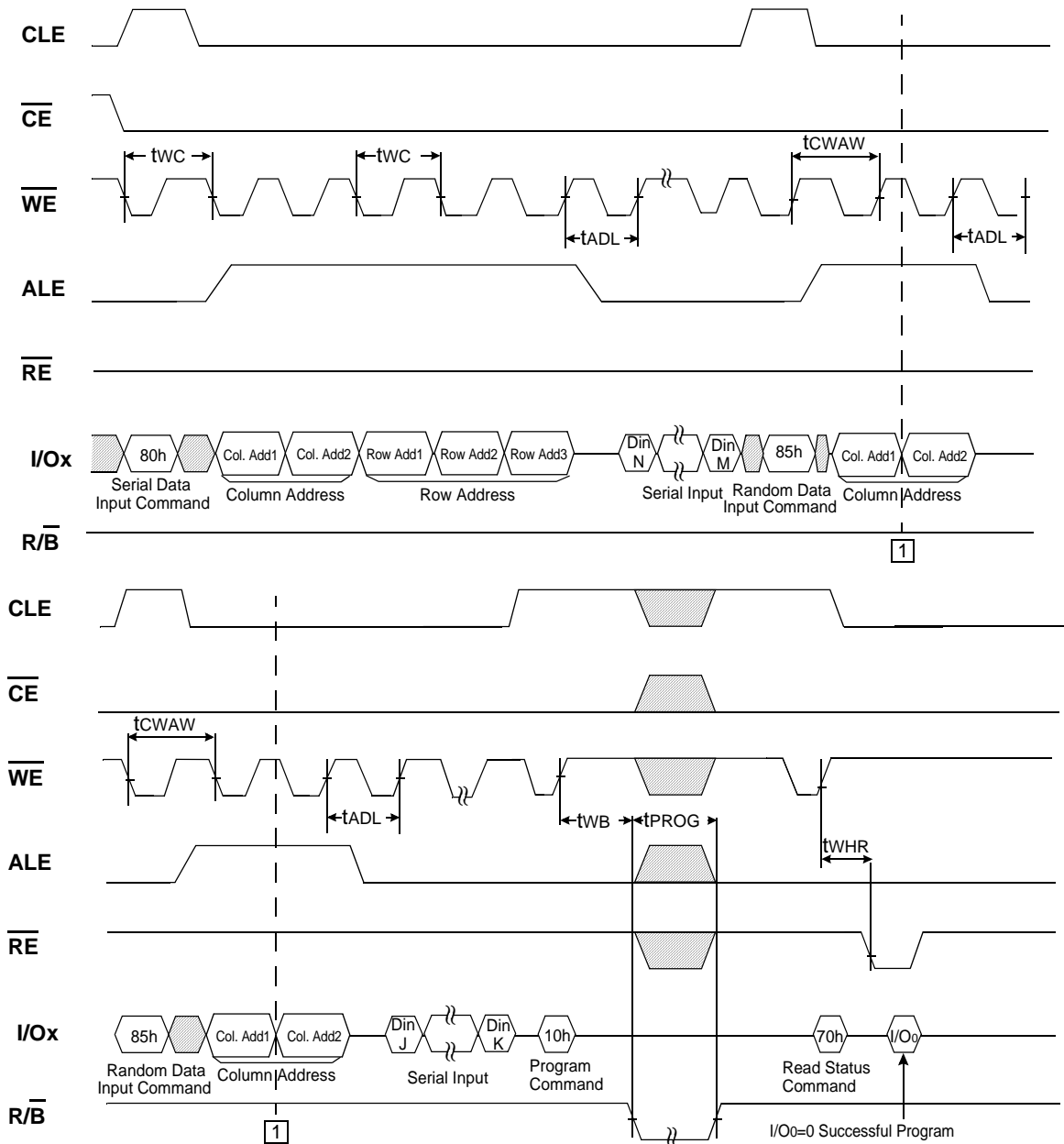
4.14 Page Program Operation



NOTE :

tADL is the time from the \overline{WE} rising edge of final address cycle to the \overline{WE} rising edge of first data cycle.

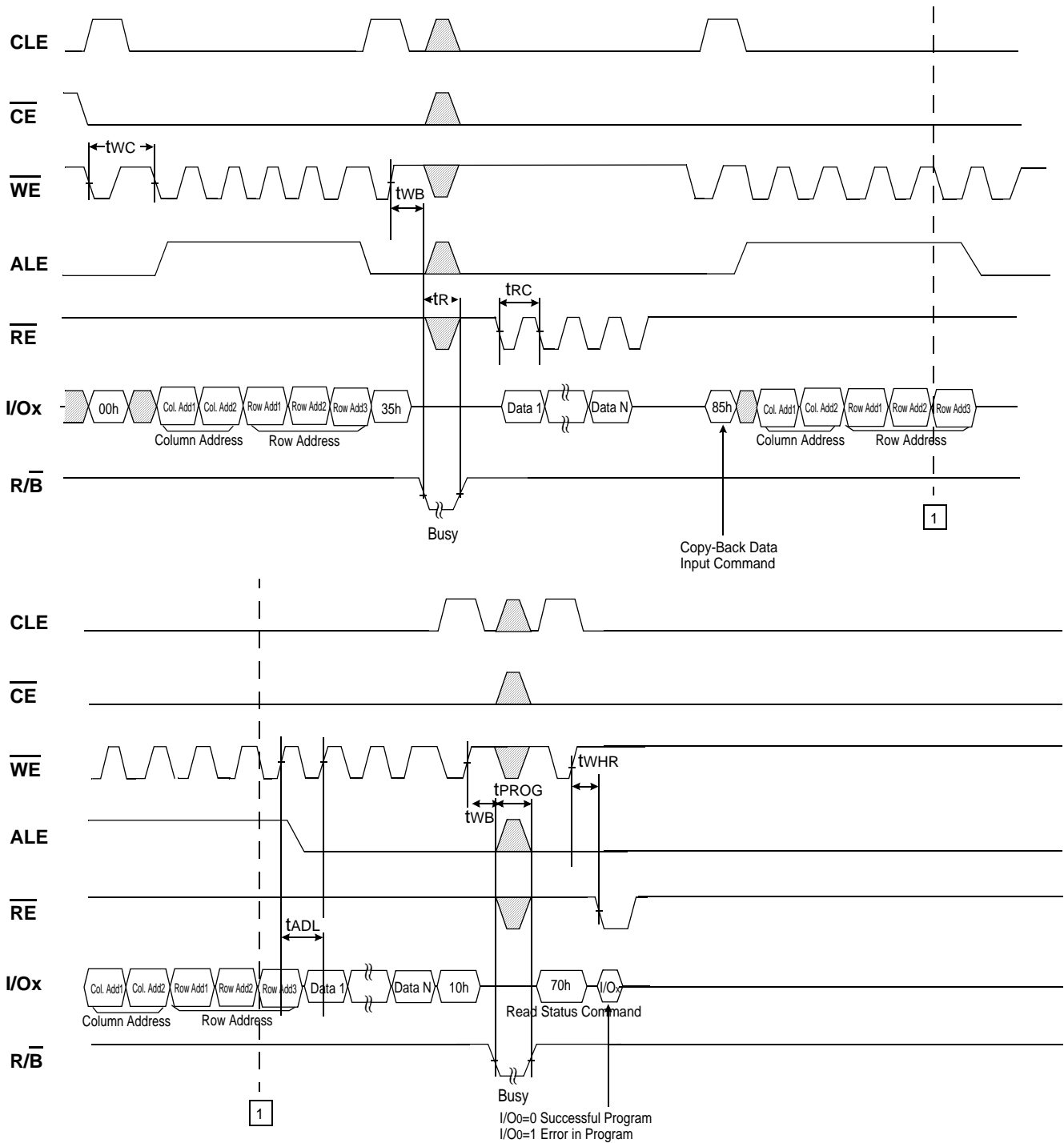
4.15 Page Program Operation with Random Data Input



NOTE :

1) tADL is the time from the \overline{WE} rising edge of final address cycle to the \overline{WE} rising edge of first data cycle.

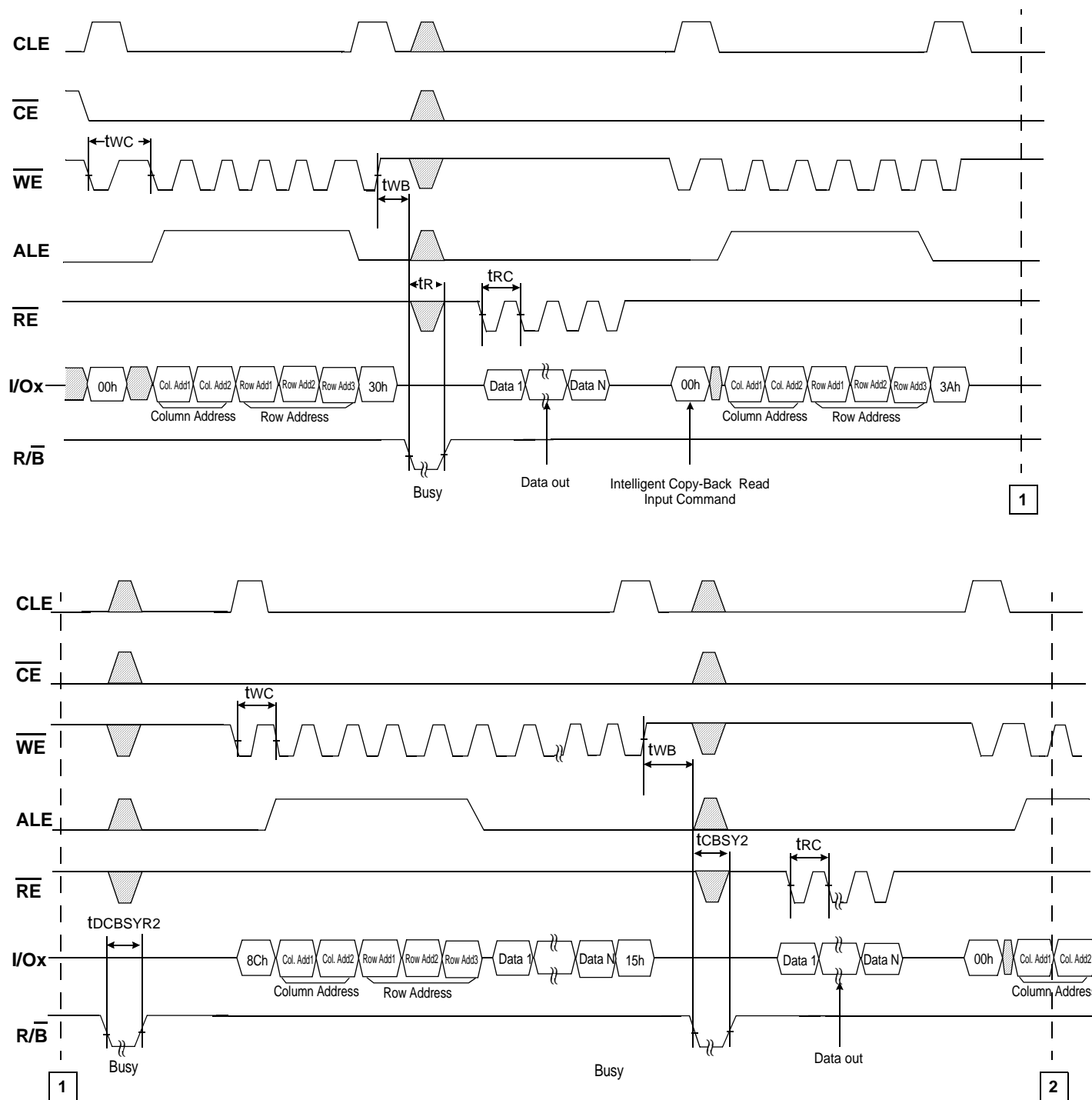
4.16 Copy-Back Program Operation with Random Data Input



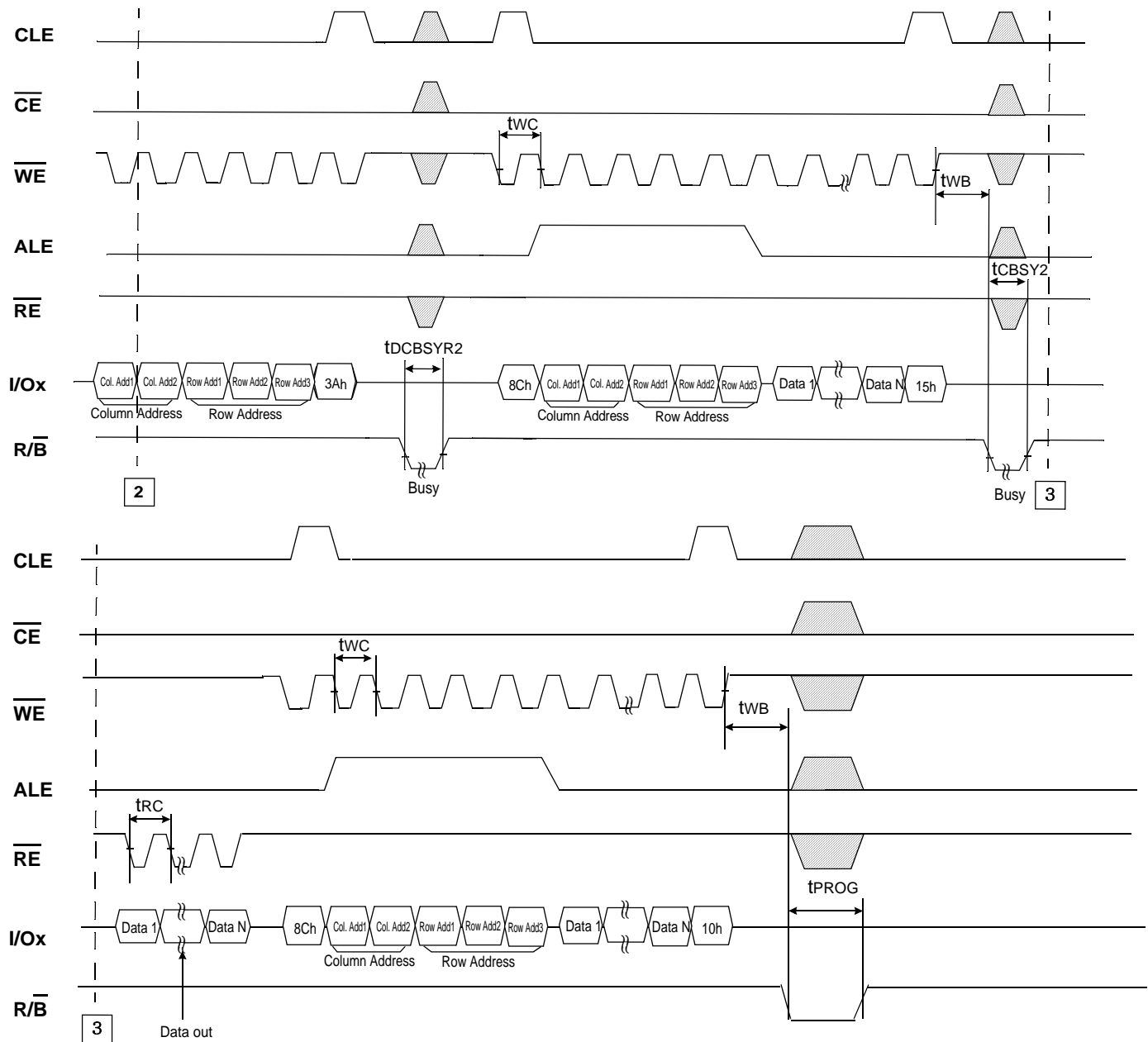
NOTE :

- 1) t_{ADL} is the time from the \overline{WE} rising edge of final address cycle to the \overline{WE} rising edge of first data cycle.
- 2) Copy-Back Program operation is allowed only within the same memory plane.

4.17 Intelligent Copy-Back Program(1/2)



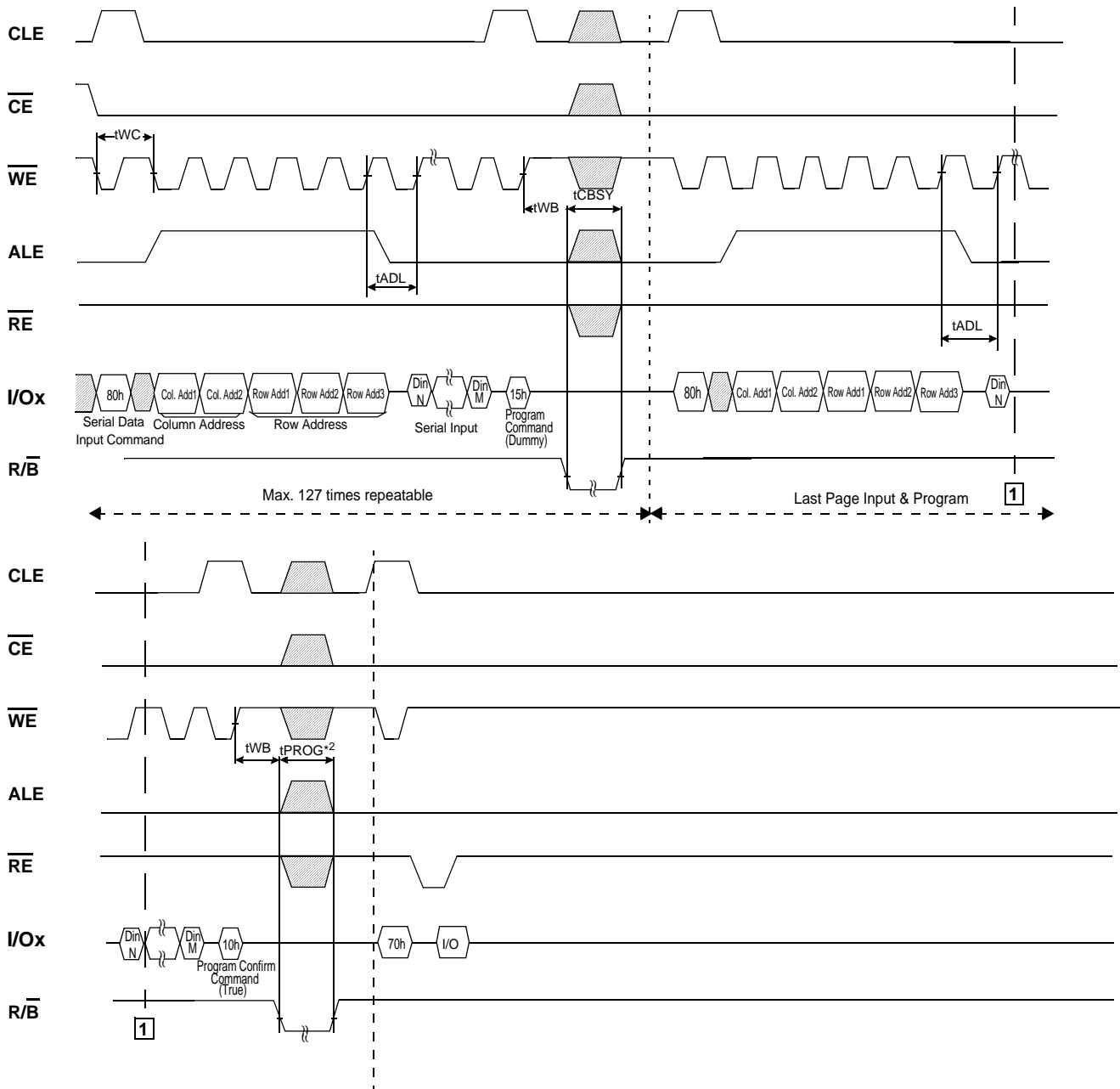
Intelligent Copy-Back Program(2/2)



NOTE :

1) Intelligent copy-Back Program operation is allowed only within the same memory plane.

4.18 Cache Program Operation(available only within a block)

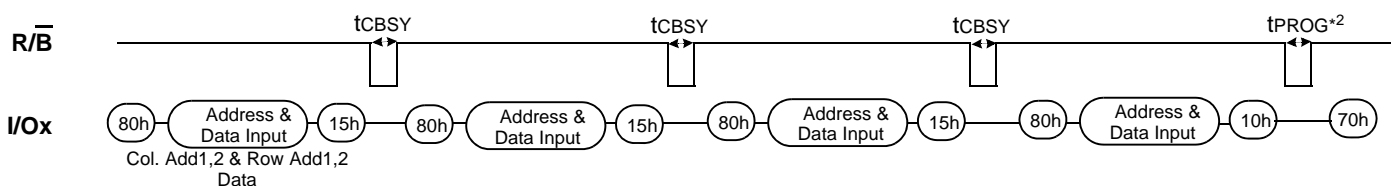


NOTE :

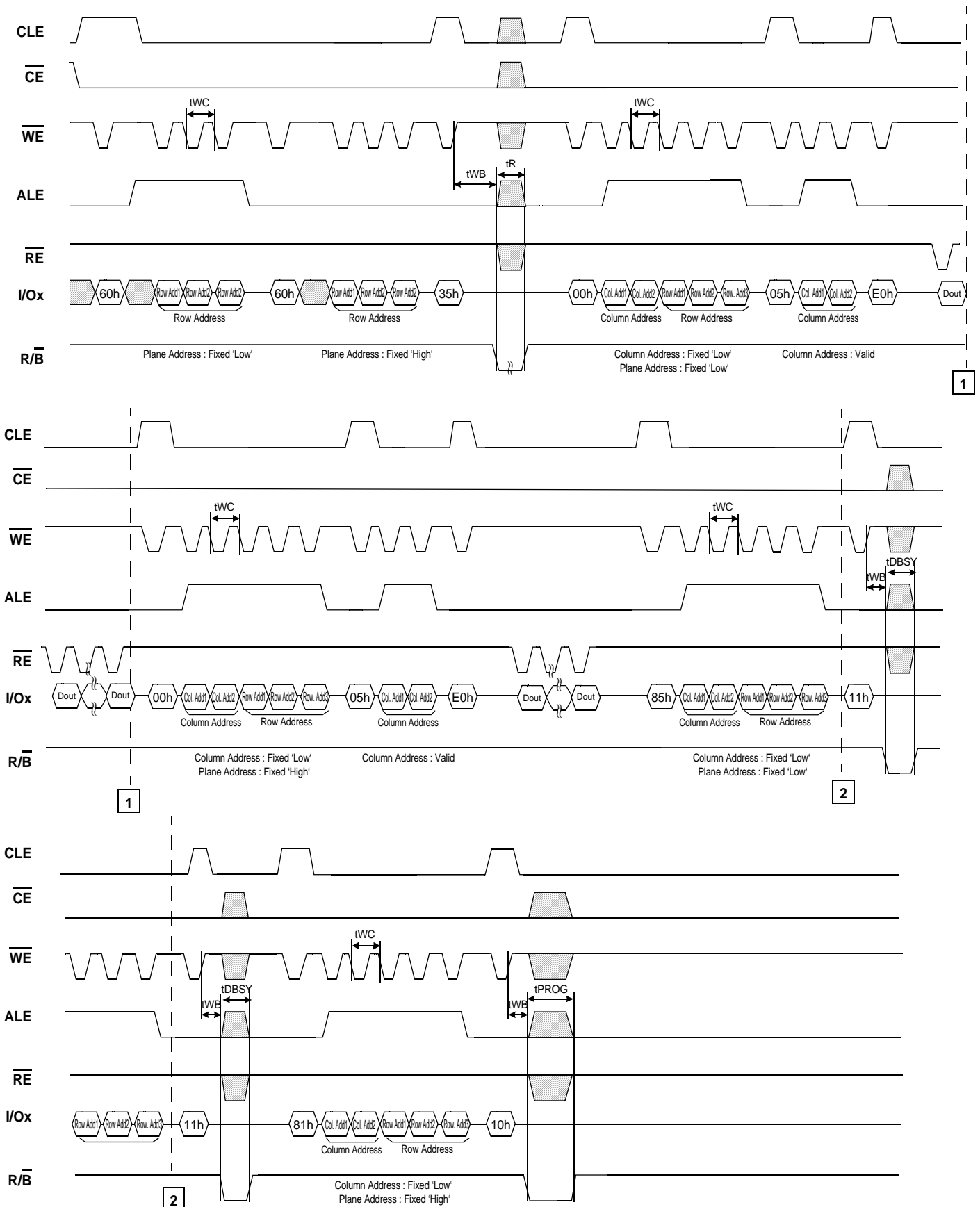
- 1) tADL is the time from the WE rising edge of final address cycle to the WE rising edge of first data cycle.
- 2) Since programming the last page does not employ caching, the program time has to be that of Page Program. However, if the previous program cycle with the cache data has not finished, the actual program cycle of the last page is initiated only after completion of the previous cycle, which can be expressed as the following formula.

$$tPROG = \text{Program time for the last page} + \text{Program time for the (last - 1)^{th} \text{ page} - (\text{command input cycle time} + \text{address input cycle time} + \text{Last page data loading time})$$
 Maximum tPROG is 10ms in this case.

e.g.) Cache Program



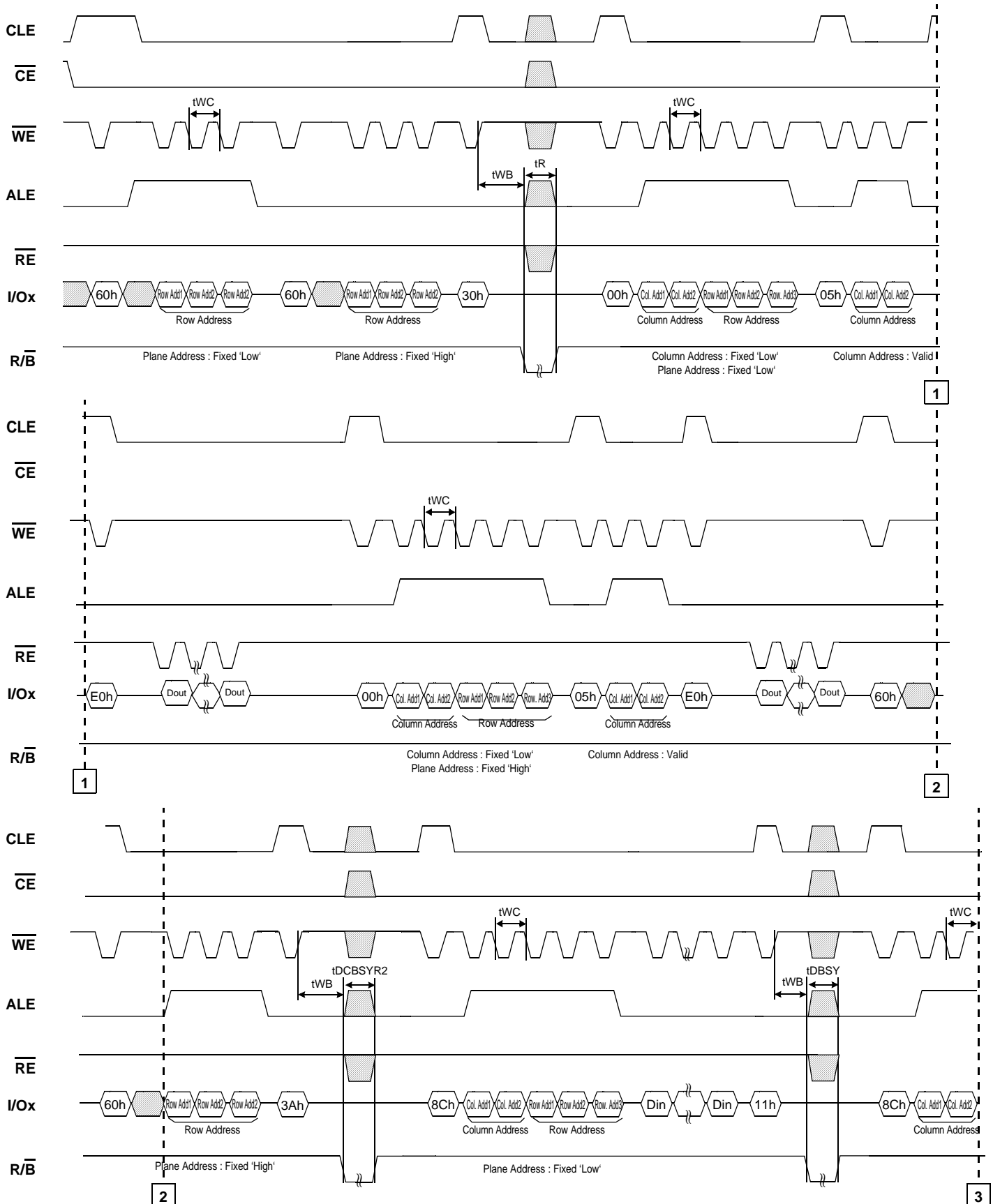
4.19 Two-Plane Copy-Back Program



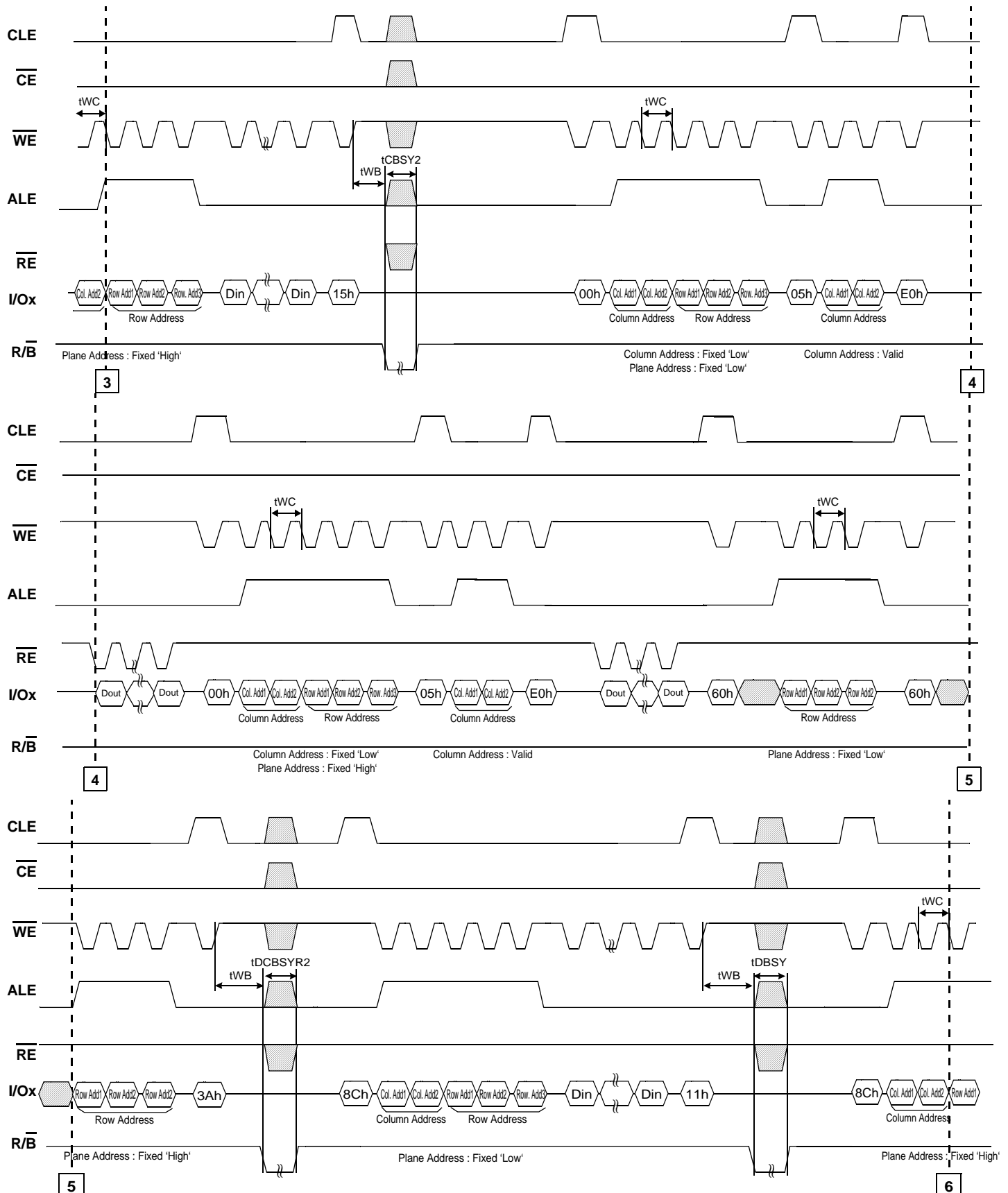
NOTE :

1) Copy-Back Program operation is allowed only within the same memory plane.

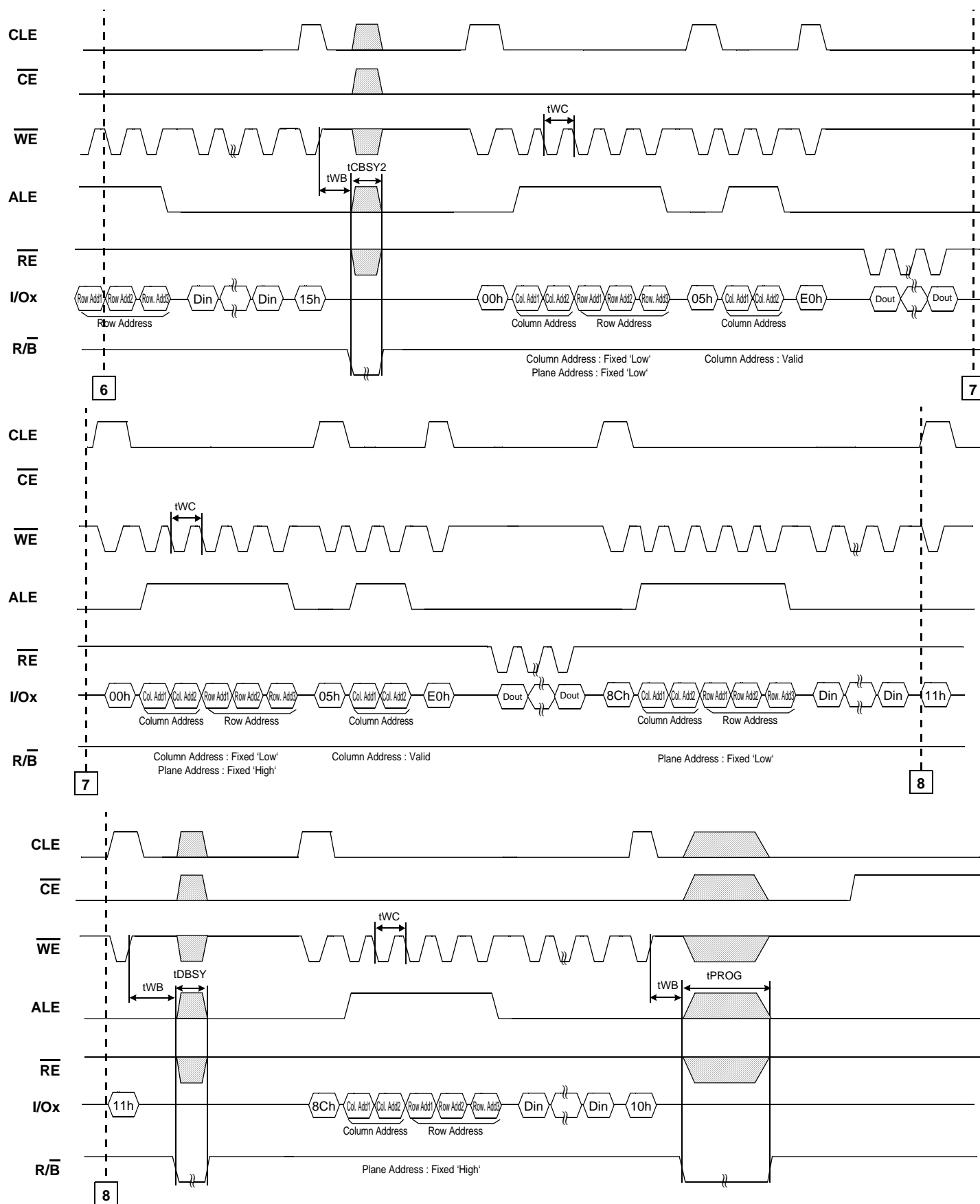
4.20 Two-Plane Intelligent Copy-Back Program(1/3)



Two-Plane Intelligent Copy-Back Program(2/3)



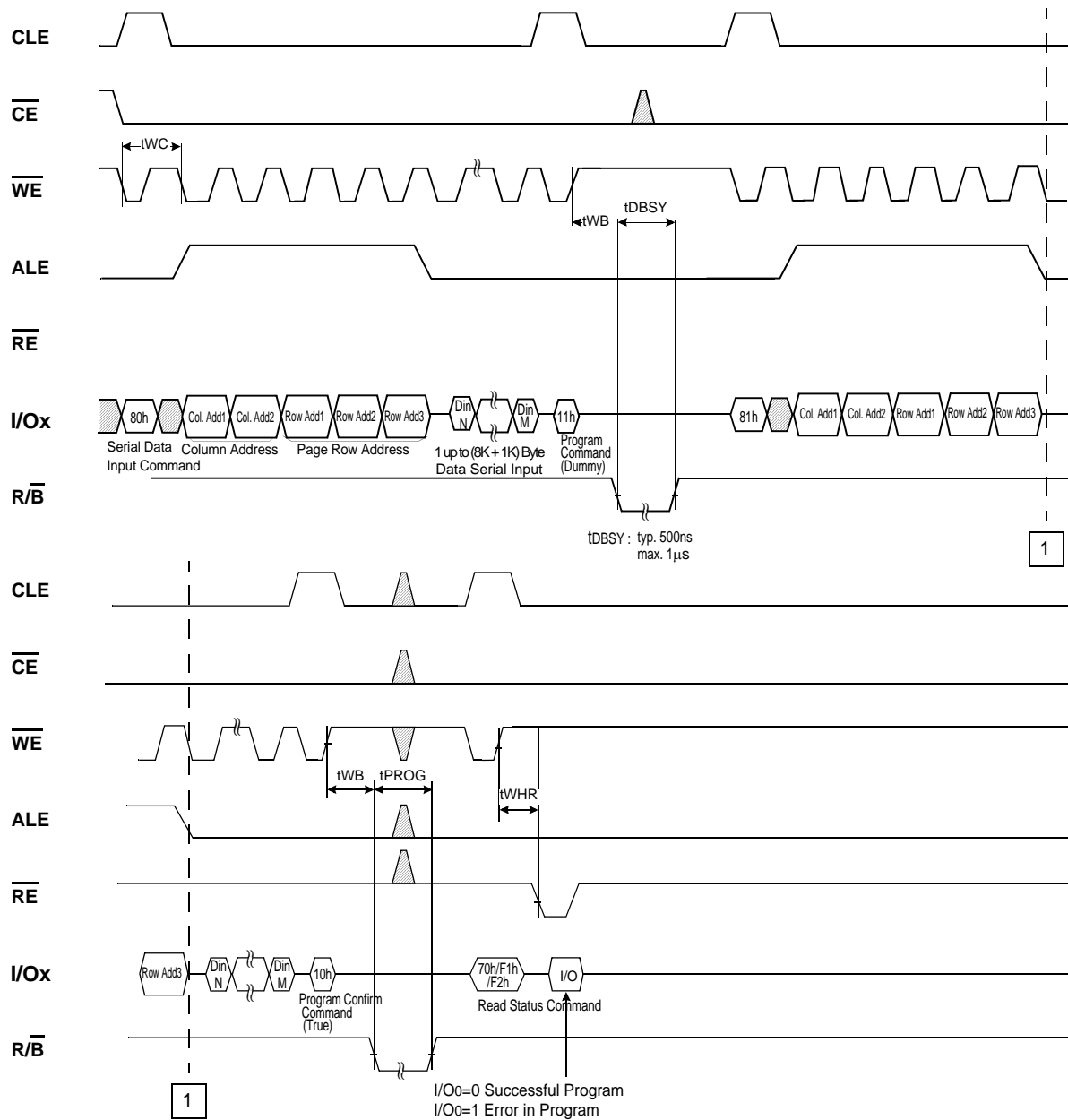
Two-Plane Intelligent Copy-Back Program(3/3)



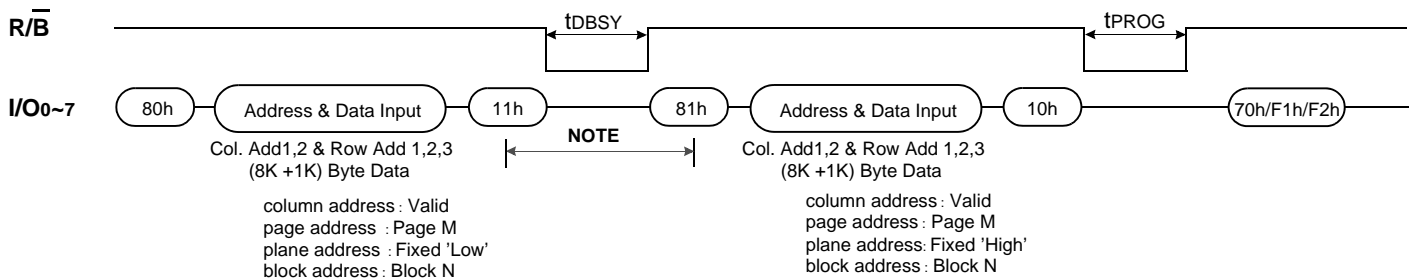
NOTE :

1) Intelligent copy-Back Program operation is allowed only within the same memory plane.

4.21 Two-Plane Page Program Operation

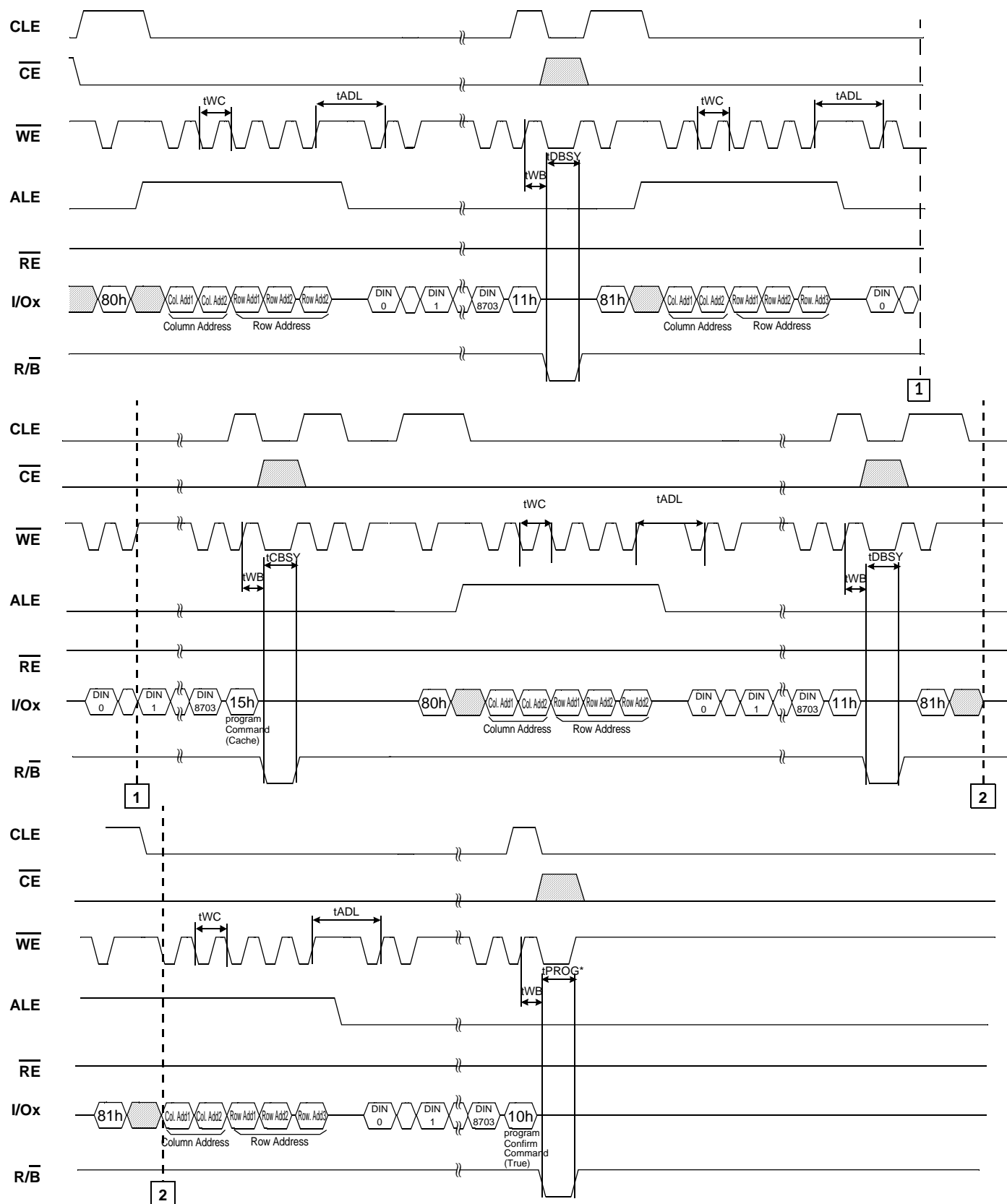


e.g.) Two-Plane Page Program



NOTE :
Any command between 11h and 81h is prohibited except 70h/F1h/F2h and FFh.

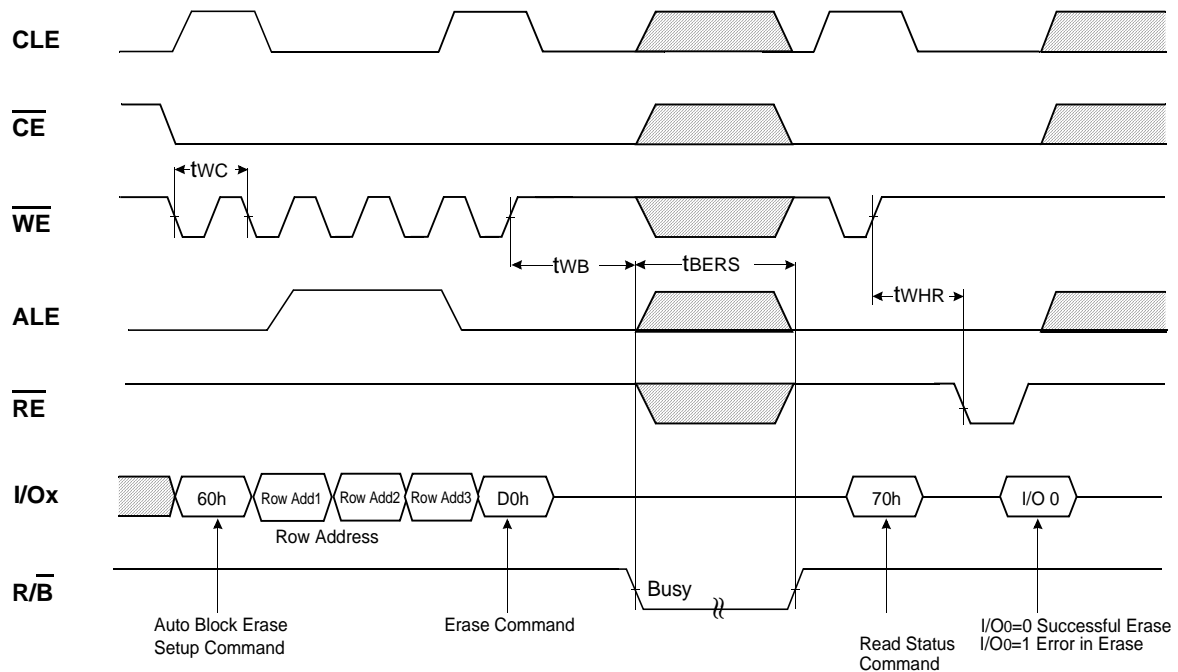
4.22 Two-Plane Cache Program Operation



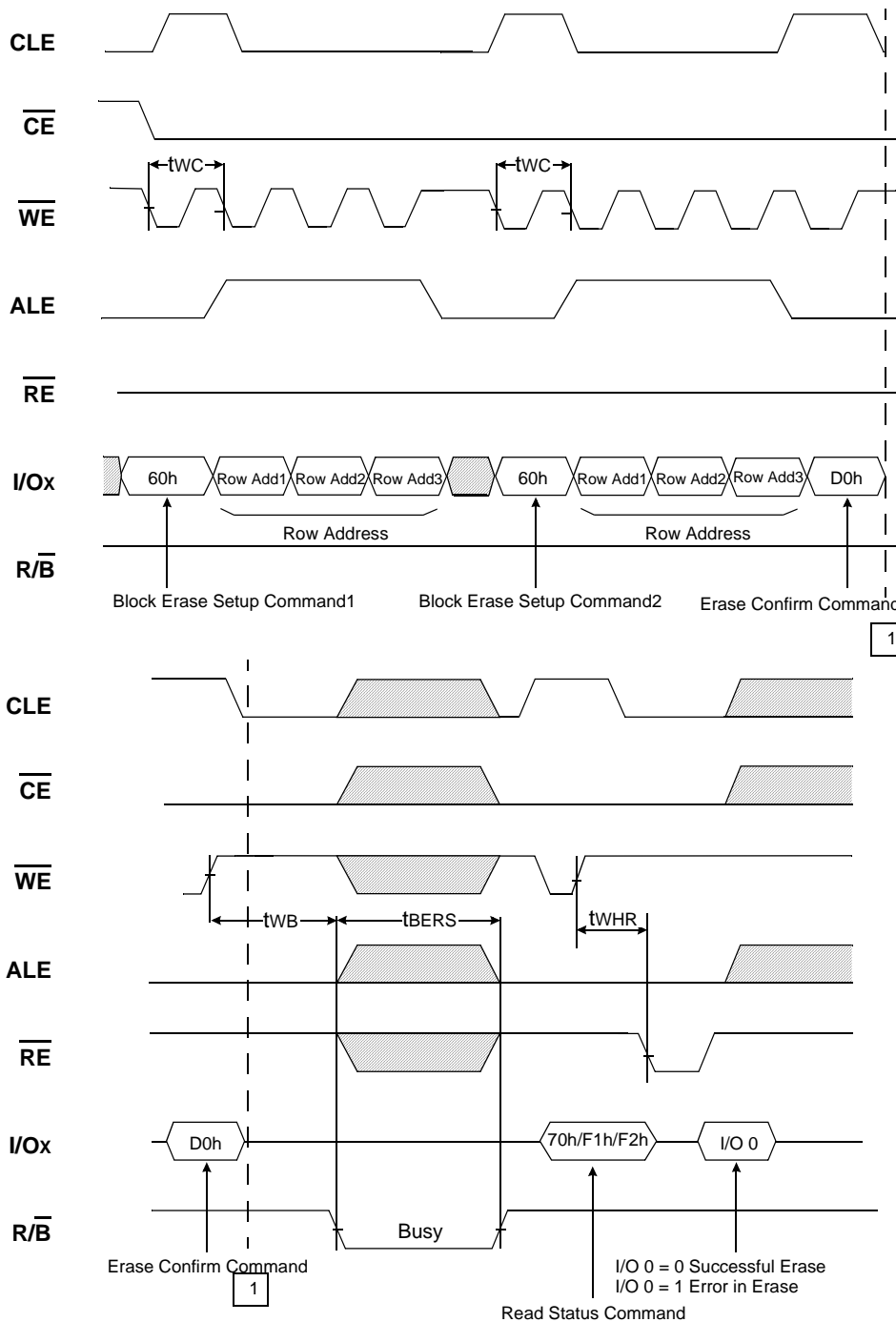
NOTE :

- 1) $tPROG$ = Program time for the last page + Program time for the (last -1)th page - (command input cycle time + address input cycle time + Last page data loading time)
- 2) Make sure to terminate the operation with 80h-10h- command sequence. If the operation is terminated by 80h-15h command sequence, monitor I/O 6 (Ready/Busy) by issuing Status Read Command (70h/F1h/F2h) and make sure the previous page program operation is completed. If the page program operation is completed issue FFh reset before next operation.

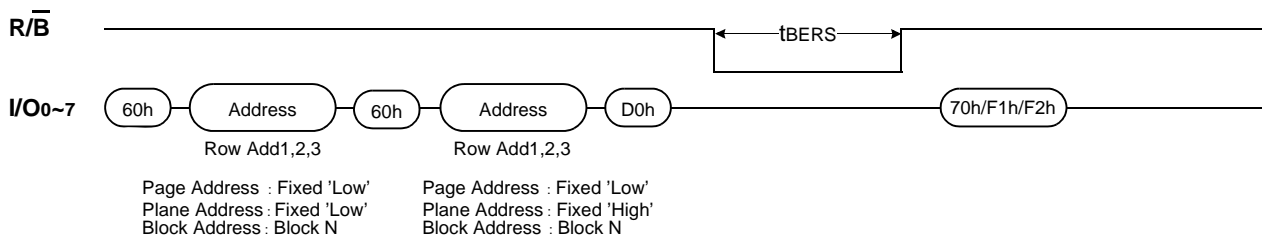
4.23 Block Erase Operation



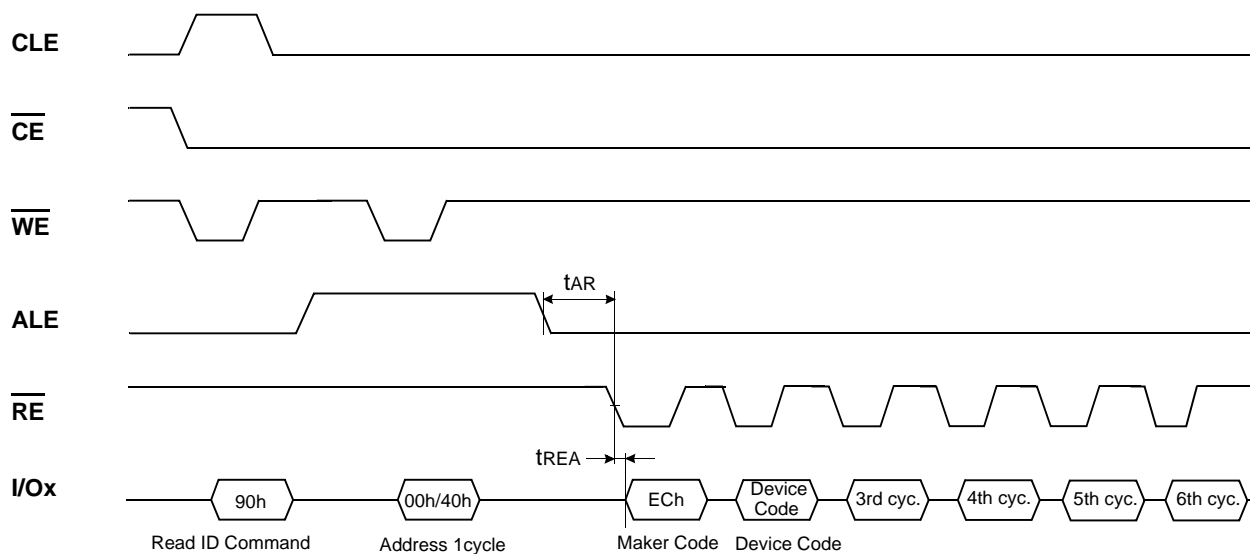
4.24 Two-Plane Block Erase Operation



e.g.) Address Restriction for Two-Plane Block Erase Operation



4.25 Read ID Operation



NOTE :

1) Address 00h is for Samsung legacy and 40h is for new JEDEC ID informat

4.26 00h Address ID Cycle

| Device | 1st Cycle | 2nd Cycle | 3rd Cycle | 4th Cycle | 5th Cycle | 6th Cycle |
|------------|-----------|-----------|-----------|-----------|-----------|-----------|
| K9GBG08U0B | ECh | D7h | 94h | 7Eh | 64h | 44h |
| K9LCG08U0B | | DEh | D5h | | 68h | |
| K9HDG08U1B | | DEh | D5h | | 68h | |

4.27 40h Address ID Cycle

| Device | 1st Cycle | 2nd Cycle | 3rd Cycle | 4th Cycle | 5th Cycle | 6th Cycle |
|------------|-----------|-----------|-----------|-----------|-----------|-----------|
| K9XXG08UXB | 4Ah | 45h | 44h | 45h | 43h | 01h |

00h Address ID Definition Table

| | Description |
|----------------------|--|
| 1 st Byte | Maker Code |
| 2 nd Byte | Device Code |
| 3 rd Byte | Internal Chip Number, Cell Type, Number of Simultaneously Programmed Pages, Etc. |
| 4 th Byte | Page Size, Block Size, Redundant Area Size. |
| 5 th Byte | Plane Number, ECC Level, Organization. |
| 6 th Byte | Device Technology, EDO, Interface. |

3rd ID Data

| | Description | IO7 | IO6 | IO5 IO4 | IO3 IO2 | IO1 IO0 |
|---|---------------|-----|-----|---------|---------|---------|
| Internal Chip Number | 1 | | | | | 0 0 |
| | 2 | | | | | 0 1 |
| | 4 | | | | | 1 0 |
| | 8 | | | | | 1 1 |
| Cell Type | 2 Level Cell | | | | 0 0 | |
| | 4 Level Cell | | | | 0 1 | |
| | 8 Level Cell | | | | 1 0 | |
| | 16 Level Cell | | | | 1 1 | |
| Number of Simultaneously Programmed Pages | 1 | | | 0 0 | | |
| | 2 | | | 0 1 | | |
| | 4 | | | 1 0 | | |
| | 8 | | | 1 1 | | |
| Interleaving operation between multiple chips | Not Support | | 0 | | | |
| | Support | | 1 | | | |
| Cache Program | Not Support | 0 | | | | |
| | Support | 1 | | | | |

4th ID Data

| | Description | IO7 | IO6 | IO5 IO4 | IO3 | IO2 | IO1 IO0 |
|---|-------------|-----|-----|---------|-----|-----|---------|
| Page Size (w/o redundant area) | 2KB | | | | | | 0 0 |
| | 4KB | | | | | | 0 1 |
| | 8KB | | | | | | 1 0 |
| | Reserved | | | | | | 1 1 |
| Block Size (w/o redundant area) | 128KB | 0 | | 0 0 | | | |
| | 256KB | 0 | | 0 1 | | | |
| | 512KB | 0 | | 1 0 | | | |
| | 1MB | 0 | | 1 1 | | | |
| | Reserved | 1 | | 0 0 | | | |
| | Reserved | 1 | | 0 1 | | | |
| | Reserved | 1 | | 1 0 | | | |
| | Reserved | 1 | | 1 1 | | | |
| Redundant Area Size (byte / Page Size) | Reserved | | 0 | | 0 | 0 | |
| | 128B | | 0 | | 0 | 1 | |
| | 218B | | 0 | | 1 | 0 | |
| | 400B | | 0 | | 1 | 1 | |
| | 436B | | 1 | | 0 | 0 | |
| | 512B | | 1 | | 0 | 1 | |
| | 640B | | 1 | | 1 | 0 | |
| | 1024B | | 1 | | 1 | 1 | |

5th ID Data

| | Description | I/O7 | I/O6 | I/O5 | I/O4 | I/O3 | I/O2 | I/O1 |
|--------------|-------------|------|------|------|------|------|------|------|
| Plane Number | 1 | | | | | 0 | 0 | 0 |
| | 2 | | | | | 0 | 1 | 0 |
| | 4 | | | | | 1 | 0 | 0 |
| | 8 | | | | | 1 | 1 | 0 |
| | 16 | | | | | 1 | 1 | 1 |
| ECC Level | 1bit | | 0 | 0 | 0 | | | |
| | 2bit | | 0 | 0 | 1 | | | |
| | 4bit | | 0 | 1 | 0 | | | |
| | 8bit | | 0 | 1 | 1 | | | |
| | 16bit | | 1 | 0 | 0 | | | |
| | 24bit | | 1 | 0 | 1 | | | |
| | 40bit | | 1 | 1 | 0 | | | |
| | 60bit | | 1 | 1 | 1 | | | |
| Reserved | | 0 | | | | | | 0 |

6th ID Data

| | Description | I/O7 | I/O6 | I/O5 | I/O4 | I/O3 | I/O2 | I/O1 | I/O0 |
|----------------|-------------------|------|------|------|------|------|------|------|------|
| Device Version | 50nm | | | | | | 0 | 0 | 0 |
| | 40nm | | | | | | 0 | 0 | 1 |
| | 30nm | | | | | | 0 | 1 | 0 |
| | 2xnm | | | | | | 0 | 1 | 1 |
| | 2ynm | | | | | | 1 | 0 | 0 |
| | Reserved | | | | | | 1 | 0 | 1 |
| | Reserved | | | | | | 1 | 1 | 0 |
| | Reserved | | | | | | 1 | 1 | 0 |
| | Reserved | | | | | | | | |
| EDO | Not Support | | 0 | | | | | | |
| | Support | | 1 | | | | | | |
| Interface | Conventional Mode | 0 | | | | | | | |
| | Toggle Mode | 1 | | | | | | | |
| Reserved | | | | 0 | 0 | 0 | | | |

40h Address ID Definition Table

| Byte | Description | I/O7 | I/O6 | I/O5 | I/O4 | I/O3 | I/O2 | I/O1 | I/O0 |
|------|-------------------------|------|------|------|------|------|------|------|------|
| 0 | J | 0 | 1 | 0 | 0 | 1 | 0 | 1 | 0 |
| 1 | E | 0 | 1 | 0 | 0 | 0 | 1 | 0 | 1 |
| 2 | D | 0 | 1 | 0 | 0 | 0 | 1 | 0 | 0 |
| 3 | E | 0 | 1 | 0 | 0 | 0 | 1 | 0 | 1 |
| 4 | C | 0 | 1 | 0 | 0 | 0 | 0 | 1 | 1 |
| 5 | Legacy Asynchronous SDR | | | | | 0 | 0 | 0 | 1 |
| | Toggle Mode DDR | | | | | 0 | 0 | 1 | 0 |
| | Synchronous DDR | | | | | 0 | 1 | 0 | 0 |

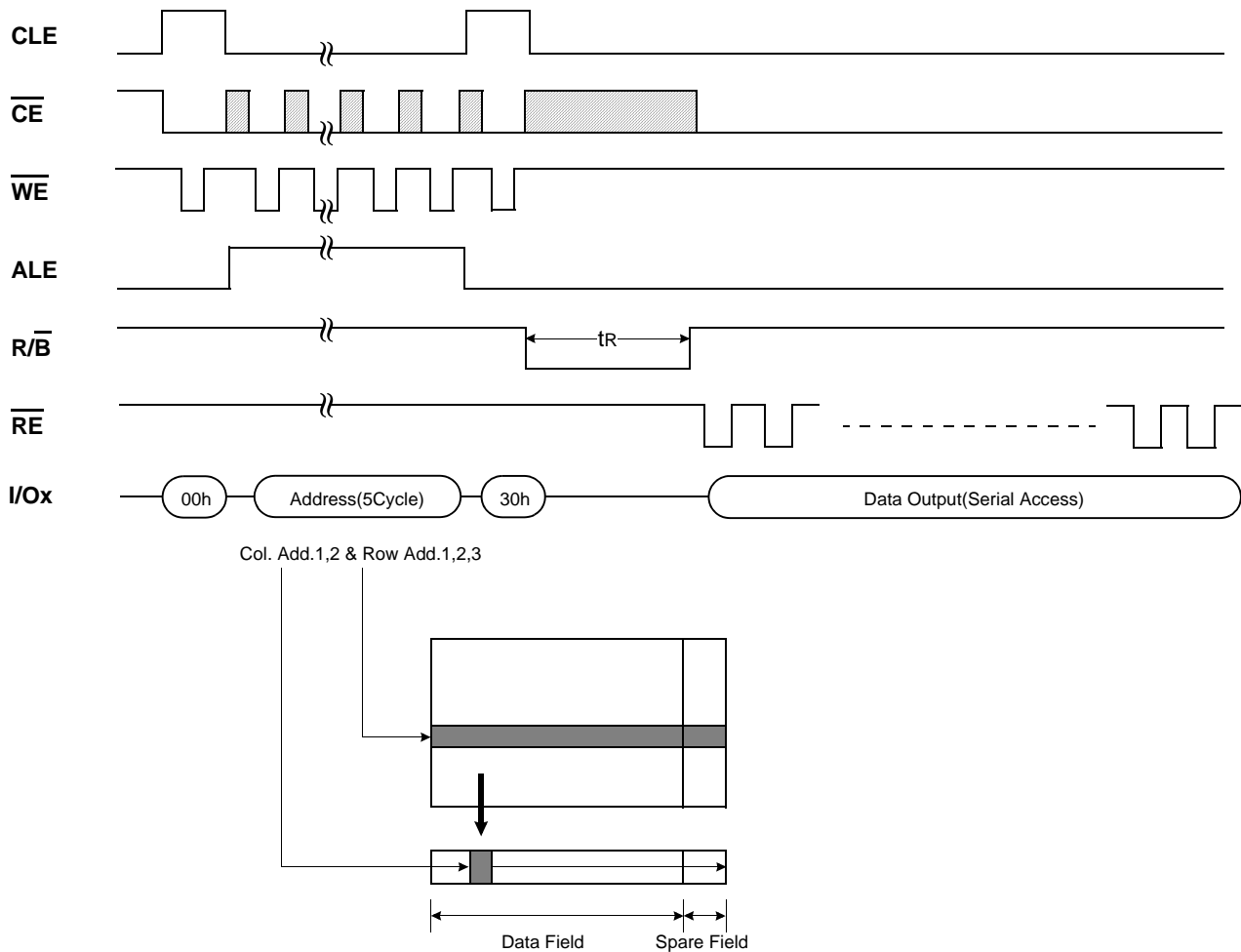
5.0 DEVICE OPERATION

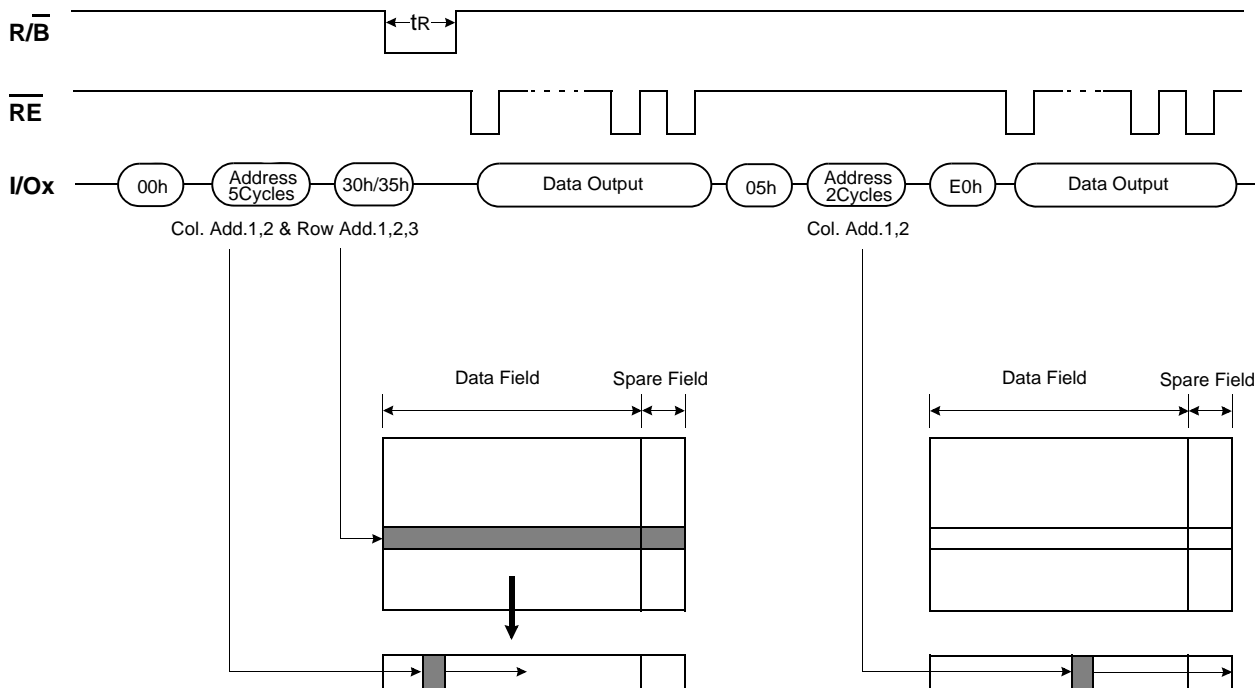
5.1 Page Read

Page read is initiated by writing 00h-30h to the command register along with five address cycles. The (8K+1K) byte of data within the selected page are transferred to the cache registers via data registers in less than t_R . The system controller can detect the completion of this data transfer(t_R) by analyzing the output of R/\overline{B} pin. Once the data in a page is loaded into the cache registers, they may be read out in Read cycle time(t_{RC}) by sequentially pulsing \overline{RE} . The repetitive high to low transitions of the \overline{RE} clock make the device output the data starting from the selected column address up to the last column address.

The device may output random data in a page instead of the consecutive sequential data by writing random data output command. The column address of next data, which is going to be out, may be changed to the address which follows random data output command. Random data output can be operated multiple times regardless of how many times it is done in a page.

Read Operation



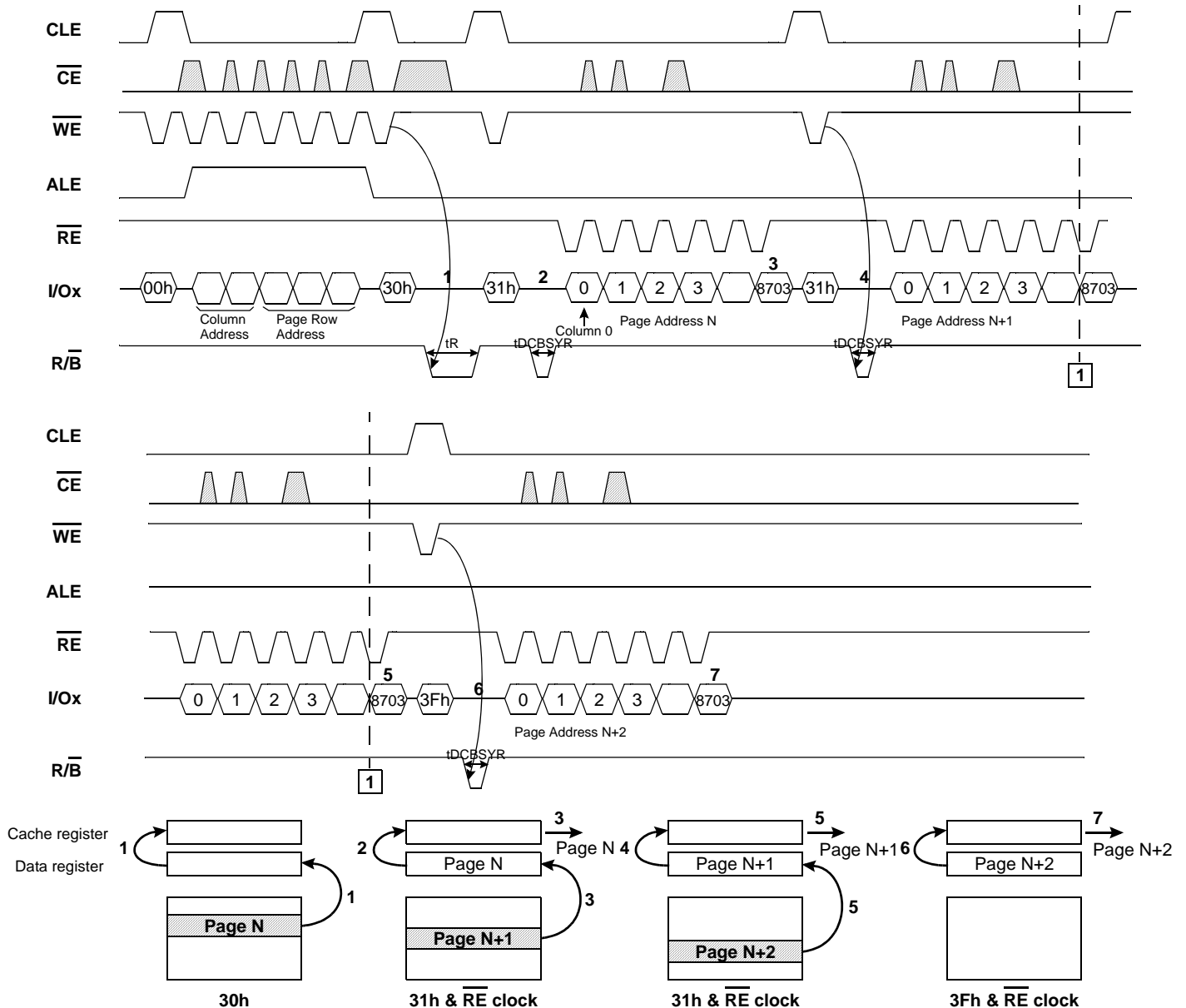
Random Data Output In a Page**5.2 Cache Read**

Cache Read is an extension of Page Read, which is executed with (8K+1K) byte data registers, and is available only within a block. Since the device has 1 page of cache memory, serial data output may be executed while data in the memory cell is read into data registers.

Cache read is also initiated by writing 00h-30h to the command register along with five address cycles. After initial power up, 00h command is latched. Therefore only five address cycles and 30h command initiates that operation after initial power up. The (8K+1K) byte of data within the selected page are transferred to the cache registers via data registers in less than t_R . After issuing Cache Read command(31h), read data in the data registers is transferred to cache registers for a short period of time(t_{DCBSYR}). While the data in the cache registers is read out in Read cycle time(t_{RC}) by sequentially pulsing \overline{RE} , data of next page is transferred to the data registers. By issuing Last Cache Read command(3Fh), last data is transferred to the cache registers from the data registers after the completion of transfer from memory cell to data registers.

Cache Read

The device has a Read operation with cache registers that enables the high speed read operation shown below. When the block address changes, this sequence has to be started from the beginning.



NOTE :

-. If the 31h command is issued to the device, the data content of the next page is transferred to the data registers during serial data out from the cache registers, and therefore the tR (Data transfer from memory cell to data register) will be reduced.

- 1) Normal read. Data is transferred from Page N to cache registers through data registers. During this time period, the device outputs Busy state for tR max.
- 2) After the Ready/Busy returns to Ready, 31h command is issued and data is transferred to cache registers from data registers again. This data transfer takes tDCBSYR max and the completion of this time period can be detected by Ready/Busy signal.
- 3) Data of Page N+1 is transferred to data registers from cell while the data of Page N in cache registers can be read out by RE clock simultaneously.
- 4) The 31h command makes data of Page N+1 transfer to cache registers from data registers after the completion of the transfer from cell to data registers. The device outputs Busy state for tDCBSYR max..This Busy period depends on the combination of the internal data transfer time from cell to data registers and the serial data out time.
- 5) Data of Page N+2 is transferred to data registers from cell while the data of Page N+1 in cache registers can be read out by RE clock simultaneously.
- 6) The 3Fh command makes the data of Page N+2 transfer to the cache registers from the data registers after the completion of transfer from cell to data registers. The device outputs Busy state for tDCBSYR max..This Busy period depends on the combination of the internal data transfer time from cell to data registers and the transfer from data registers to cache registers.
- 7) Data of Page N+2 in cache registers can be read out, but since the 3Fh command does not transfer the data from the memory cell to data registers, the device can accept new command input immediately after the completion of serial data out.

5.3 Two-plane Page Read

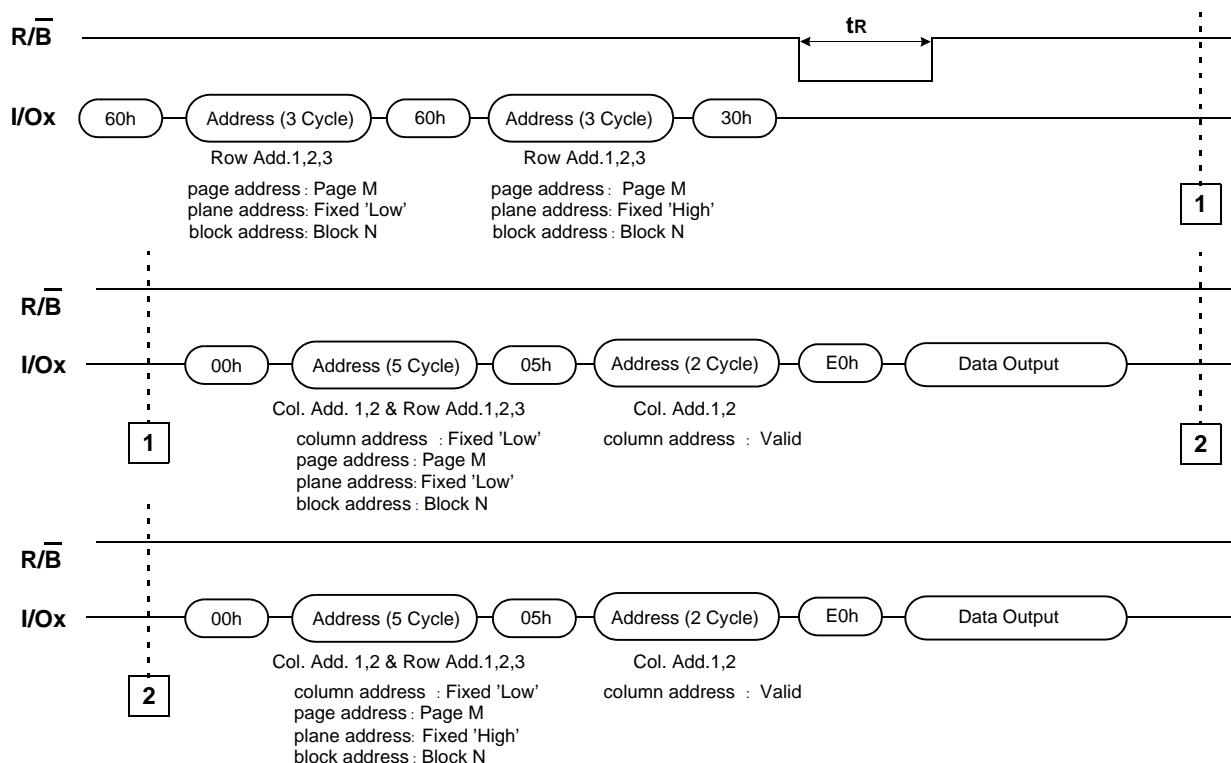
Two-Plane Page Read is an extension of Page Read, for a single plane with (8K+1K) byte data registers. Since the device is two memory plane based, activating the two sets of (8K+1K) byte data registers enables two pages in a row at the same time. Two-Plane Page Read is initiated by writing 60h command with three address cycles twice. In this case, only same page of same block can be selected from each plane.

After Read Confirm command(30h), the (16K +2K)bytes of data within the selected two page are transferred to the data registers in less than tR. The system controller can detect the completion of data transfer(tR) by monitoring the output of R/B pin.

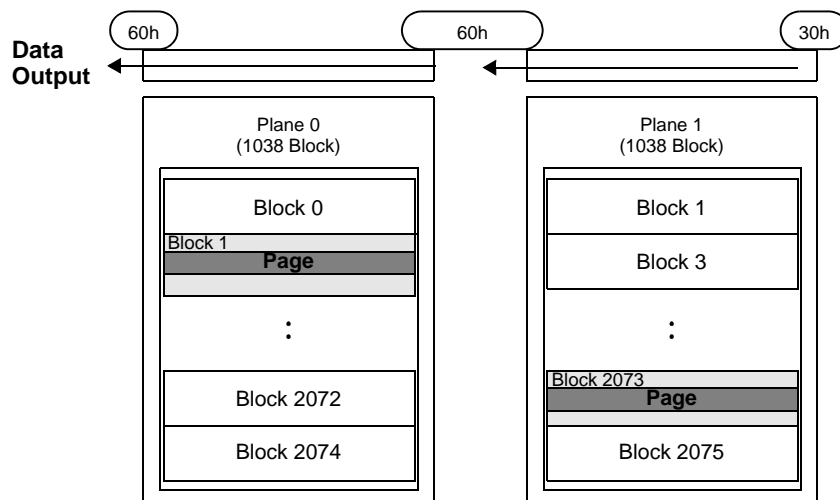
Once the data is loaded into the data registers, the data output of first plane can be read out with a following sequence: command 00h - five address cycles - command 05h - two column address - command E0h. The data output of second plane can be read out using the identical command/address sequence.

Two-Plane Read must be used in the block which is programmed with Two-Plane Page Program.

Two-Plane Page Read Operation with Two-Plane Random Data Out



Unaligned Two-Plane Page Read Operation



NOTE :

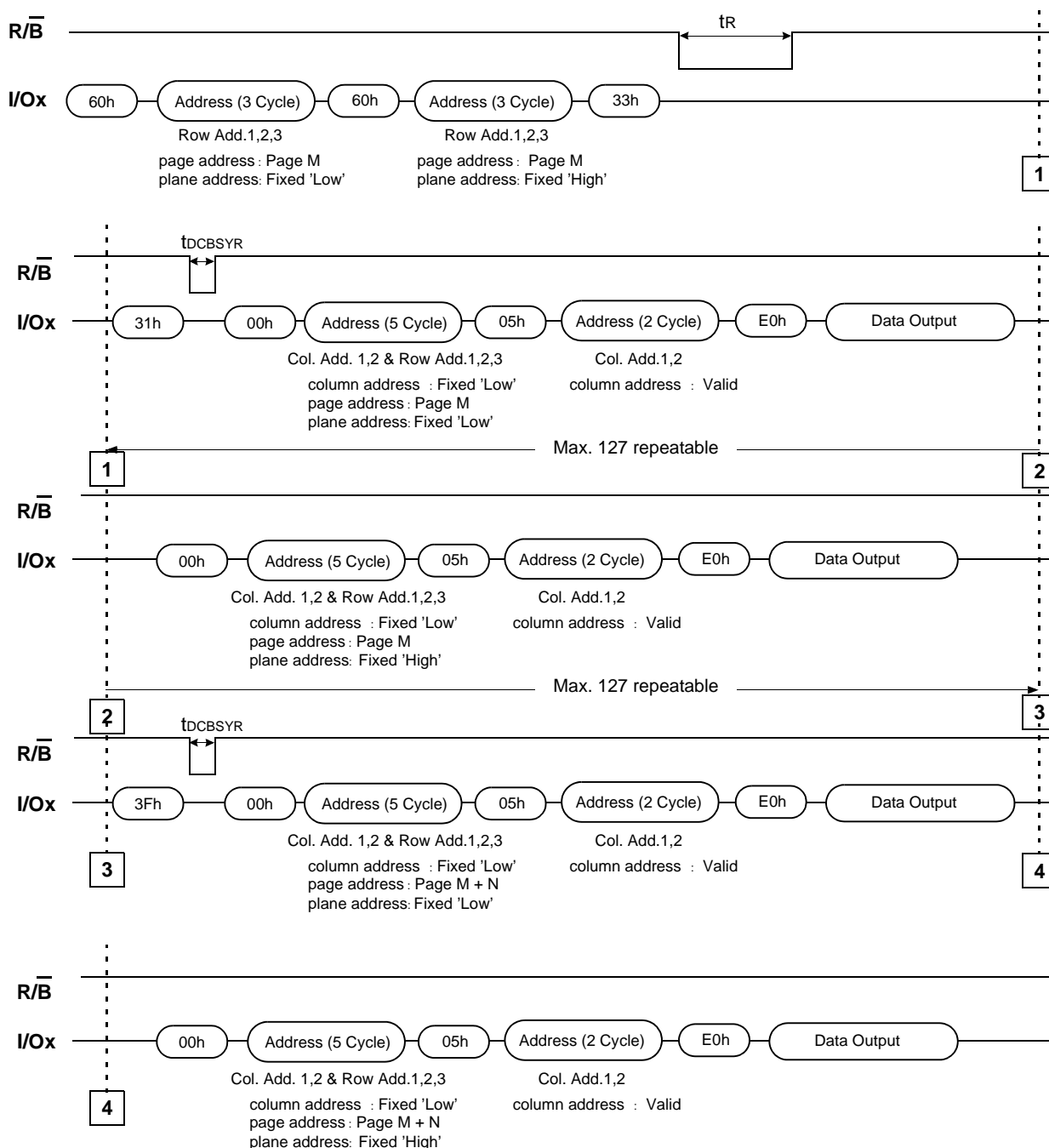
1) Two-Plane page Read operation shall be supported in unaligned block address, as long as address are same in all pages.

5.4 Two-plane Cache Read

Two-Plane Cache Read is an extension of Cache Read, for a single plane with (8K+1K) byte data registers. Since the device is two memory plane based, activating the two sets of (8K+1K) byte data registers enables a cache read of two pages. Two-Plane Cache Read is initiated by repeating command 60h followed by three address cycles twice. In this case only same page of same block can be selected from each plane.

After Read Confirm command(33h) the (16K +2K)bytes of data within the selected two page are transferred to the cache registers via data registers in less than tR. After issuing Cache Read command(31h), read data in the data registers is transferred to cache registers for a short period of time(tDCBSYR). Once the data is loaded into the cache registers from data registers, the data output of first plane can be read out by issuing command 00h with Five Address Cycles, command 05h with two column address and finally E0h. The data output of second plane can be read out using the identical command sequences. The detail sequence of Two-Plane Cache Read is shown below.

Two-Plane Cache Read Operation with Two-Plane Random Data Out



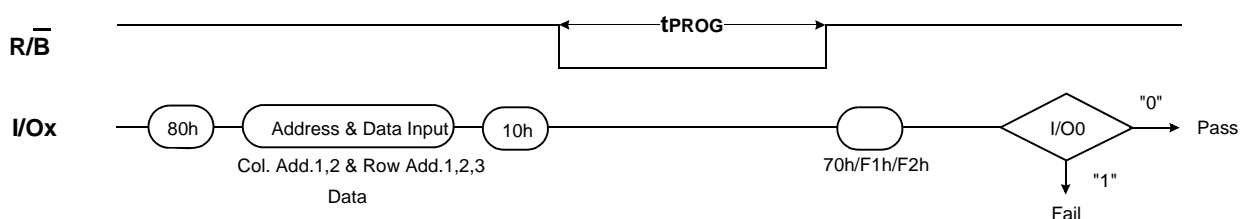
5.5 Page Program

The device is programmed basically on a page basis, and the number of consecutive partial page programming operation within the same page without an intervening erase operation(NOP) must not exceed 1 time for the page, and partial programming less than the minimum randomization unit is not allowed. Also, unwritten sectors in a page must be loaded with randomized data before program operation. The addressing should be done in sequential order in a block. A page program cycle consists of a serial data loading period in which up to (8K+1K) byte of data may be loaded into the data registers via cache registers, followed by a non-volatile programming period where the loaded data is programmed into the appropriate cell.

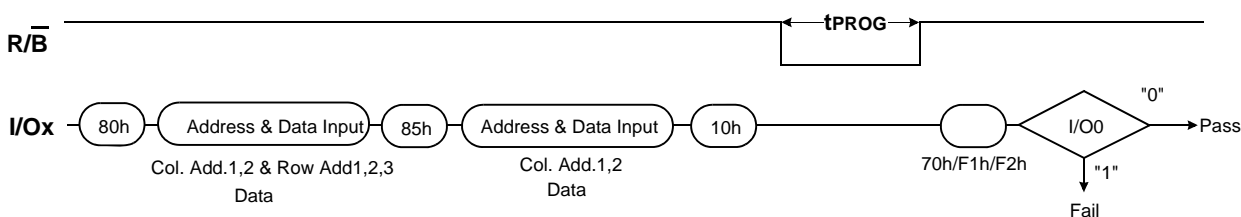
The serial data loading period begins by inputting the Serial Data Input command(80h), followed by the five cycle address inputs and then serial data loading. The words other than those to be programmed do not need to be loaded. The device supports random data input in a page. The column address for the next data, which will be entered, may be changed to the address which follows random data input command(85h). Random data input may be operated multiple times regardless of how many times it is done in a page.

The Page Program confirm command(10h) initiates the programming process. Writing 10h alone without previously entering the serial data will not initiate the programming process. The internal write state controller automatically executes the algorithms and timings necessary for program and verify, thereby freeing the system controller for other tasks. Once the program process starts, the Read Status Register command may be entered to read the status register. The system controller can detect the completion of a program cycle by monitoring the R/B output, or the Status bit(I/O 6) of the Status Register. Only the Read Status command and Reset command are valid while programming is in progress. When the Page Program is complete, the Write Status Bit(I/O 0) may be checked. The internal write verify detects only errors for "1"s that are not successfully programmed to "0"s. The command register remains in Read Status command mode until another valid command is written to the command register.

Program & Read Status Operation



Random Data Input In a Page

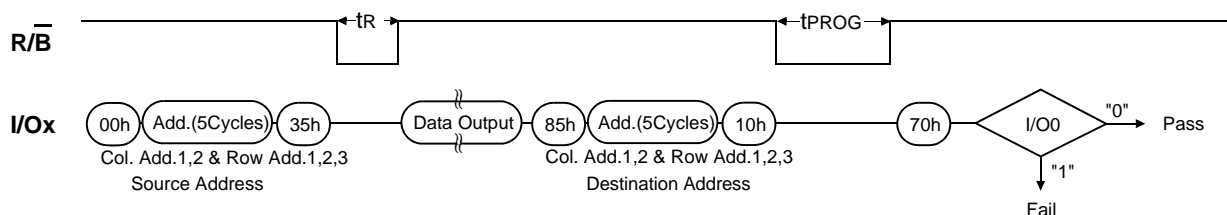


5.6 Copy-back Program

Copy-Back program with Read for Copy-Back is configured to quickly and efficiently rewrite data stored in one page without data re-loading when the bit error is not in data stored. Since the time-consuming re-loading cycles are removed, the system performance is improved. The benefit is especially obvious when a portion of a block is updated and the rest of the block also needs to be copied to the newly assigned free block. Copy-Back operation is a sequential execution of Read for Copy-Back and of copy-back program with the destination page address. A read operation with "35h" command and the address of the source page moves the whole (8K+1K) byte data into the internal data buffer. A bit error is checked by sequential reading the data output. In the case where there is no bit error, the data do not need to be reloaded. Therefore Copy-Back program operation is initiated by issuing Page-Copy Data-Input command (85h) with destination page address. Actual programming operation begins after Program Confirm command (10h) is issued. Once the program process starts, the Read Status Register command (70h) may be entered to read the status register. The system controller can detect the completion of a program cycle by monitoring the R/B output, or the Status bit(I/O 6) of the Status Register. When the Copy-Back Program is complete, the Write Status Bit(I/O 0) may be checked. The command register remains in Read Status command mode until another valid command is written to the command register.

During copy-back program, data modification is possible using random data input command (85h) as shown below.

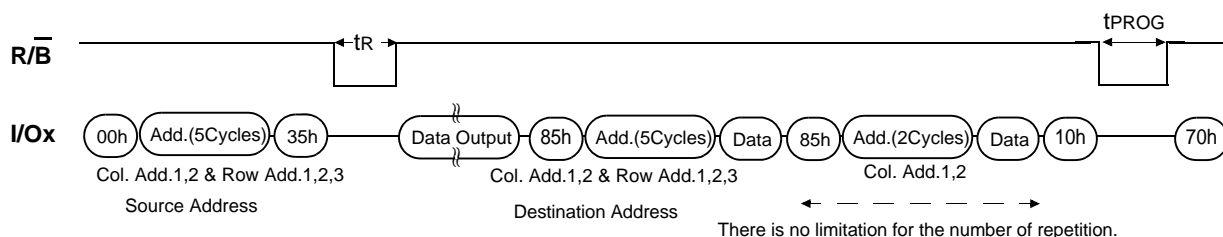
Page Copy-Back Program Operation



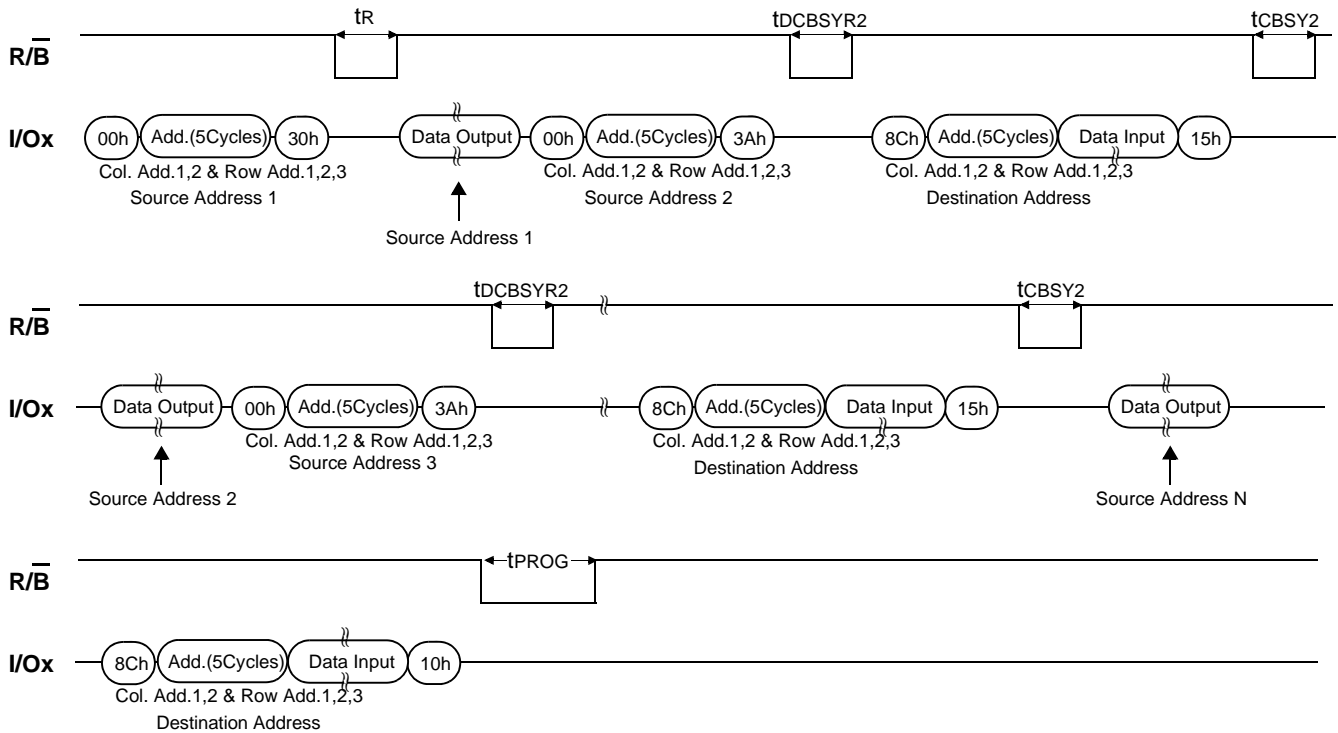
NOTE :

1) Copy-Back Program operation is allowed only within the same memory plane.

Page Copy-Back Program Operation with Random Data Input



5.7 Intelligent Copy-Back Program

Intelligent Page Copy-Back Program Operation**NOTE :**

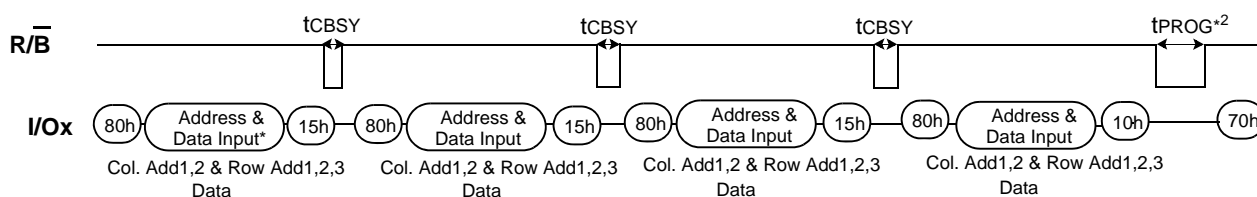
- 1) Intelligent Copy-Back Program operation is allowed only within the same memory plane.

5.8 Cache Program

Cache Program is an extension of Page Program, which is executed with (8K+1K) byte data registers, and is available only within a block. Since the device has 1 page of cache memory, serial data input may be executed while data stored in data registers are programmed into memory cell.

After writing the first set of data up to (8K+1K) byte into the selected cache registers, Cache Program command (15h) instead of actual Page Program (10h) is inputted to make cache registers free and to start internal program operation. To transfer data from cache registers to data registers, the device remains in Busy state for a short period of time(t_{CBSY}) and has its cache registers ready for the next data-input while the internal programming gets started with the data loaded into data registers. Read Status command (70h/F1h/F2h) may be issued to find out when cache registers become ready by polling the Cache-Busy status bit(I/O 6). Pass/fail status of only the previous page is available upon the return to Ready state. When the next set of data is inputted with the Cache Program command, t_{CBSY} is affected by the progress of pending internal programming. The programming of the cache registers is initiated only when the pending program cycle is finished and the data registers are available for the transfer of data from cache registers. The status bit(I/O5) for internal Ready/Busy may be polled to identify the completion of internal programming. If the system monitors the progress of programming only with R/B, the last page of the target programming sequence must be programmed with actual Page Program command (10h).

Cache Program(1/2)



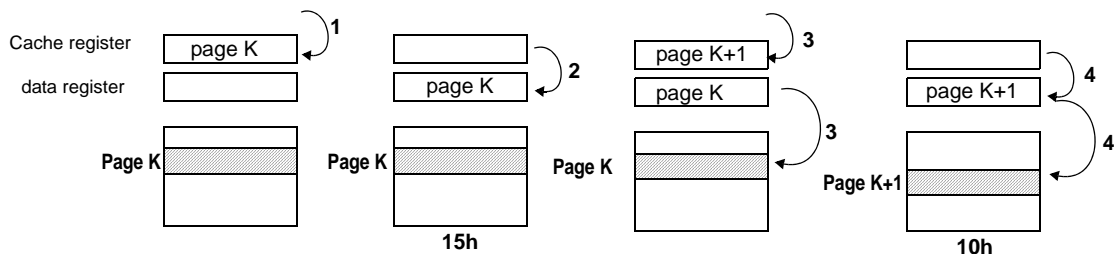
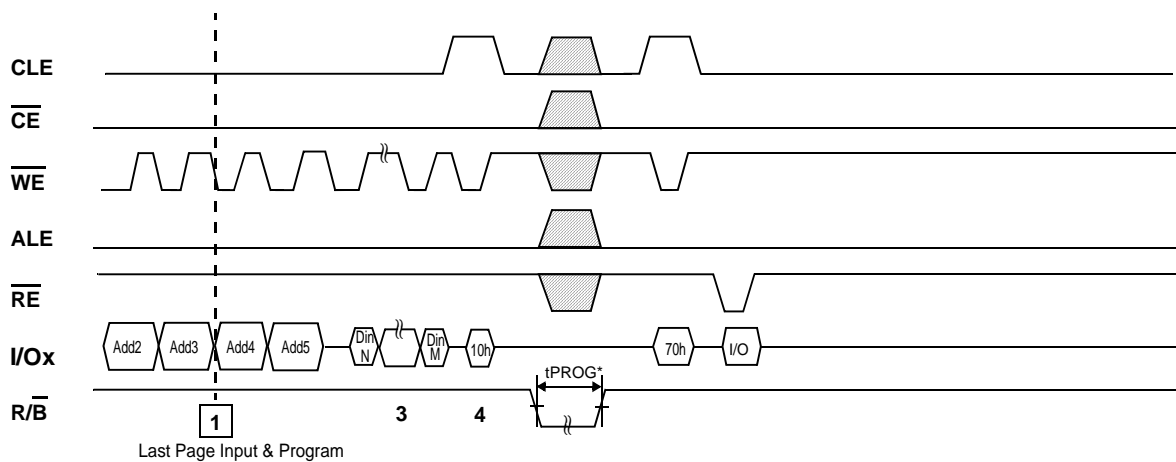
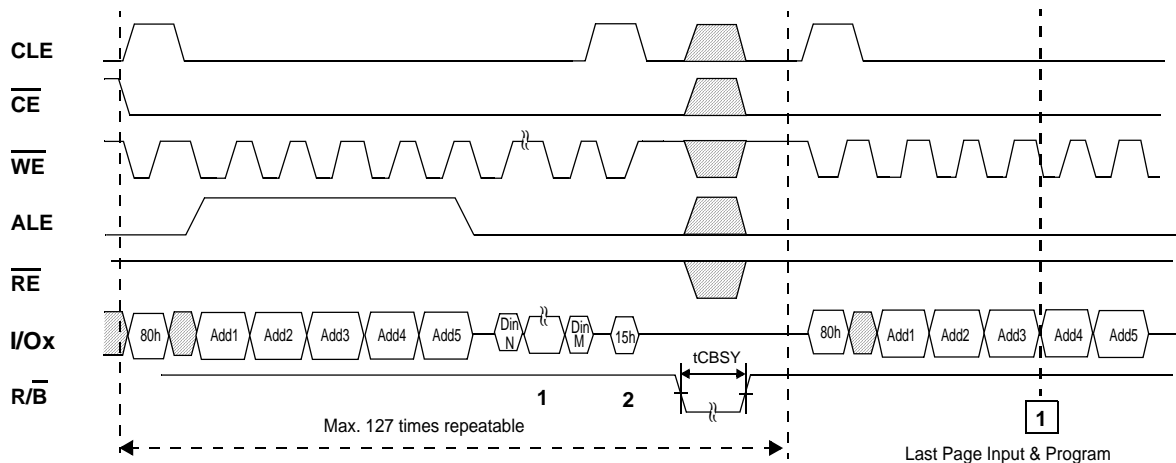
NOTE :

1) Cache Program operation is available only within a block.

2) Since programming the last page does not employ caching, the program time has to be that of Page Program. However, if the previous program cycle with the cache data has not finished, the actual program cycle of the last page is initiated only after completion of the previous cycle, which can be expressed as the following formula.

$$t_{PROG} = \text{Program time for the last page} + \text{Program time for the (last - 1)^{th} \text{ page} - (\text{Program command cycle time} + \text{Last page data loading time})$$

Maximum t_{PROG} is 10ms in this case.

Cache Program(2/2)**NOTE :**

- Issuing the 15h command to the device after serial data input initiates the program operation with cache registers.
- 1) Data for Page K is input to cache registers.
- 2) Data is transferred to the data registers by the 15h command. During the transfer the Ready/Busy outputs Busy State (tCBSY).
- 3) Data for Page K+1 is input to cache registers while the data of the Page K is being programmed.
- 4) The programming with cache registers is terminated by the 10h command . When the device becomes Ready, it shows that the internal programming of the Page K+1 is completed.

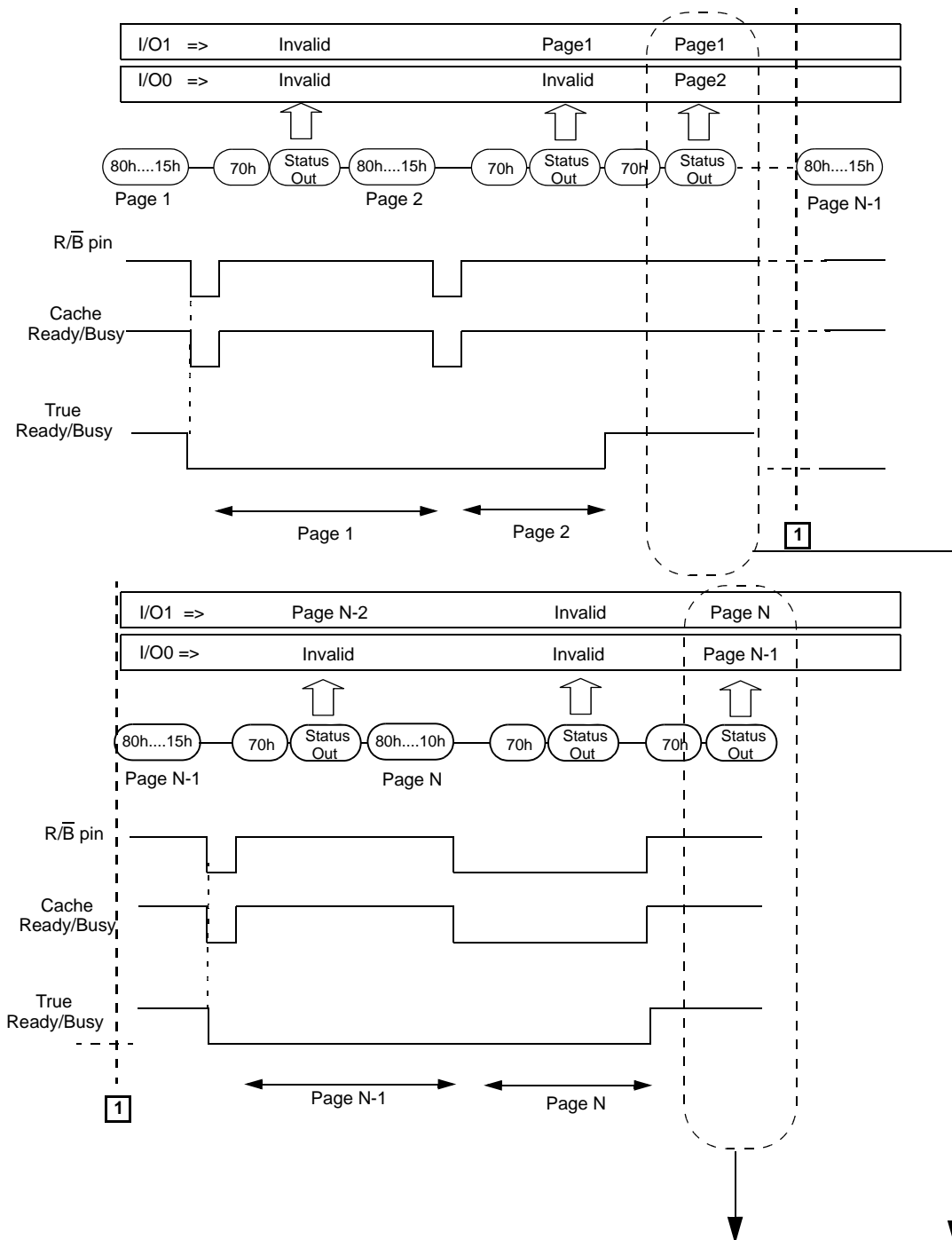
tPROG* = Program time for the last page + Program time for the (last -1)th page - (command input cycle time + address input cycle time + Last page data loading time)
Maximum tPROG is 10ms in this case.

Pass/Fail status for each page programmed by the Cache Program operation can be detected by the Read Status operation.

- I/O 0 : Pass/Fail of the current page program operation.
- I/O 1 : Pass/Fail of the previous page program operation.

The Pass/Fail status on I/O 0 and I/O 1 are valid under the following conditions.

- Status on I/O 0 : True Ready/Busy is Ready state.
The True Ready/Busy is output on I/O 5 by Read Status operation or R/B pin after the 10h command.
- Status on I/O 1 : Cache Read/Busy is Ready State.
The Cache Ready/Busy is output on I/O 6 by Read Status operation or R/B pin after the 15h command.

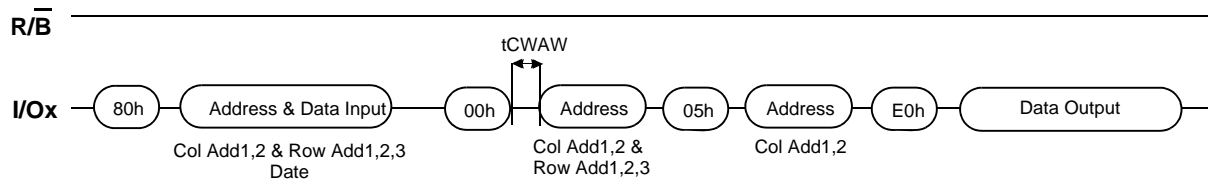


During both True Ready/Busy and Cache Ready/Busy return to Ready state, the Pass/Fail for previous page and current page can be shown through I/O 1 and I/O 0 concurrently.

5.9 Register Read Out Mode 1

At program operation, loaded data to the register can be read out before program confirm command(10h). The sequence is as follow.

Register Read Out

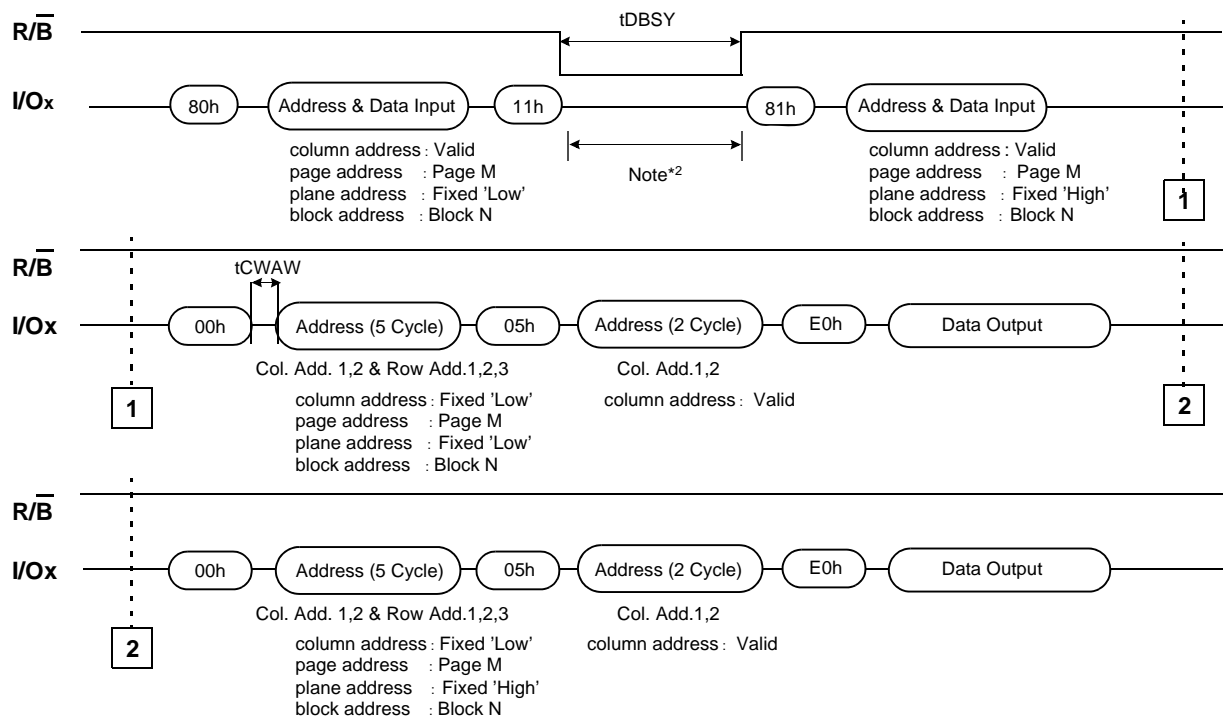


NOTE :
Register read out operation is prohibited during cache program operation.

5.10 Two-plane Register Read Out Mode 1

At two-plane program operation, loaded data to the register can be read out before program confirm command(10h). The sequence is as follow.

Two-Plane Register Read Out Mode 1



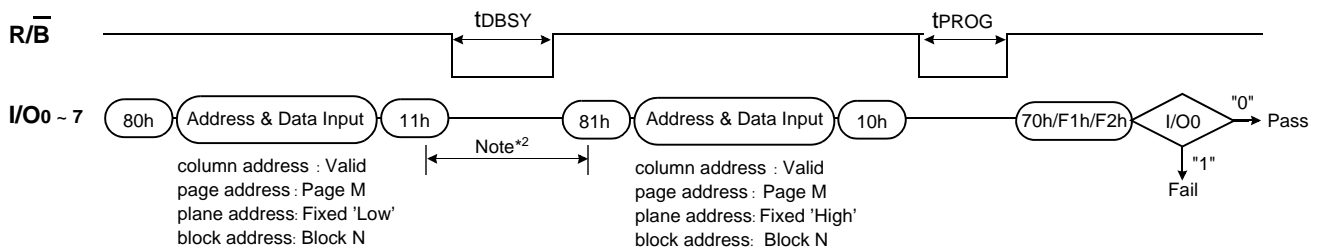
NOTE :
1) It is noticeable that physically same row address is applied to two planes .
2) Any command between 11h and 81h is prohibited except 70h/F1h/F2h and FFh.
3) Register read out operation is prohibited during cache program operation.

5.11 Two-plane Page Program

Two-Plane Page Program is an extension of Page Program, for a single plane with (8K+1K) byte data registers. Since the device is equipped with two memory planes, activating the two sets of (8K+1K) byte data registers enables a simultaneous programming of two pages.

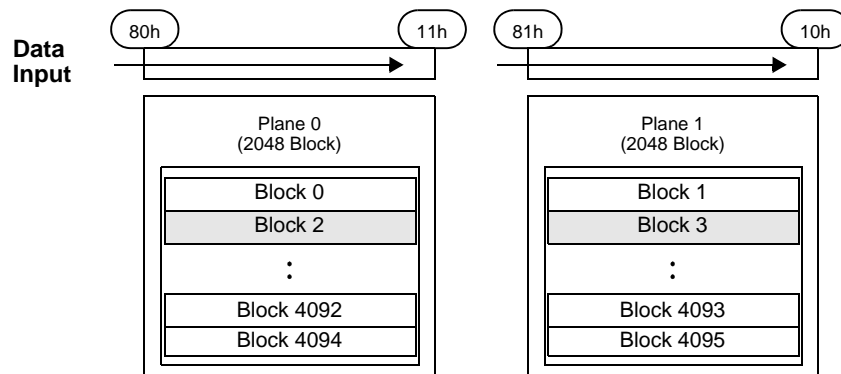
After writing the first set of data up to (8K+1K) byte into the selected data registers via cache registers, Dummy Page Program command (11h) instead of actual Page Program command (10h) is inputted to finish data-loading of the first plane. Since no programming process is involved, R/B remains in Busy state for a short period of time(t_{DBSY}). Read Status command (70h/F1h/F2h) may be issued to find out when the device returns to Ready state by polling the Ready/Busy status bit(I/O 6). Then the next set of data for the other plane is inputted after the 81h command and address sequences. After inputting data for the last plane, actual True Page Program(10h) instead of dummy Page Program command (11h) must be followed to start the programming process. The operation of R/B and Read Status is the same as that of Page Program. Although two planes are programmed simultaneously, pass/fail is not available for each page when the program operation completes. Status bit of I/O 0 is set to "1" when any of the pages fails. Restriction in addressing with Two-Plane Page Program is shown below.

Two-Plane Page Program

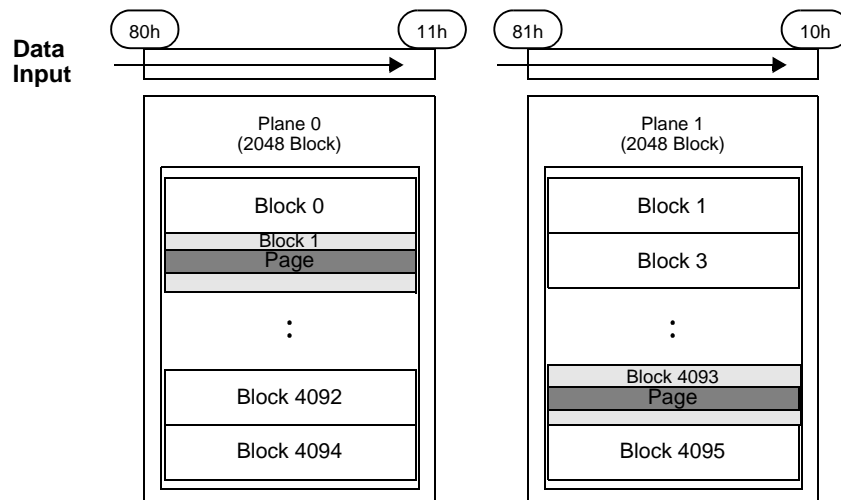


NOTE :

- 1) It is noticeable that same row address except for the Plane address is applied to the two blocks
- 2) Any command between 11h and 81h is prohibited except 70h/F1h/F2h and FFh.



Unaligned Two-Plane Page Program



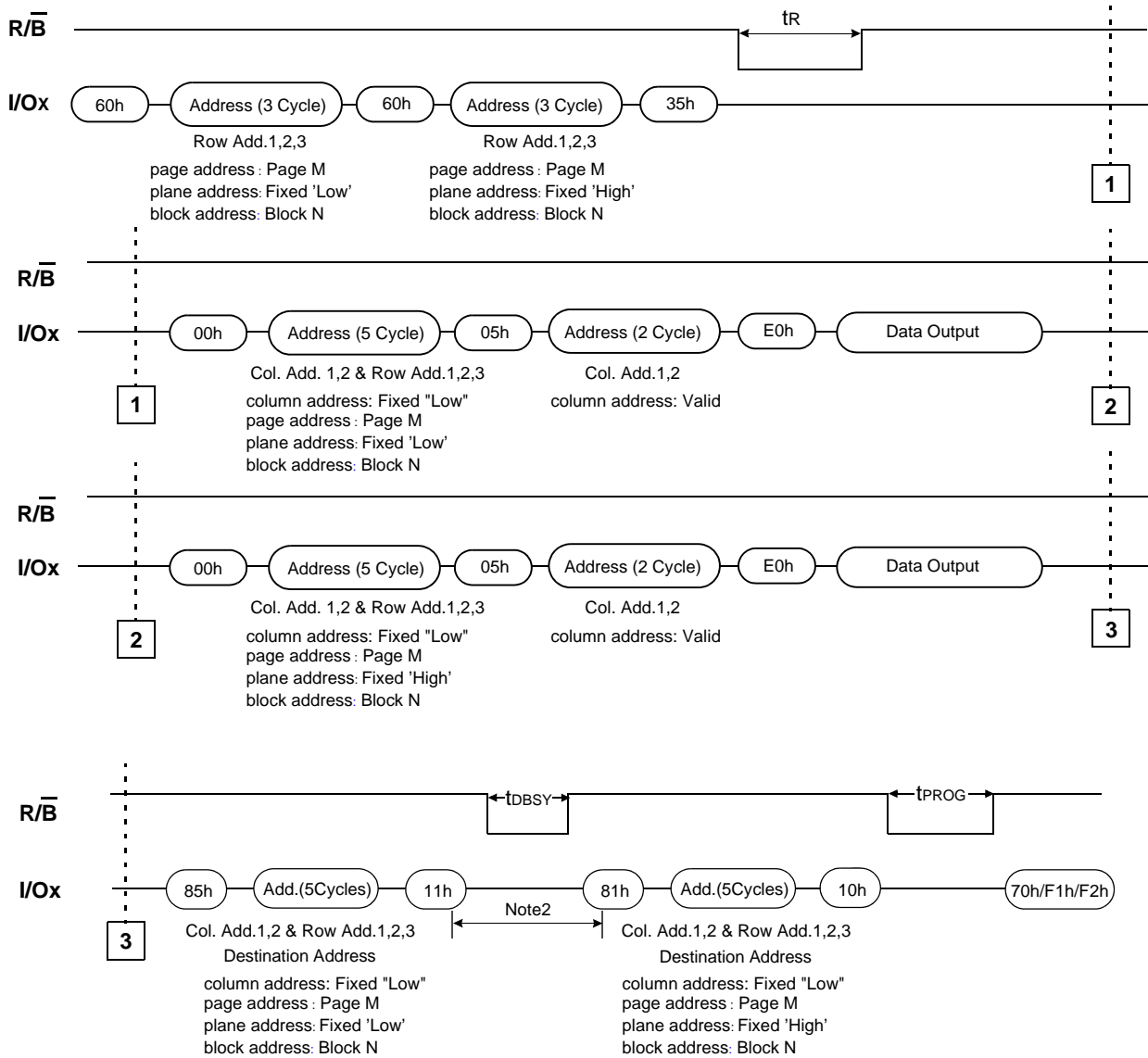
NOTE :

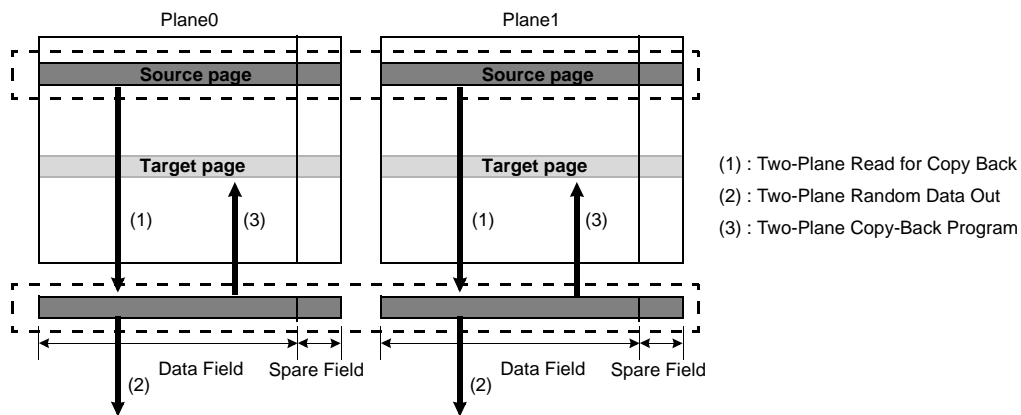
- 1) Two-Plane page Program operation shall be supported in unaligned block address, as long as address are same in all pages.

5.12 Two-plane Copy-back Program

Two-Plane Copy-Back Program is an extension of Copy-Back Program, for a single plane with (8K+1K) byte data registers. Since the device is equipped with two memory planes, activating the two sets of (8K+1K) byte data registers enables a simultaneous programming of two pages.

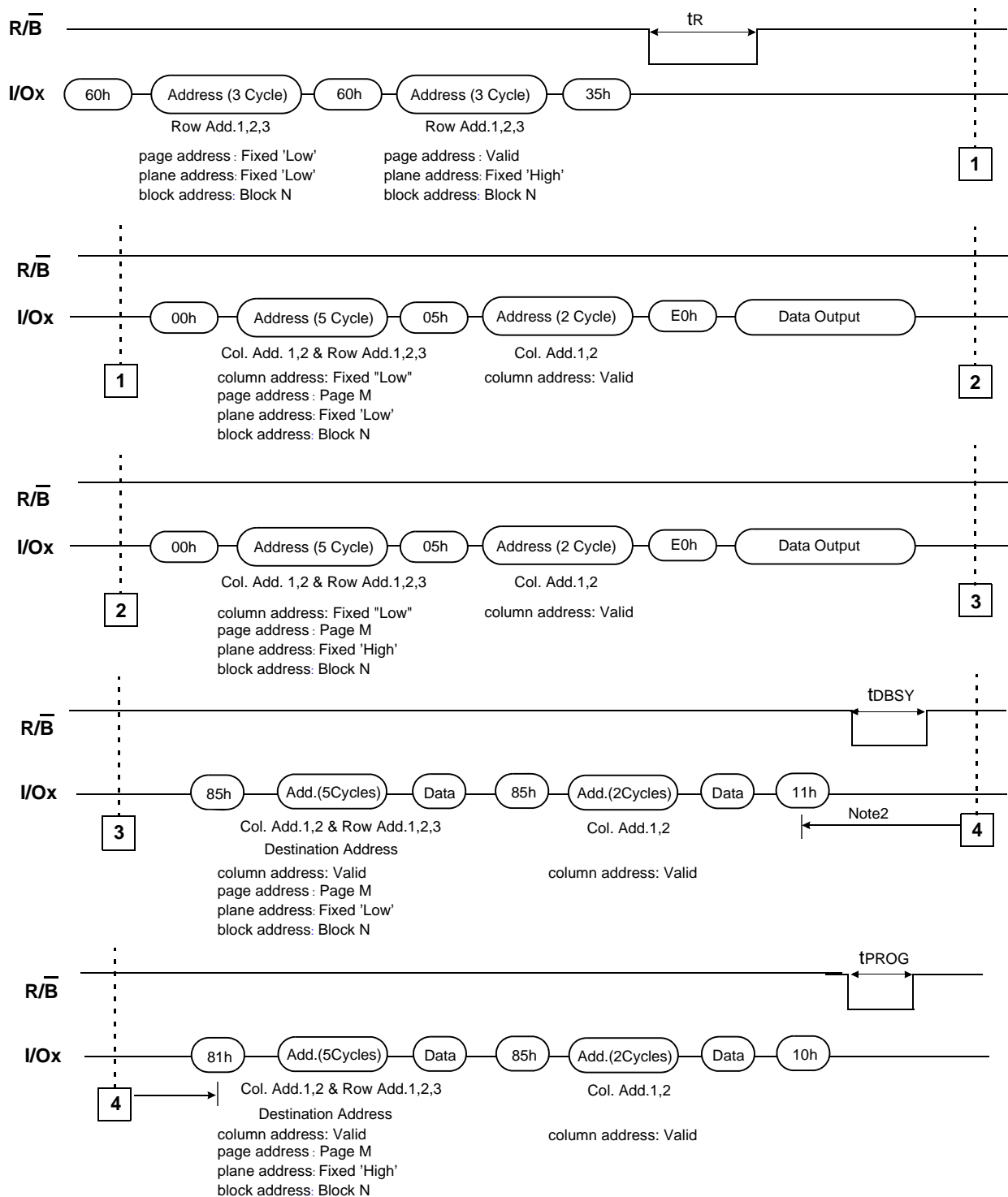
Two-Plane Copy-Back Program Operation



**NOTE :**

- 1) Copy-Back Program operation is allowed only within the same memory plane.
- 2) Any command between 11h and 81h is prohibited except 70h/F1h/F2h and FFh.

Two-Plane Copy-Back Program Operation with Random Data Input

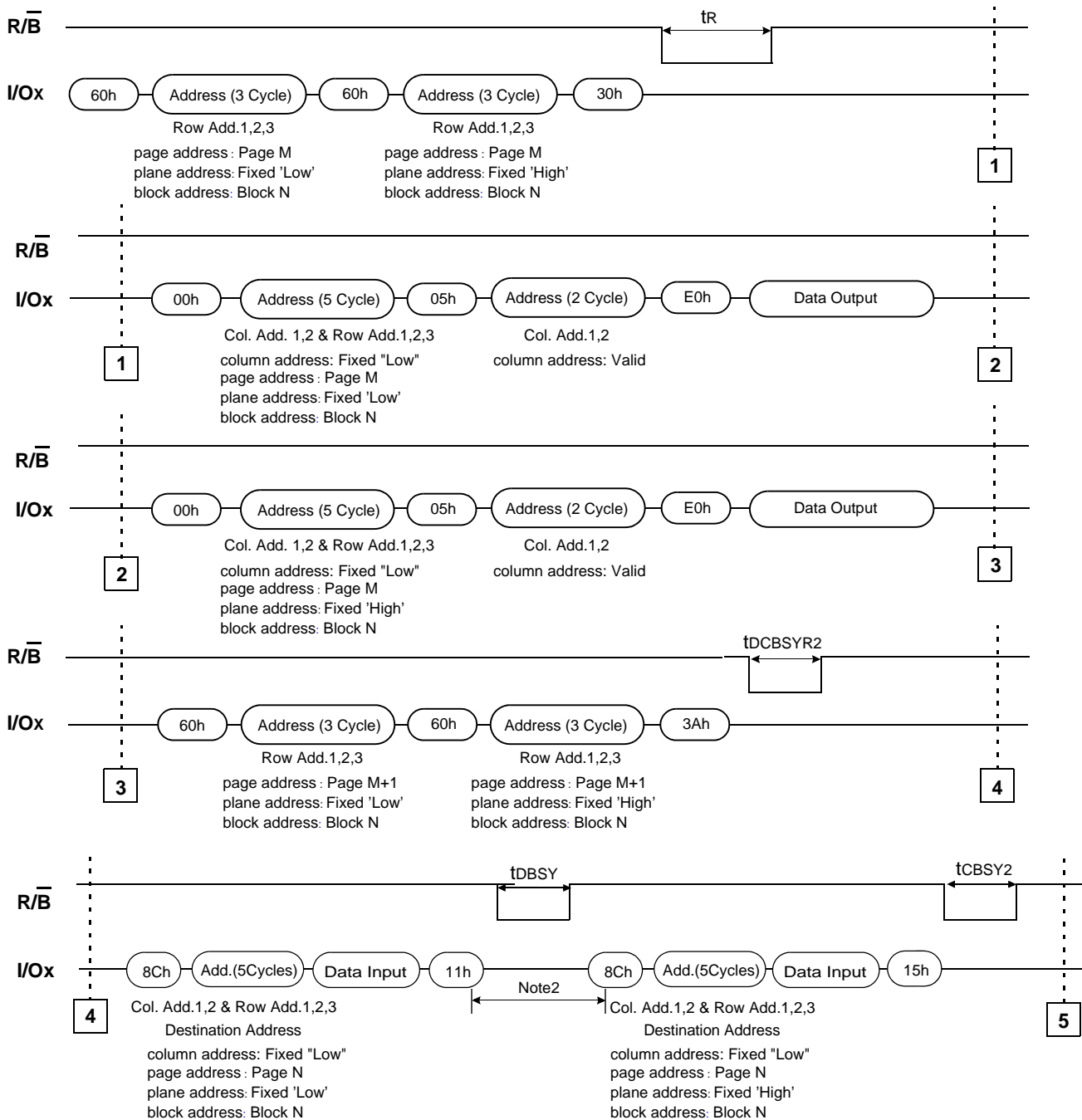


NOTE :

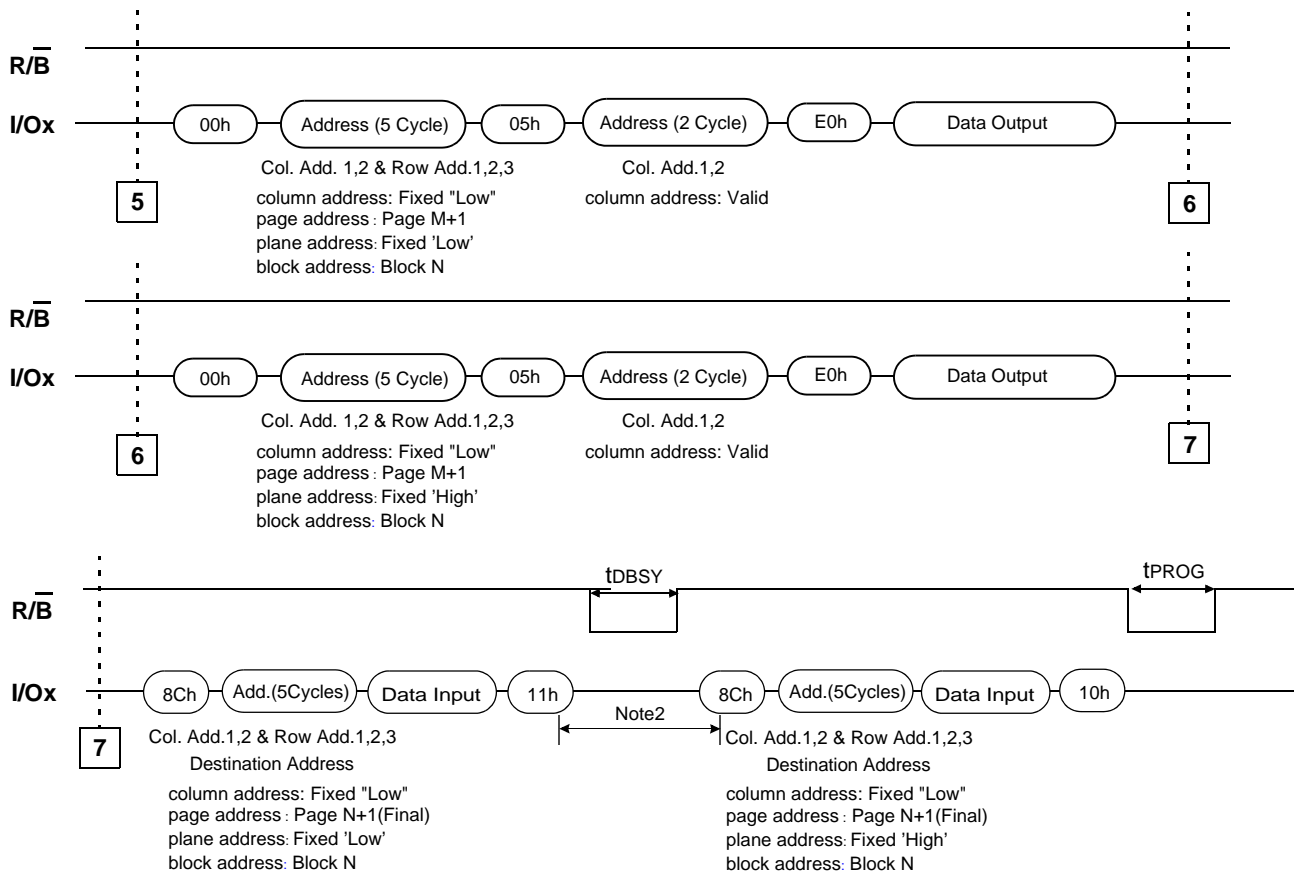
- 1) Copy-Back Program operation is allowed only within the same memory plane.
- 2) Any command between 11h and 81h is prohibited except 70h/F1h/F2h and FFh.

5.13 Two-Plane Intelligent Copy-back Program(1/2)

Two-Plane Intelligent Copy-Back Program Operation



Two-Plane Intelligent Copy-back Program(2/2)

**NOTE :**

- 1) Two-Plane Intelligent Copy-Back Program operation is allowed only within the same memory plane.
- 2) Any command between 11h and 8Ch is prohibited except 70h/F1h/F2h and FFh.

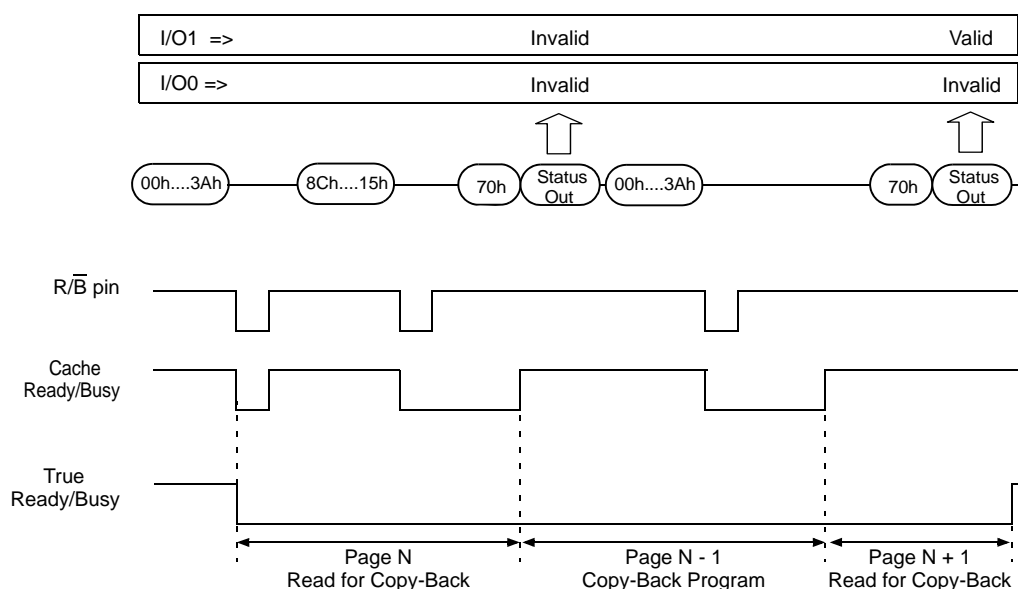
Pass/Fail status for each page programmed by the Intelligent Copy-Back Program operation can be detected by the Read Status operation.

- I/O 0 : Pass/Fail of the current page program operation.
- I/O 1 : Pass/Fail of the previous page program operation.

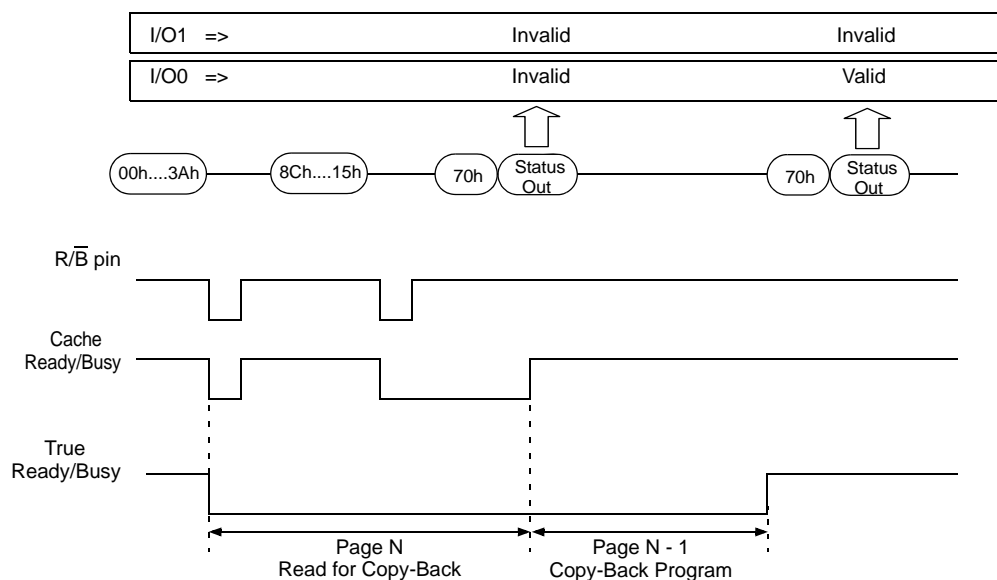
The Pass/Fail status on I/O 0 and I/O 1 are valid under the following conditions.

- Status on I/O 0 : True Ready/Busy is Ready state.
The True Ready/Busy is output on I/O 5 by Read Status operation or R/B pin after the 10h command.
- Status on I/O 1 : Cache Read/Busy is Ready State.
The Cache Ready/Busy is output on I/O 6 by Read Status operation or R/B pin after the 15h command.

CASE 1



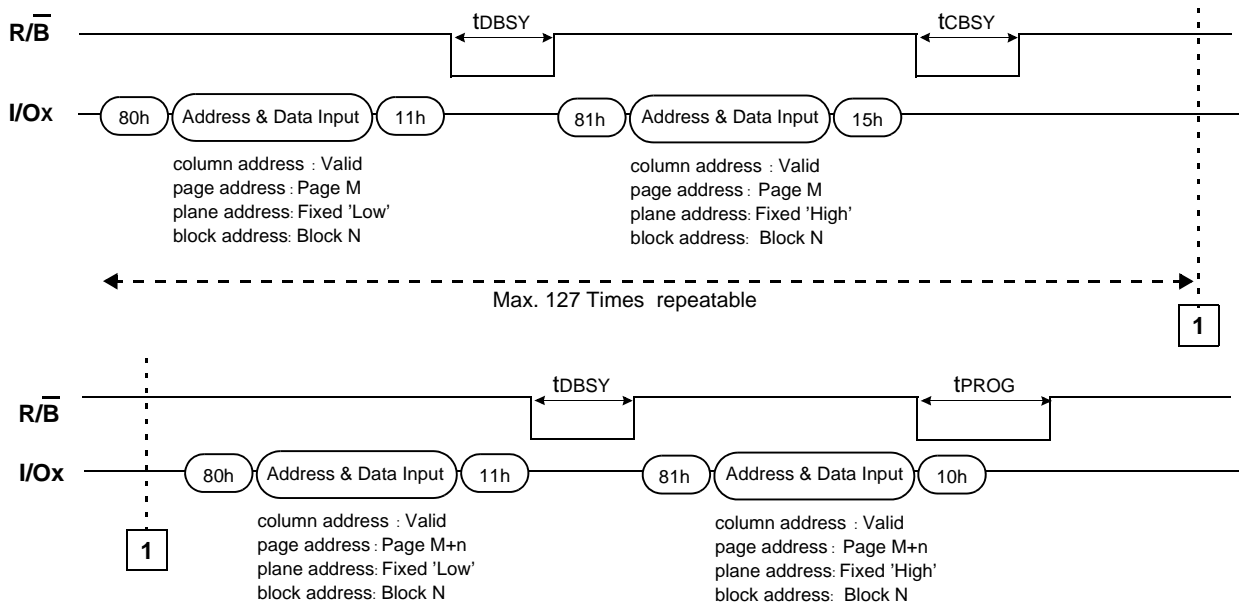
CASE 2



5.14 Two-plane Cache Program

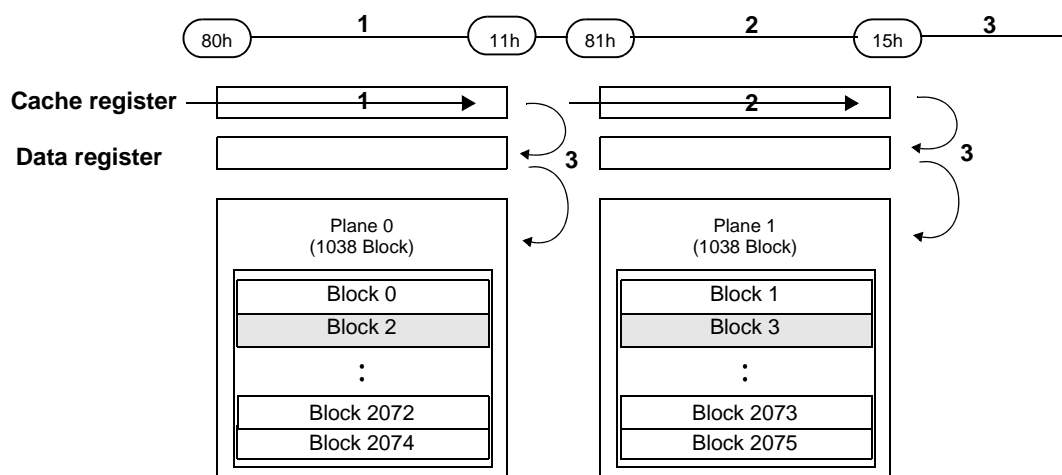
Two-Plane Cache Program is an extension of Cache Program, for a single plane with (8K+1K) byte data registers. Since the device is equipped with two memory planes, activating the two sets of (8K+1K) byte data registers enables a simultaneous programming of two pages.

Two-Plane Cache Program Operation



NOTE :

- 1) It is noticeable that same row address except for the Plane address is applied to the two blocks
- 2) Any command between 11h and 81h is prohibited except 70h/F1h/F2h and FFh.
- 3) Since programming the last page does not employ caching, the program time has to be that of Page Program. However, if the previous program cycle with the cache data has not finished, the actual program cycle of the last page is initiated only after completion of the previous cycle, which can be expressed as the following formula.
 $t_{PROG} = \text{Program time for the last page} + \text{Program time for the (last - 1)^{th} \text{ page}}$
 - (Program command cycle time + Last page data loading time)

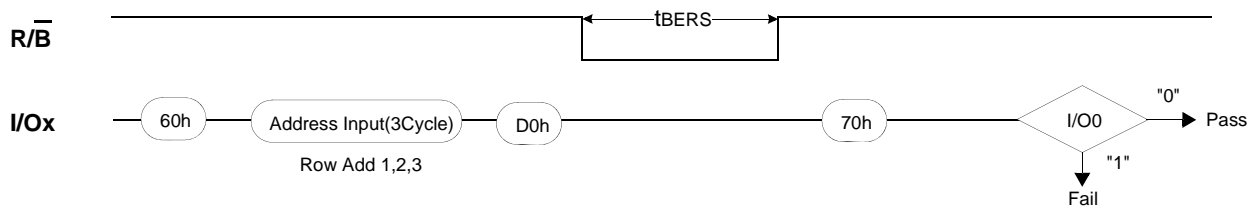


5.15 Block Erase

The Erase operation is done on a block basis. Block address loading is accomplished in three cycles initiated by an Erase Setup command(60h). Only Plane address and Block address are valid while Page address is ignored. The Erase Confirm command(D0h) following the block address loading initiates the internal erasing process. This two-step sequence of setup followed by execution command ensures that memory contents are not accidentally erased due to external noise conditions.

At the rising edge of \overline{WE} after the erase confirm command input, the internal write controller handles erase and erase-verify. When the erase operation is completed, the Write Status Bit(I/O 0) may be checked.

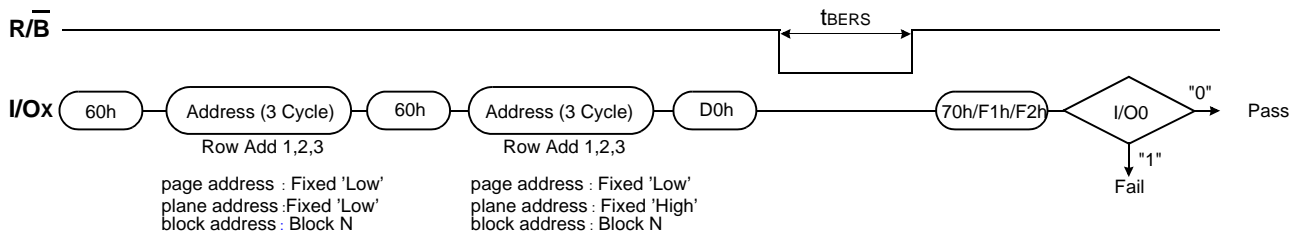
Block Erase Operation



5.16 Two-plane Block Erase

Basic concept of Two-Plane Block Erase operation is identical to that of Two-Plane Page Program. Up to two blocks, one from each plane can be simultaneously erased. Standard Block Erase command sequences (Block Erase Setup command(60h) followed by three address cycles) may be repeated up to twice for erasing up to two blocks. Only one block should be selected from each plane. The Erase Confirm command(D0h) initiates the actual erasing process. The completion is detected by monitoring $\overline{R/B}$ pin or Ready/Busy status bit (I/O 6).

Two-Plane Block Erase Operation



5.17 Read Status

The device contains a Status Register which may be read to find out whether program or erase operation is completed, and whether the program or erase operation is completed successfully. After writing 70h or F1h/F2h command to the command register, a read cycle outputs the content of the Status Register to the I/O pins on the falling edge of \overline{CE} or \overline{RE} , whichever occurs last. This two line control allows the system to poll the progress of each device in multiple memory connections even when R/B pins are common-wired. \overline{RE} or \overline{CE} does not need to be toggled for updated status. Refer to the table for specific 70h Status Register definitions and F1h/F2h status Register definitions. The command register remains in Status Read mode until further commands are issued to it. Therefore, if the status register is read during a random read cycle, the read command(00h) should be given before starting read cycles.

Status Register Definition for 70h Command

| I/O | Page Program | Block Erase | Cache Program | Intelligent Copy-Back Program | Read | Cache Read | Intelligent Copy-Back Read | Definition |
|-------|------------------------------------|------------------------------------|---|--|------------------------------------|----------------------|----------------------------|--|
| I/O 0 | Pass/Fail | Pass/Fail | Pass/Fail(N) | Pass/Fail(N) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 1 | Not Use Use | Not Use Use | Pass/Fail(N-1) District 0 Pass/Fail | Pass/Fail(N-1) District 0 Pass/ Fail | Not Use District 0 Pass/Fail | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 2 | Not Use District 0 Pass/Fail | Not Use District 0 Pass/Fail | Not Use District 0 Pass/Fail | Not Use District 0 Pass/ Fail | Not Use District 0 Pass/Fail | Not Use | Not Use | Don't -cared |
| I/O 3 | Not Use | Not Use | Not Use | Not Use | Not Use | Not Use | Not Use | Don't -cared |
| I/O 4 | Not Use | Not Use | Not Use | Not Use | Not Use | Not Use | Not Use | Don't -cared |
| I/O 5 | Not Use | Not Use | True Ready/Busy | True Ready/Busy | Not Use | True Ready/Busy | True Ready/Busy | Busy : "0" Ready : "1" |
| I/O 6 | Ready/Busy | Ready/Busy | Cache Ready/Busy | Cache Ready/Busy | Ready/Busy | Cache Ready/ Busy | Cache Ready/ Busy | Busy : "0" Ready : "1" |
| I/O 7 | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Protected : "0" Not Protected : "1" |

NOTE :

- 1) I/Os defined 'Not use' are recommended to be masked out when Read Status is being executed.
2) N : current page, N-1: previous page.

Status Register Definition for F1h Command

| I/O | Page Program | Block Erase | Cache Program | Intelligent Copy-Back Program | Read | Cache Read | Intelligent Copy-Back Read | Definition |
|-------|---------------------|---------------------|--------------------------|-------------------------------|---------------|---------------------|----------------------------|--|
| I/O 0 | Chip1 Pass/Fail | Chip1 Pass/Fail | Chip1 Pass/Fail(N) | Chip1 Pass/Fail(N) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 1 | Plane0 Pass/Fail | Plane0 Pass/Fail | Plane0 Pass/Fail(N) | Plane0 Pass/Fail(N) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 2 | Plane1 Pass/Fail | Plane1 Pass/Fail | Plane1 Pass/Fail(N) | Plane1 Pass/Fail(N) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 3 | Not Use | Not Use | Plane0 Pass/Fail(N-1) | Plane0 Pass/Fail(N-1) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 4 | Not Use | Not Use | Plane1 Pass/Fail(N-1) | Plane1 Pass/Fail(N-1) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 5 | Not Use | Not Use | True Ready/Busy | True Ready/Busy | Not Use | True Ready/Busy | True Ready/Busy | Busy : "0" Ready : "1" |
| I/O 6 | Ready/Busy | Ready/Busy | Cache Ready/Busy | Cache Ready/Busy | Ready/Busy | Cache Ready/Busy | Cache Ready/Busy | Busy : "0" Ready : "1" |
| I/O 7 | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Protected : "0" Not Protected : "1" |

NOTE :

- 1) I/Os defined 'Not use' are recommended to be masked out when Read Status is being executed.
2) N : current page, N-1 : previous page.

Status Register Definition for F2h Command

| I/O | Page Program | Block Erase | Cache Program | Intelligent Copy-Back Program | Read | Cache Read | Intelligent Copy-Back Read | Definition |
|-------|------------------|------------------|-----------------------|-------------------------------|---------------|------------------|----------------------------|--|
| I/O 0 | Chip2 Pass/Fail | Chip2 Pass/Fail | Chip2 Pass/Fail(N) | Chip2 Pass/Fail(N) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 1 | Plane0 Pass/Fail | Plane0 Pass/Fail | Plane0 Pass/Fail(N) | Plane0 Pass/Fail(N) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 2 | Plane1 Pass/Fail | Plane1 Pass/Fail | Plane1 Pass/Fail(N) | Plane1 Pass/Fail(N) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 3 | Not Use | Not Use | Plane0 Pass/Fail(N-1) | Plane0 Pass/Fail(N-1) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 4 | Not Use | Not Use | Plane1 Pass/Fail(N-1) | Plane1 Pass/Fail(N-1) | Not Use | Not Use | Not Use | Pass : "0" Fail : "1" |
| I/O 5 | Not Use | Not Use | True Ready/Busy | True Ready/Busy | Not Use | True Ready/Busy | True Ready/Busy | Busy : "0" Ready : "1" |
| I/O 6 | Ready/Busy | Ready/Busy | Cache Ready/Busy | Cache Ready/Busy | Ready/Busy | Cache Ready/Busy | Cache Ready/Busy | Busy : "0" Ready : "1" |
| I/O 7 | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Write Protect | Protected : "0" Not Protected : "1" |

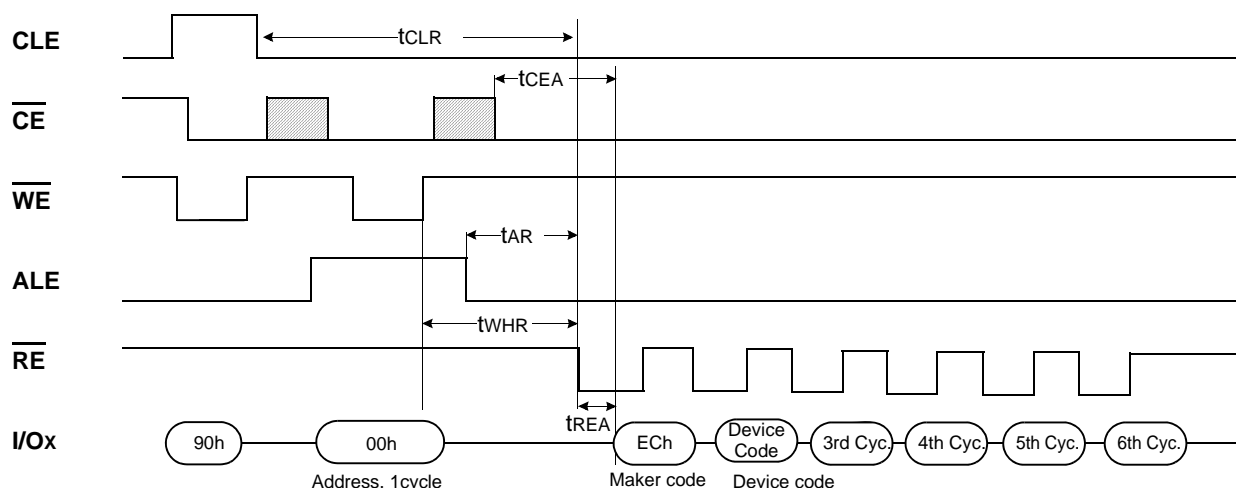
NOTE :

1) I/Os defined 'Not use' are recommended to be masked out when Read Status is being executed.

2) N : current page, N-1 : previous page.

5.18 Read Id

The device contains a product identification mode, initiated by writing 90h to the command register, followed by an address input of 00h. Six read cycles sequentially output the manufacturer code(ECh), and the device code and 3rd, 4th, 5th, 6th cycle ID respectively. The command register remains in Read ID mode until further commands are issued to it.

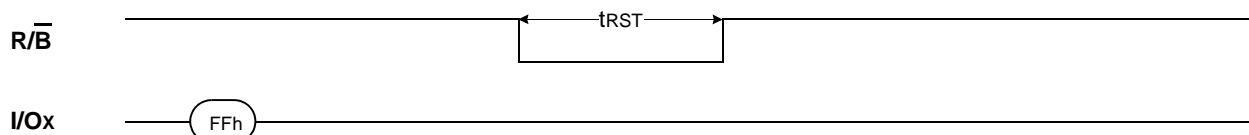
Read ID Operation

| Device | 1st Cycle | 2nd Cycle | 3rd Cycle | 4th Cycle | 5th Cycle | 6th Cycle |
|------------|-----------|-----------|-----------|-----------|-----------|-----------|
| K9GBG08U0B | ECh | D7h | 94h | 7Eh | 64h | 44h |
| K9LCG08U0B | | DEh | D5h | | 68h | |
| K9HDG08U1B | | DEh | D5h | | 68h | |

5.19 Reset

The device offers a reset feature, executed by writing FFh to the command register. When the device is in Busy state during random read, program or erase mode, the reset operation will abort these operations. The contents of memory cells being altered are no longer valid, as the data will be partially programmed or erased. The command register is cleared to wait for the next command, and the Status Register is cleared to value C0h when WP is high. Refer to table for device status after reset operation. If the device is already in reset state a new reset command will be accepted by the command register. The R/B pin changes to low for tRST after the Reset command is written.

RESET Operation



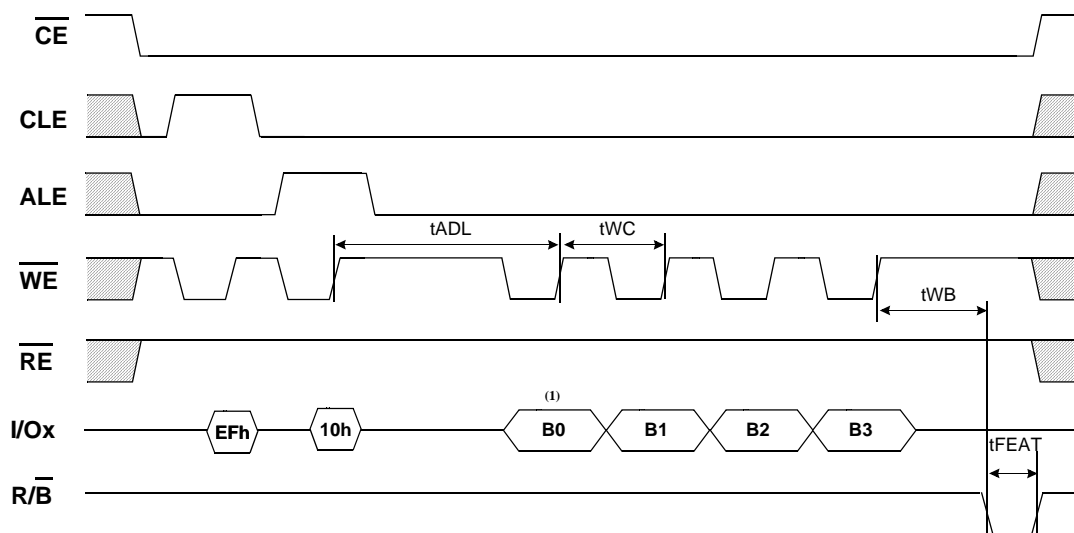
Device Status

| | After Power-up | After Reset |
|---------------------|------------------------|--------------------------|
| Operation mode Mode | 00h Command is latched | Waiting for next command |

5.20 Output driver setting

The device supports four kinds of output driver setting for matching the system characteristics. The nominal output drive strength is the power-on default value. The host is able to select a different drive strength setting using the SET FEATURES (EFh) command with following 10h address (driver setting feature address). The output impedance range from minimum to maximum covers process, voltage, and temperature variations. Devices are not guaranteed to be at the nominal value. The users can tune the output driver impedance of the data by setting the driver strength register value. (See Configuration Register Table) Table 5 shows which output driver would be tuned and the strength according to setting data. Upon power-up, the register will revert to the default setting. Table 6 & Table 7 shows the output driver strength impedance values of each strength and pull-up and pull down output impedance mismatch.

Driver Strength Register Setting



NOTE :

1) B0-B3 are parameters identifying new settings for the feature specified.

[Table 4] Output Driver Setting

| B0 Value | Driver Strength |
|----------|----------------------------------|
| 00h~01h | Reserved |
| 02h | Driver Multiplier : underdriver1 |
| 03h | Reserved |
| 04h | Driver Multiplier : 1 (default) |
| 05h | Reserved |
| 06h | Driver Multiplier : overdriver1 |
| 07h | Reserved |
| 09h | Reserved |
| 0Ah ~FFh | Reserved |

[Table 5] Output Drive Strength Impedance Values

| Output Strength | Rpd/Rpu | VOUT to VssQ | Minimum | Nominal | Maximum | Units |
|-----------------|---------|----------------------|------------|------------|------------|-------|
| | | | VccQ(3.3V) | VccQ(3.3V) | VccQ(3.3V) | |
| Overdrive1 | Rpd | $V_{ccQ} \times 0.2$ | 18 | 27 | 43 | ohms |
| | | $V_{ccQ} \times 0.5$ | 20 | 32 | 53 | ohms |
| | | $V_{ccQ} \times 0.8$ | 29 | 46 | 77 | ohms |
| | Rpu | $V_{ccQ} \times 0.2$ | 29 | 46 | 77 | ohms |
| | | $V_{ccQ} \times 0.5$ | 20 | 32 | 53 | ohms |
| | | $V_{ccQ} \times 0.8$ | 18 | 27 | 43 | ohms |
| Nominal | Rpd | $V_{ccQ} \times 0.2$ | 23 | 34 | 54 | ohms |
| | | $V_{ccQ} \times 0.5$ | 26 | 40 | 68 | ohms |
| | | $V_{ccQ} \times 0.8$ | 36 | 57 | 96 | ohms |
| | Rpu | $V_{ccQ} \times 0.2$ | 36 | 57 | 96 | ohms |
| | | $V_{ccQ} \times 0.5$ | 26 | 40 | 68 | ohms |
| | | $V_{ccQ} \times 0.8$ | 23 | 34 | 54 | ohms |
| Underdrive | Rpd | $V_{ccQ} \times 0.2$ | 30 | 45 | 72 | ohms |
| | | $V_{ccQ} \times 0.5$ | 34 | 53 | 91 | ohms |
| | | $V_{ccQ} \times 0.8$ | 48 | 76 | 128 | ohms |
| | Rpu | $V_{ccQ} \times 0.2$ | 48 | 76 | 128 | ohms |
| | | $V_{ccQ} \times 0.5$ | 34 | 53 | 91 | ohms |
| | | $V_{ccQ} \times 0.8$ | 30 | 45 | 72 | ohms |

[Table 6] Pull-up and Pull-down Output Impedance Mismatch

| Drive Strength | Min | Max | Unit | Notes |
|----------------|------------|------------|------|-------|
| | VccQ(3.3V) | VccQ(3.3V) | | |
| Overdrive 1 | 0 | 8 | ohms | 1, 2 |
| Nominal | 0 | 10 | ohms | 1, 2 |
| Underdrive | 0 | 14 | ohms | 1, 2 |

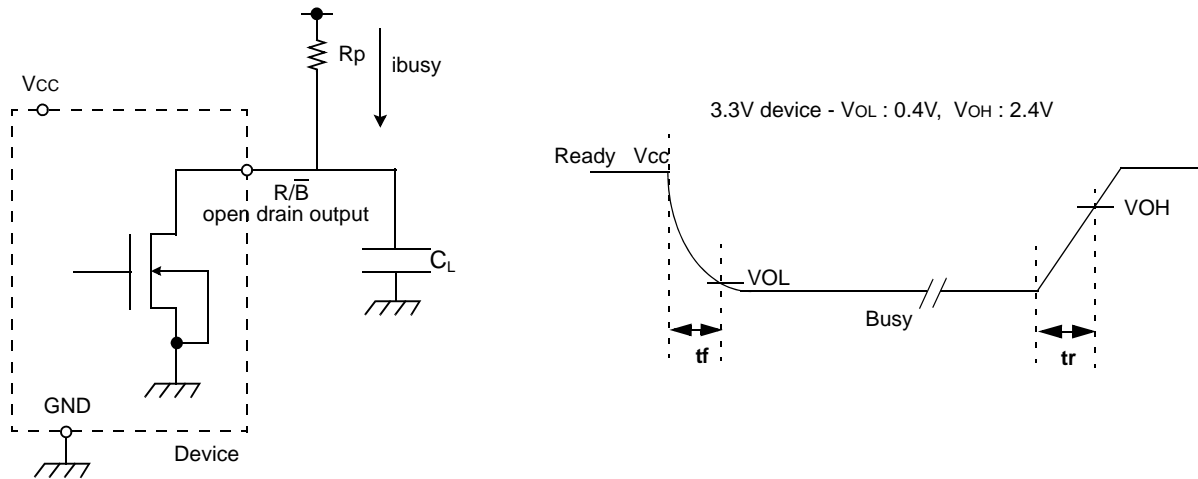
NOTE :

1) Mismatch is the absolute value between pull-up and pull-down impedances. Both are measured at the same temperature and voltage.

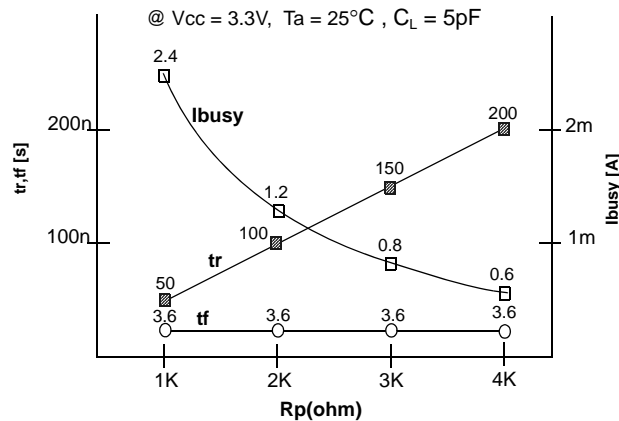
2) Test conditions: $V_{ccQ} = V_{ccQ}(\min)$, $V_{out} = V_{ccQ} \times 0.5$, $T_A = T_{OPER}$

5.21 Ready/ $\overline{\text{busy}}$

The device has a $\overline{\text{R/B}}$ output that provides a hardware method of indicating the completion of a page program, erase and random read completion. The $\overline{\text{R/B}}$ pin is normally high but transitions to low after program or erase command is written to the command register or random read is started after address loading. It returns to high when the internal controller has finished the operation. The pin is an open-drain driver thereby allowing two or more $\overline{\text{R/B}}$ outputs to be Or-tied. Because pull-up resistor value is related to $t_r(\overline{\text{R/B}})$ and current drain during busy(i_{busy}), an appropriate value can be obtained with the following reference chart. Its value can be determined by the following guidance.



R_p vs t_r, t_f & R_p vs i_{busy}



R_p value guidance

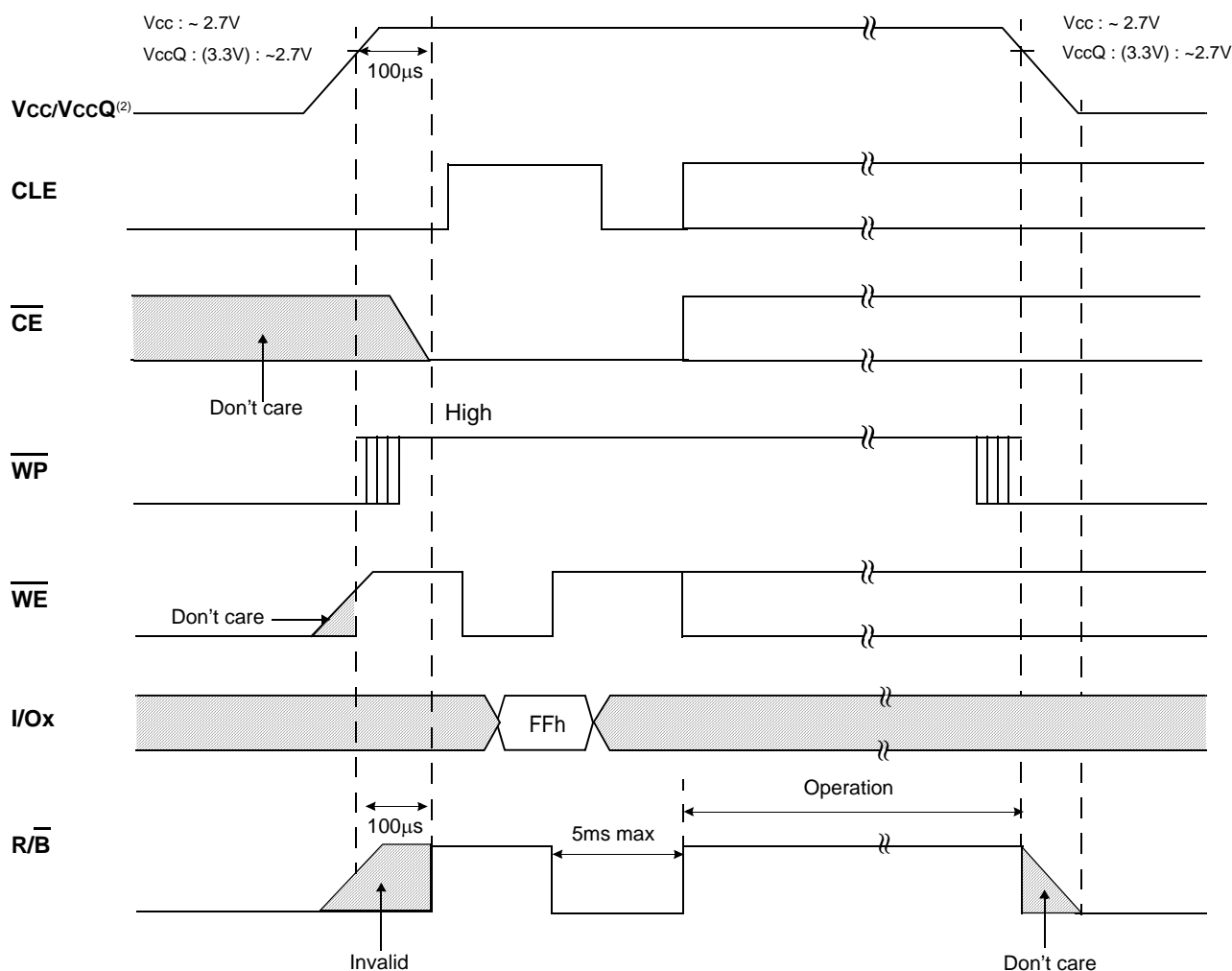
$$R_p(\text{min}, 3.3V \text{ part}) = \frac{V_{CC}(\text{Max.}) - V_{OL}(\text{Max.})}{I_{OL} + \Sigma I_L} = \frac{3.2V}{8mA + \Sigma I_L}$$

where I_L is the sum of the input currents of all devices tied to the $\overline{\text{R/B}}$ pin.
 $R_p(\text{max})$ is determined by maximum permissible limit of t_r

6.0 DATA PROTECTION & POWER UP SEQUENCE

The device is designed to offer protection from any involuntary program/erase during power-transitions. An internal voltage detector disables all functions whenever V_{CC} is below about 2V. The Reset command(FFh) must be issued to all CEs as the first command after the NAND Flash device is powered on. Each \overline{CE} will be busy for a maximum of 5ms after a RESET command is issued. In this time period, the acceptable command is 70h/F1h/F2h. \overline{WP} pin provides hardware protection and is recommended to be kept at V_{IL} during power-up and power-down. The two step command sequence for program/erase provides additional software protection.

AC Waveforms for Power Transition



NOTE :

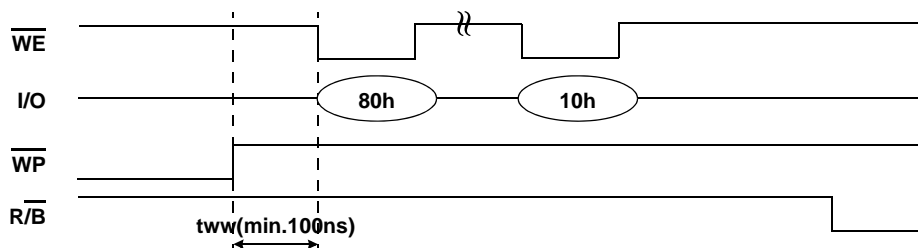
- 1) During the initialization, the device consumes a maximum current of 50mA (I_{CC1})
- 2) V_{CC} should be reached the valid voltage no later than V_{CCQ} .

6.1 \overline{WP} AC Timing guide

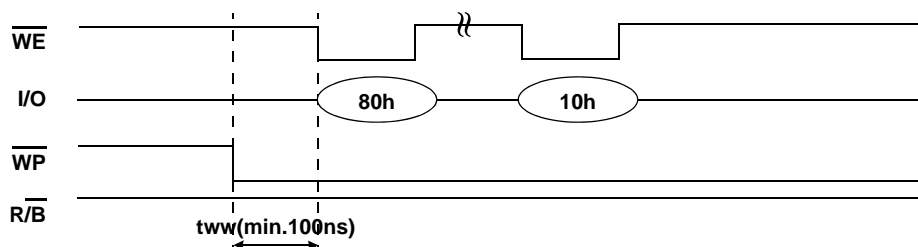
Enabling \overline{WP} during erase and program busy is prohibited. The erase and program operations are enabled and disabled as follows:

Program Operation

1. Enable Mode

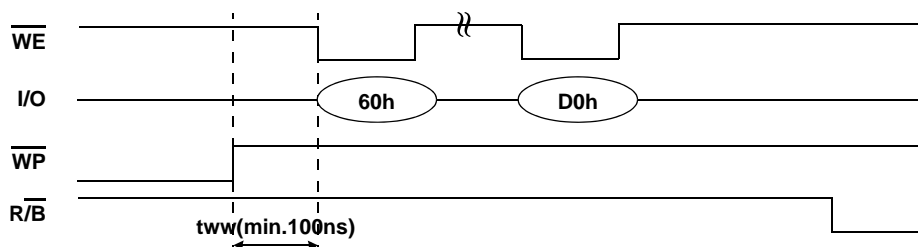


2. Disable Mode



Erase Operation

1. Enable Mode



2. Disable Mode

